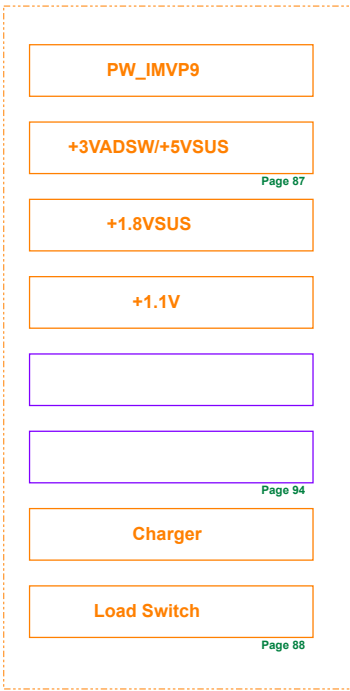
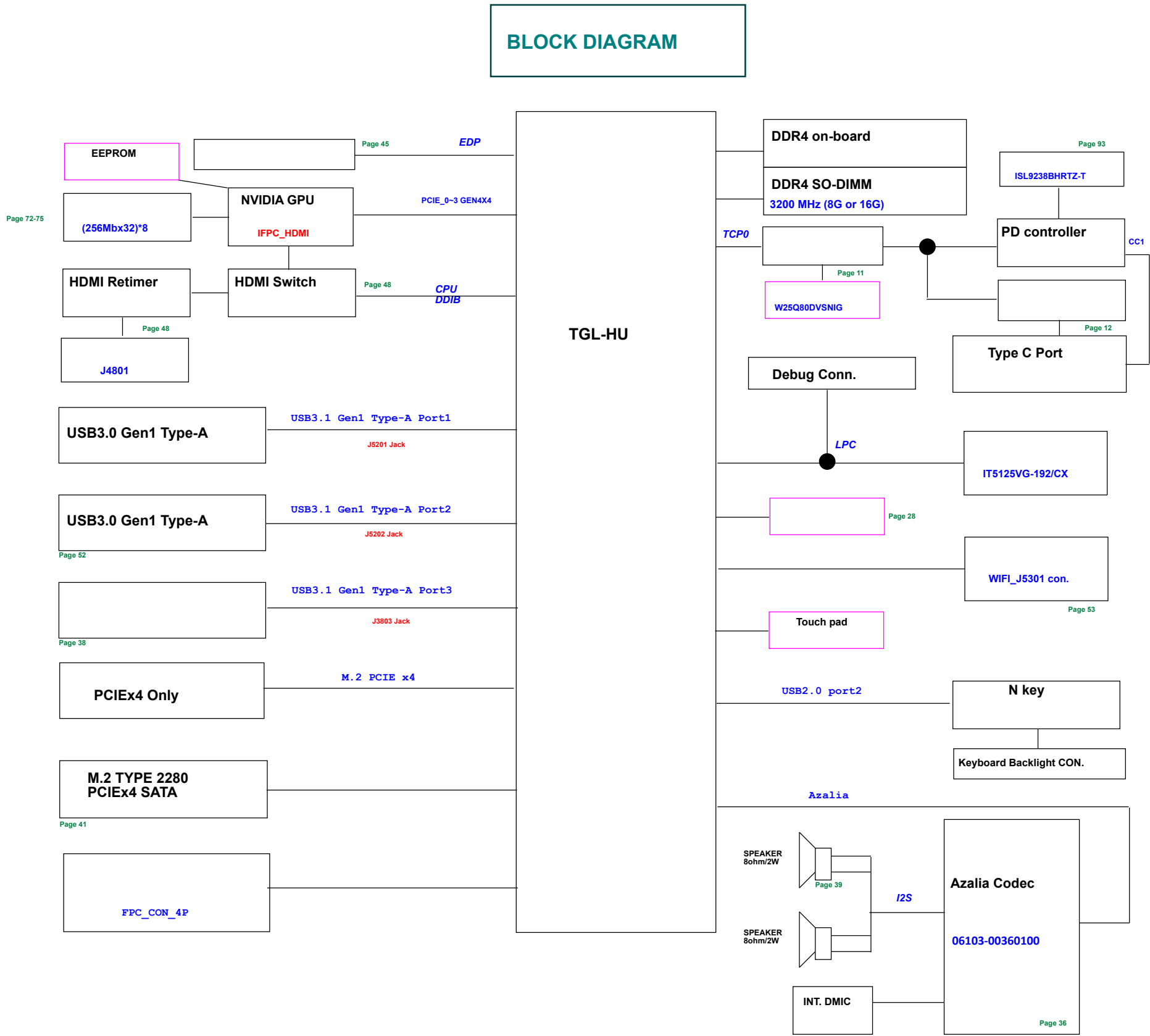
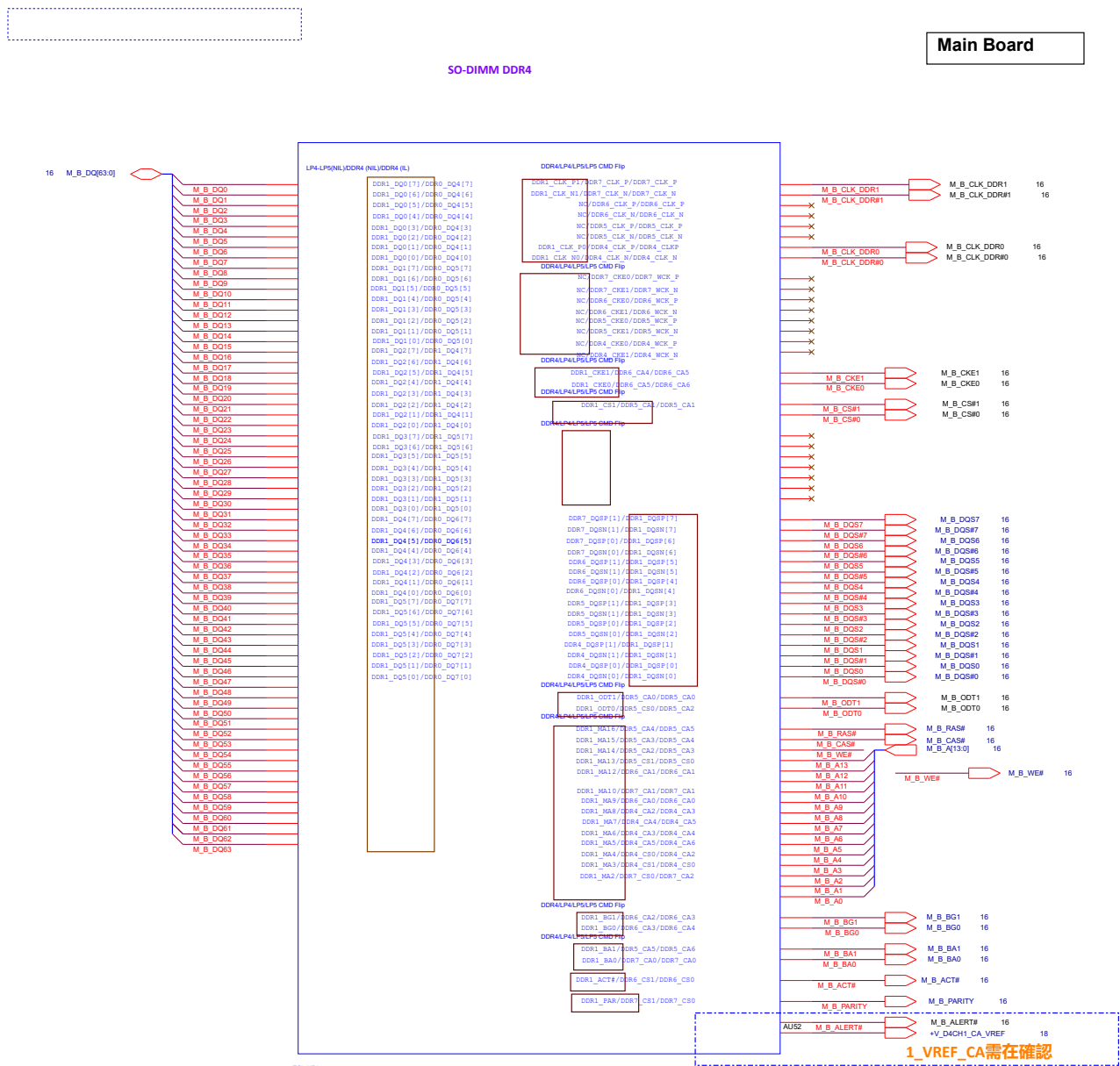
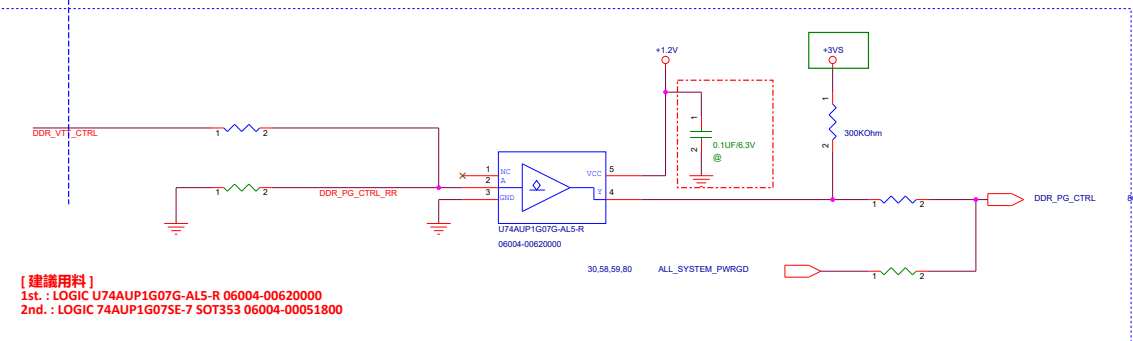
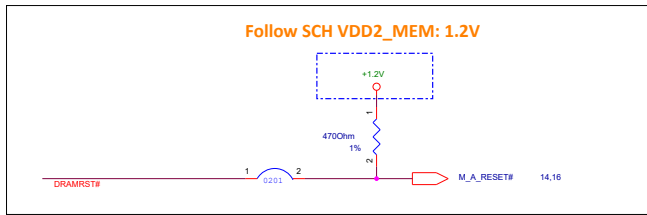




SYSTEM PAGE REF.

PAGE	Content
1	Block Diagram
2	System Setting
3	CPU_DMI,PEG,eDP,DDI
	CPU_DDR
5	CPU_GND
6	CPU_CFG,RSVD
7	CPU_ESPI,SPI,SMB,CLINK
	CPU_PCH_CSI2,EMMC,CNV
9	CPU_POWER
10	CPU_POWER_CAP
11	TBT_Titan Ridge SP
12	TBT_TPS65994ADType C
13	TBT
14	DIM_DDR4_ON-BOARD_A(1)
15	DIM
16	DIM_DDR4_SO-DIMM B(0) TOP
17	DIM_
18	DIM_CA/DQ Voltage
19	DDR4_TERMINATION*
20	PCH_HDA,SMBUS,SYS_PWR
21	PCH-CPT(2)_PCIE,USB2,MISC
22	PCH-CPT(3)_CLK,LPC,USB3
23	
24	PCH-CPT(5)_SPI
25	PCH-CPT(6)_GPIO
26	PCH-CPT(7)_POWER,GND
27	PCH-CPT(8)_POWER,GND
28	PCH-SPI_ROM,OTH
30	KBC_IT8995
31	EC_KB_TP
36	AUD-ALC3288
38	Audio_Jack
39	
40	Card Reader AU6465
44	BUG_Debug
45	CRT_LCD Panel_CMOS_DMIC
48	HDMI
51	NGFF_SSD
52	USB Port
53	USB 3.0 MB Type-C
54	G-sensor
56	LED_Indicator
57	DSG_Discharge
58	PRO_PROTECT
60	DC_DC BAT Conn.
62	ME_Conn Skew Hole
63	EMI_RF Reserve
64	U3_B2B CONN
66	WLANBT SIP
67	LID_Switch / FAN_connector
71	GPU MEMORY Interface
72	Frame Buffer
74	GPU STRAP
75	GPU GPIO
76	GPU VDD/GND
77	GPU FWG Decoupling
78	GPU Power
80_PW_IMVP8 (1)	
81_PW_IMVP8 (2)	
83_PW_+1.0VSUS / +1.8VSUS	
86_PW_1.2V/+0.6VS	
87_PW_+3VADSW/+5VSUS	
88_PW_LOAD SWITCH	
89_PW_CHARGER(BQ24780)	
90_PW_PROTECTION	
94_PW_VRAM	







CRG[7]	PEG deferred link training	Full-up to VCC down-Platform dependent
- 1 = (default) PEG Train immediately following RESET# de-assertion		
- 0 = PEG Wait for BIOS for training.		

Main Board

To ROM/TPM

28 SPI_CLK_SPI
28 PCH_SPI_DQ3
28 PCH_SPI_DQ2
28 SPI_SO_SPI
28 SPI_SI_SPI
28 SPI_CS#_SPI

DJ37

SP11_MISO_IO1/THC0_SPI1_IO1
SP11_MOSI_IO0/THC0_SPI1_IO0

GPP_B23/SMLIALERT#/PCHHOT#

GPP_A2/ESPI_IO2/SUSWRN#

GSXSRESET#/THC1_SPI2_IO3

GPP_E6

TGL-UP3

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SMB_CLK 28
SMB_SDA 28

GPP_C2

TBT_SMB_CLK 11
TBT_SMB_DATA 11

GPP_C5

PD_SMB1_CLK 12,28
PD_SMB1_DATA 12,28

GPP_B23

ESPI_CLK 30
ESPI_IO3 30
ESPI_IO2 30
ESPI_IO1 30
ESPI_IO0 30
ESPI_CS# 30
ESPI_RST# 30

To EC

To SO-DIMM

Reserved for TBT Vpro

to PD

+3VSUS

UX435

PD_SMB1_CLK

PD_SMB1_DATA

SMB_CLK

SMB_SDA

TBT_SMB_DATA

SPI0_MOSI need 100K pulled up to SPI_SI_SPI

GPP_C2

GPP_E6

+1.8VSUS

Follow Intel TGL-UP3 CRB

47KOhm

GPP_E6

20KOhm

@

nbs_r0201_h10_000s

1%

BFX STRAP 1 -BIT1 WEAK INT.PD 20K

GPP_C5

1

2

+1.8VSUS

VPRO ENABLE STRAP

LOW: TLS CONFIDENTIALITY DISABLE
HIGH: TLS CONFIDENTIALITY ENABLE
WEAK INT.PD 20K
Must be pulled up to support
Intel AMT with TLS.

+1.8VSUS

47KOhm

@

GPP_C2

20KOhm

@

nbs_r0201_h10_000s

1%

CPUNSSC CLOCK FREQ
HIGH:19.2MHZ CLOCK FROM DIVIDER
(DERIVED FROM 38.4MHZ CRYSTAL)
LOW: 38.4MHZ CLOCK FROM DIRECT CRYSTAL (DEFAULT)
WEAK INT.PD 20K

+1.8VSUS

47KOhm

@

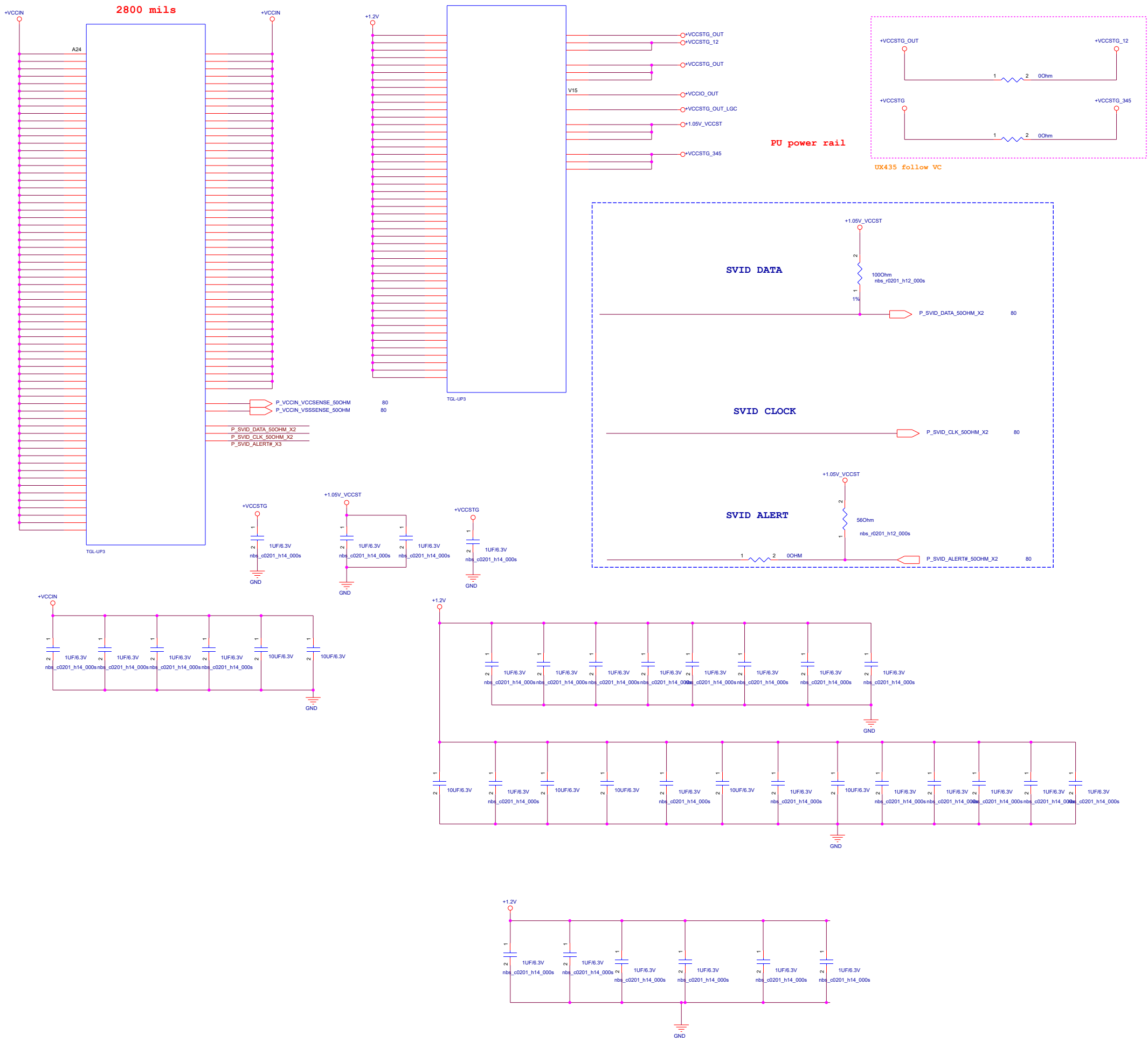
GPP_B23

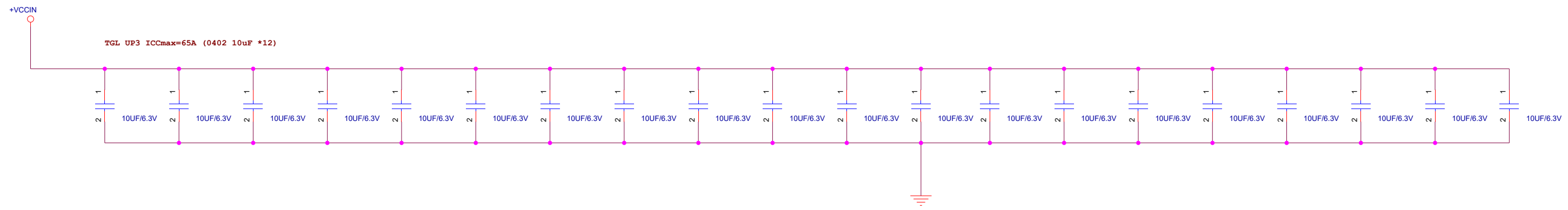
20KOhm

@

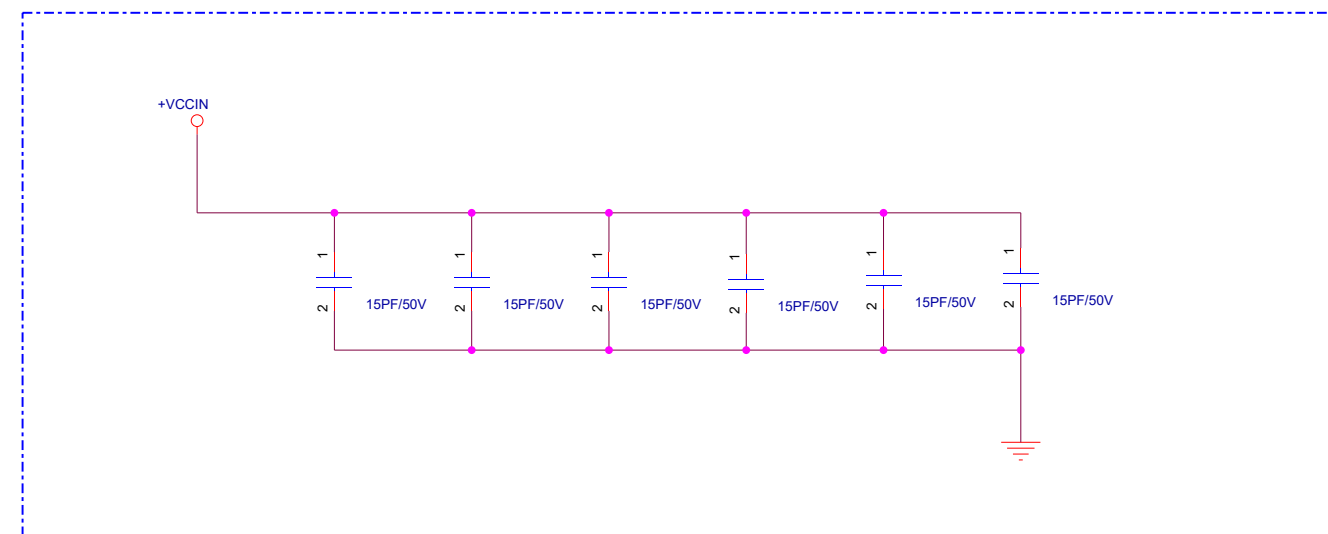
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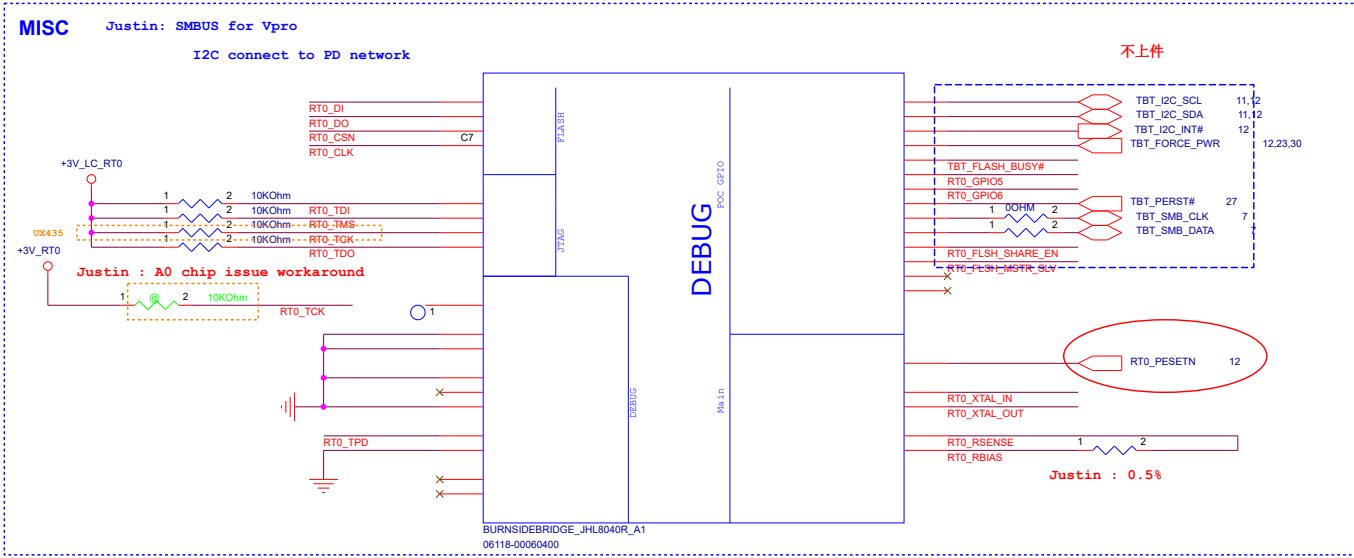
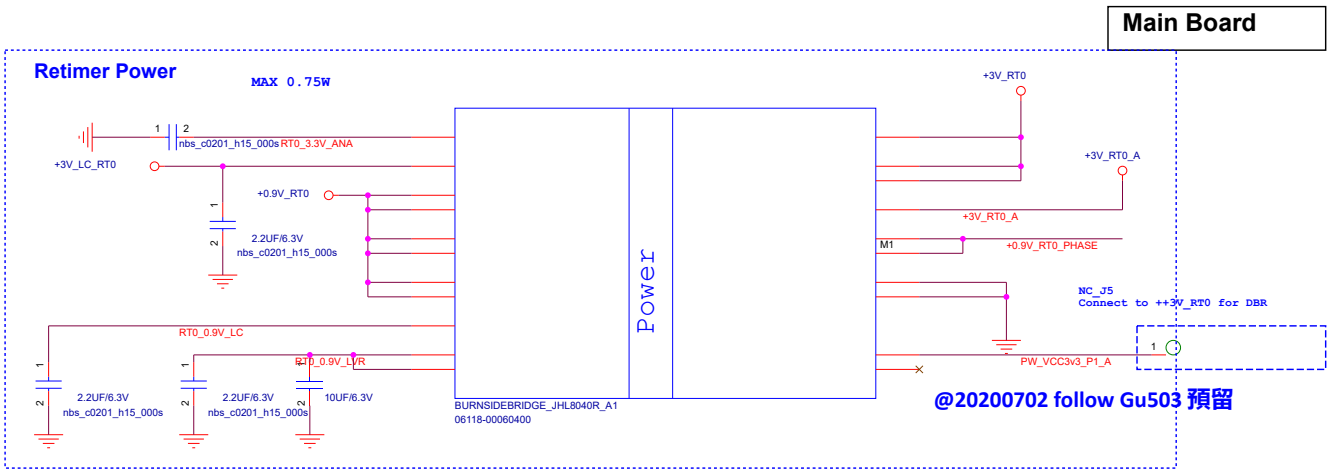
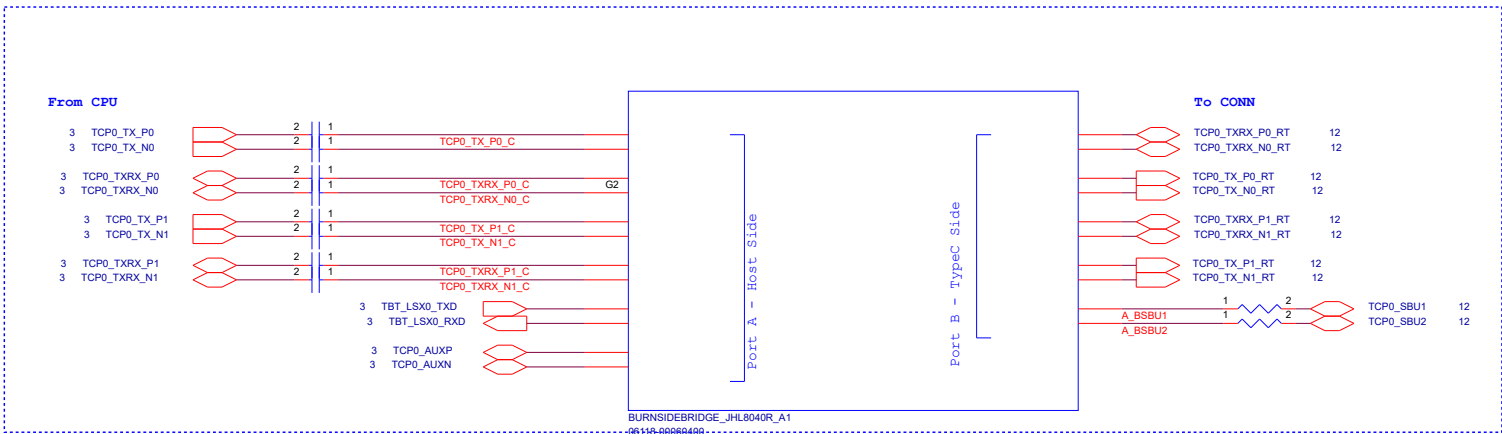
1%



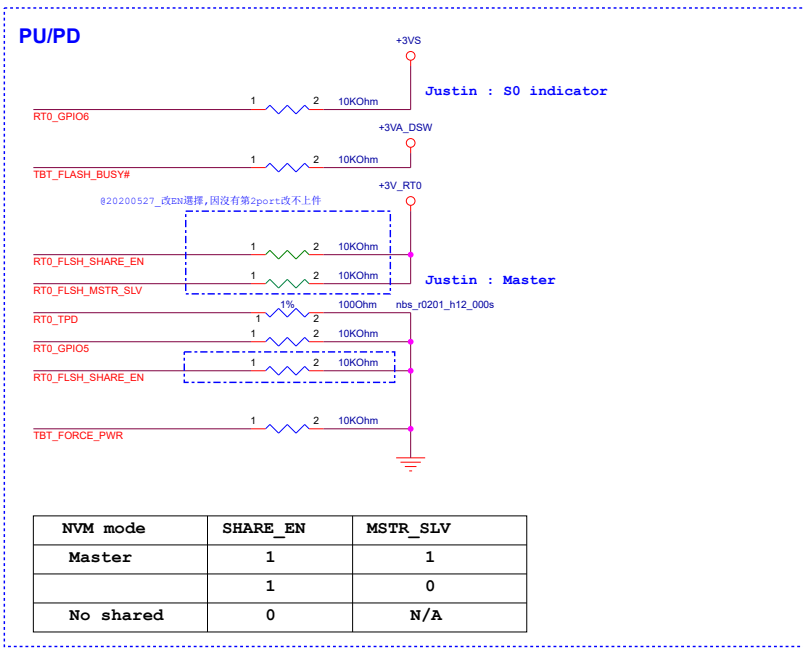
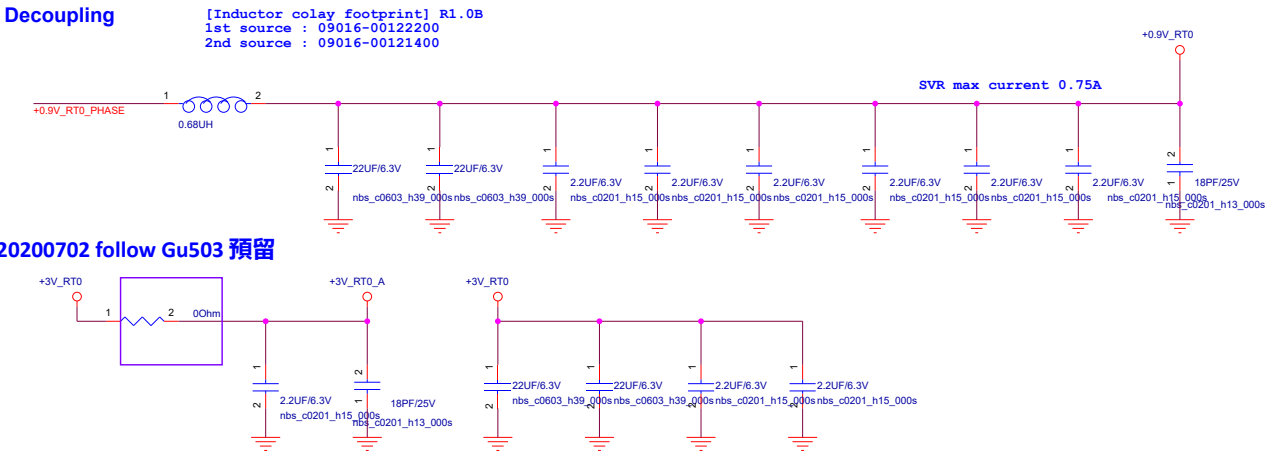


@20200616_add C1031~36: 15PF for EMI/RF

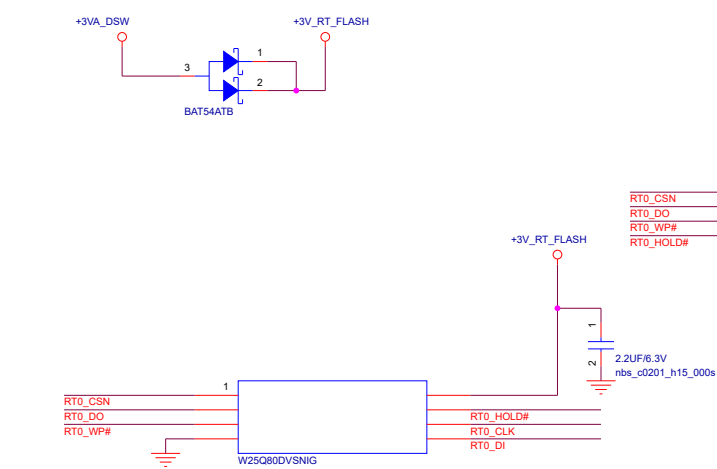




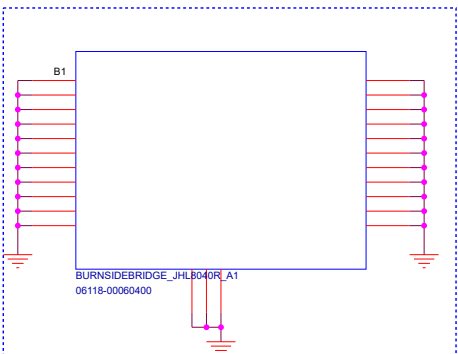
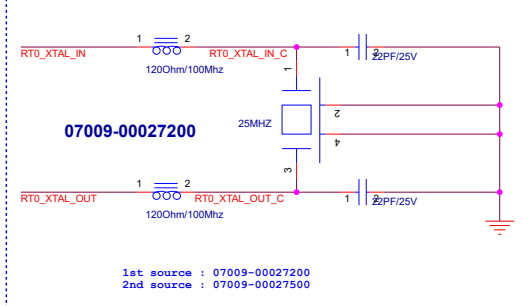
Decoupling



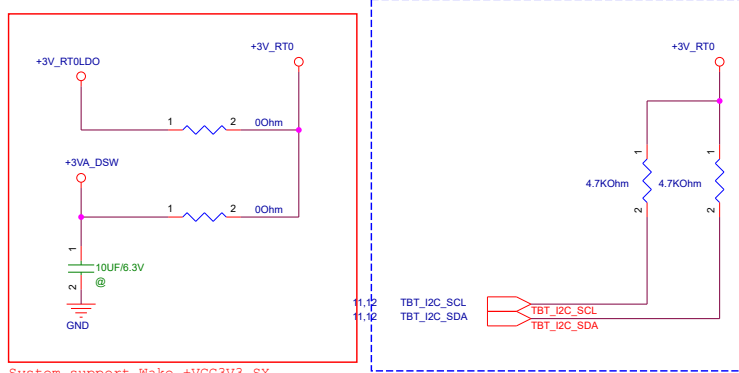
Flash ROM



25Mhz Xtal

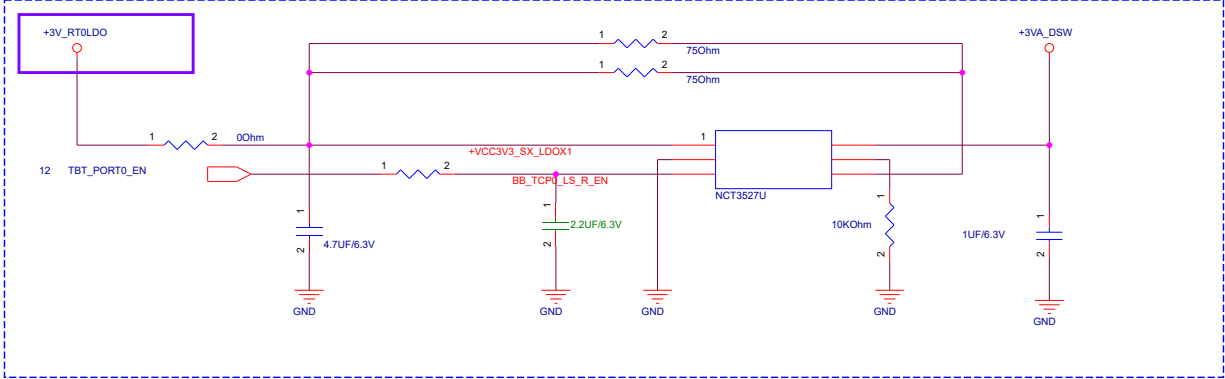


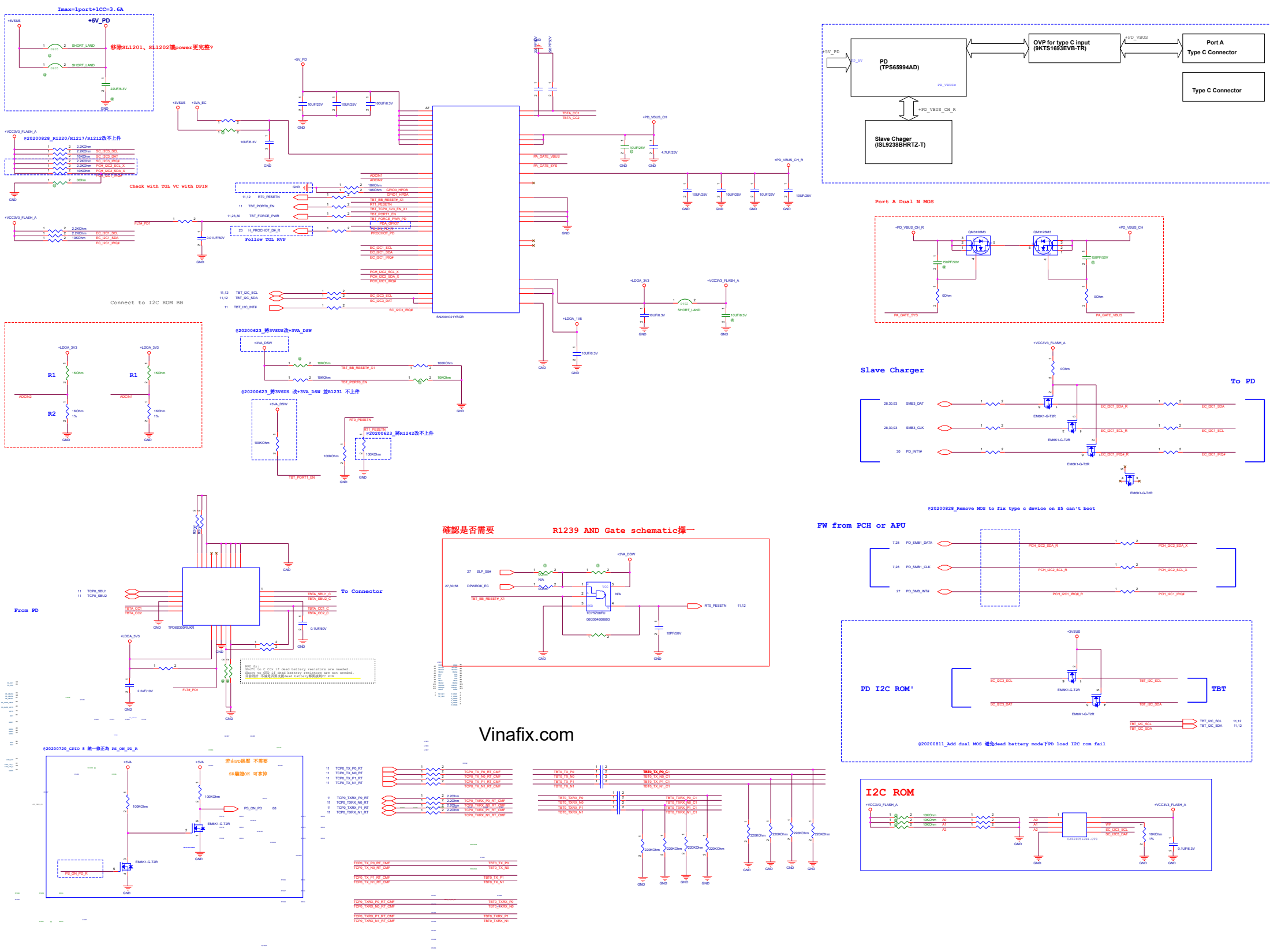
@20200702 follow Gu503 預留



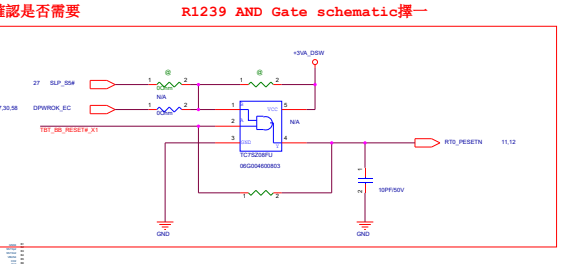
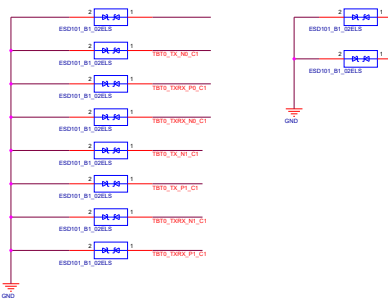
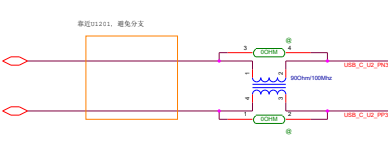
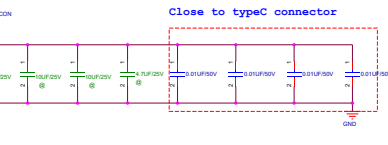
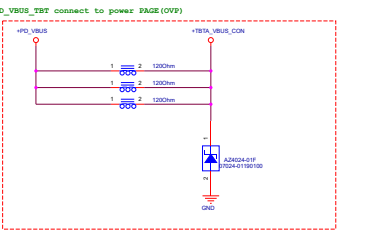
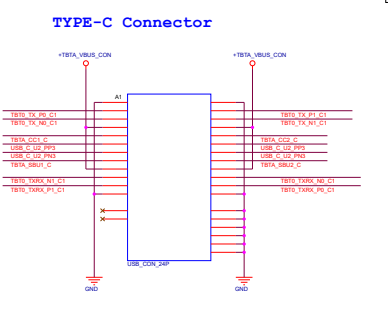
Check which power solution should be used

@20200702 follow Gu503 預留

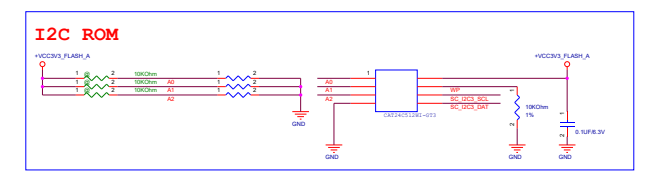




Main Board



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BR02_Miscion: 03012-0003000
BR02_Mainwing: 03012-0003100

1G:80Q
Total: 1G8Sea + 8G

DDR4 3200 2048M*8 1.2V ~ 1.35
BR02_Mainwing: 03012-0004000 (虎改更真_0603)
BR02_Mainwing: 03012-0004010

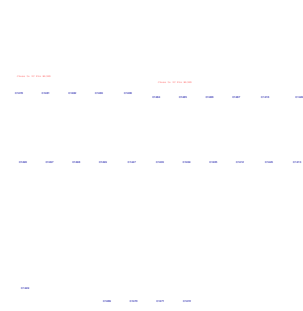
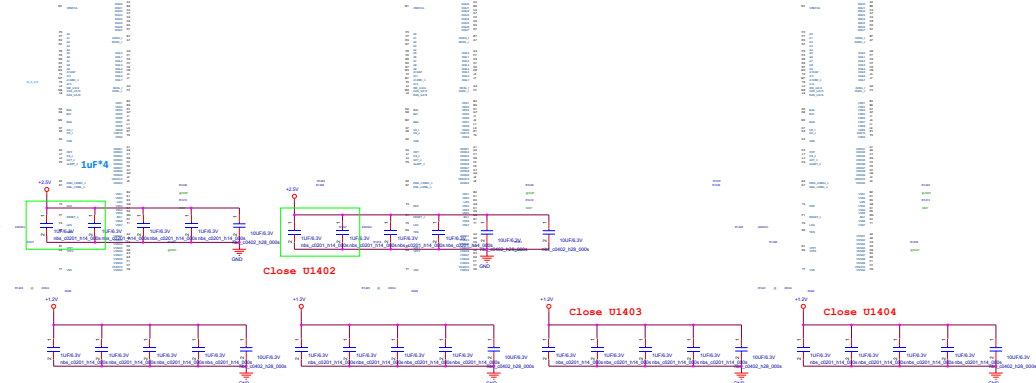
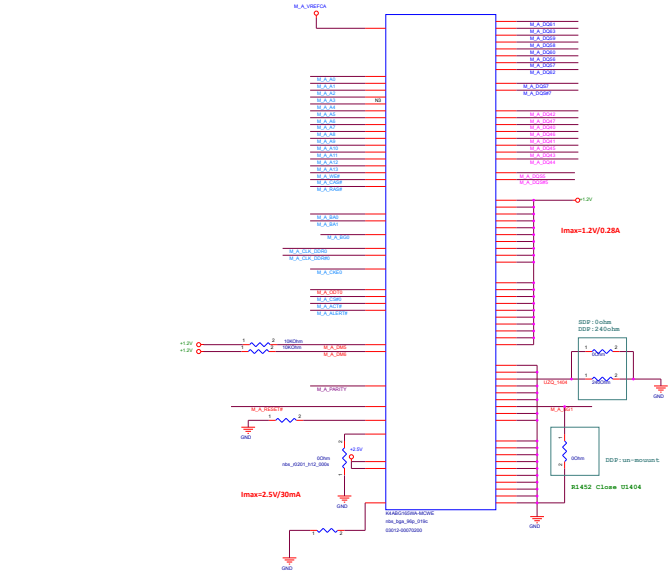
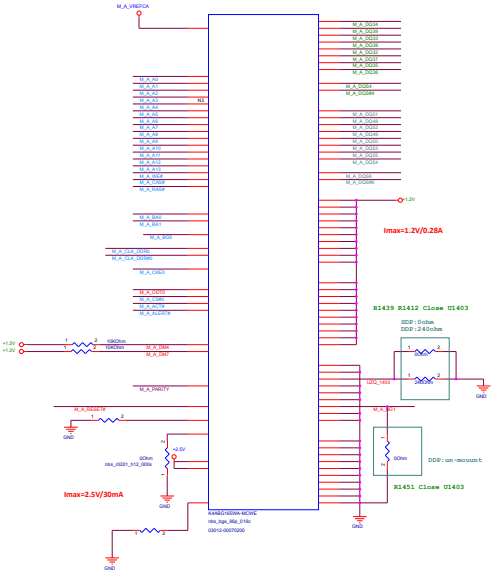
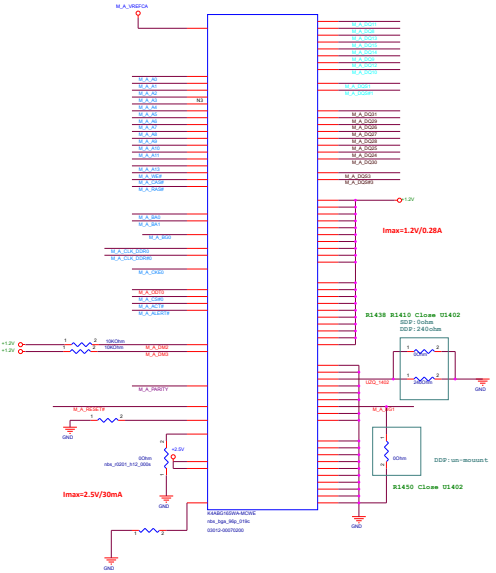
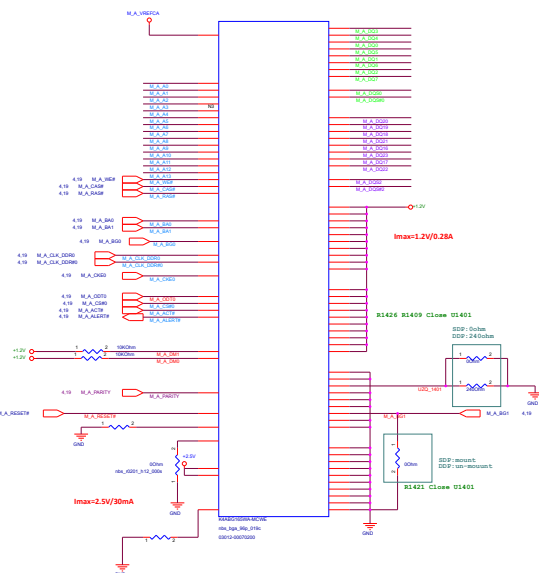
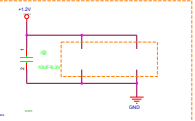


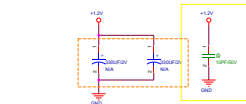
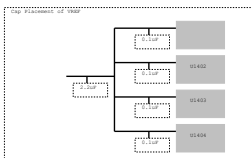
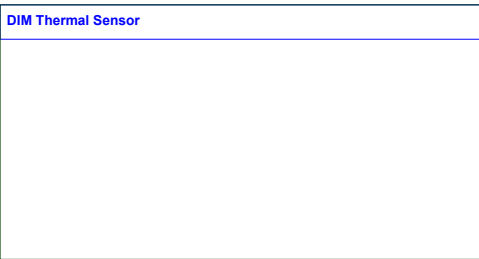
Table 4-25. DDR4 Memory Down Power Plane Decoupling

Memory Configuration	Power Domain	Decoupling Location	Qty x pF (size)	Note
DDR4 Memory (down) x8-B Devices per Channel	VDDQ/VDD (shuffled)	4.8u near each x8 DRAM device on device	64x 1uF (0402) (min of 48 shuffled)	
		Distributed around the DRAM devices	20x 10uF (0603) (min of 12 shuffled)	
	VBP	2.8u near each x8 DRAM device on device	32x 1uF (0402)	
	VTT	Distributed around the DRAM devices	10x 10uF (0603)	
		Distributed along termination resistors	32x 1uF (0402)	
		Distributed evenly across domain	8x 10uF (0603)	



Add C1401 C1402 C1458
0603 0603 0603
@20190713A

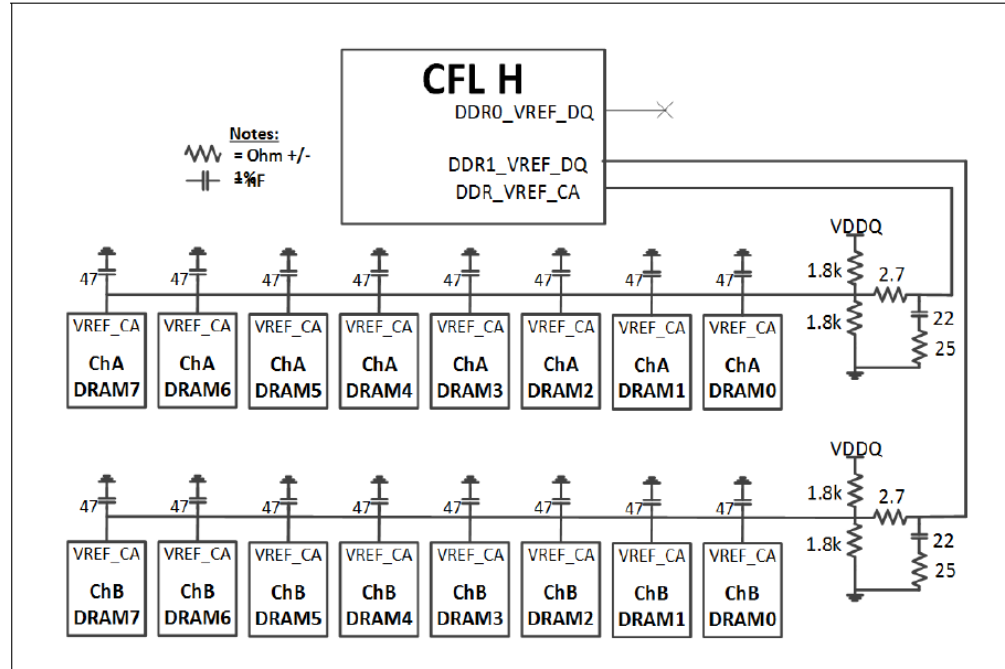
Delete C1402 C1458
C1401 0603 - 0603
0603 0603
@20190715E



C1402, C1401 (220uF) change to C1361 (330uF)
@20190626A



Figure 4-24. CFL-H DDR4 x8 Memory Down V_{REF-CA} Overview



Memory Down Vref

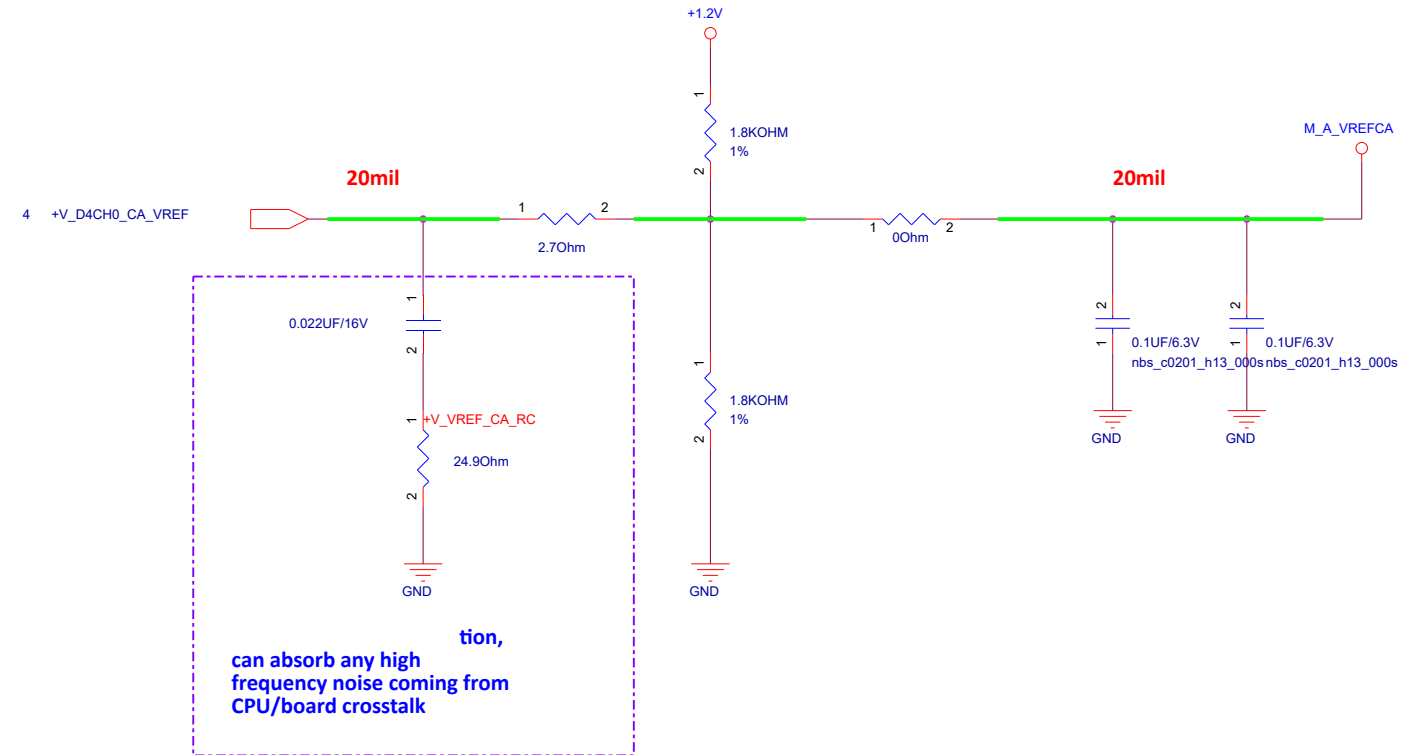
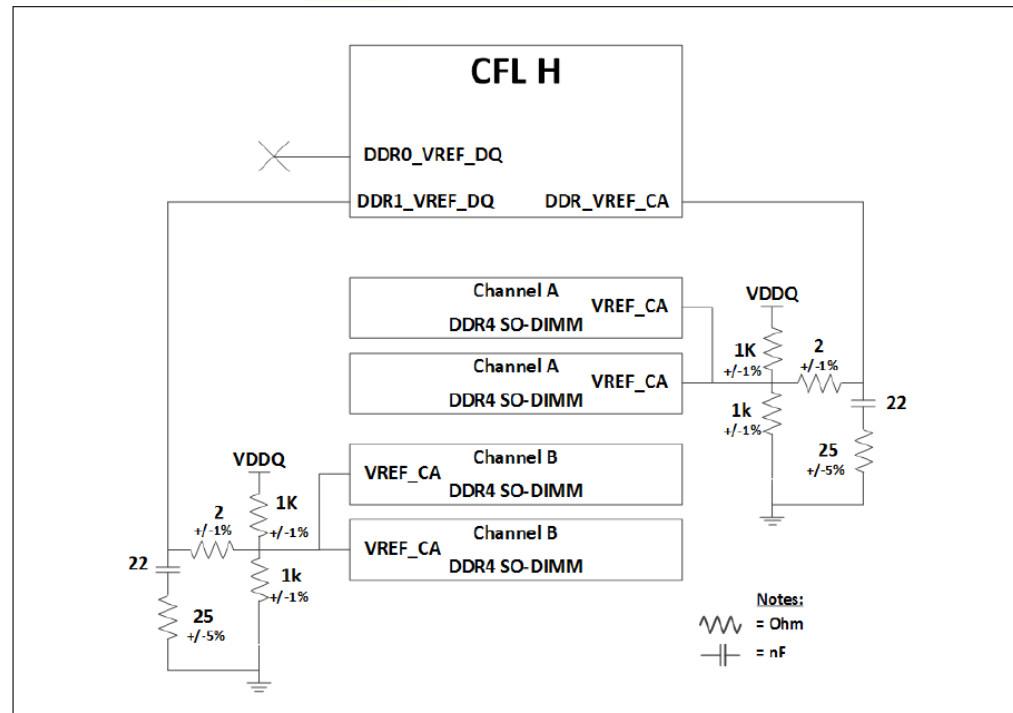
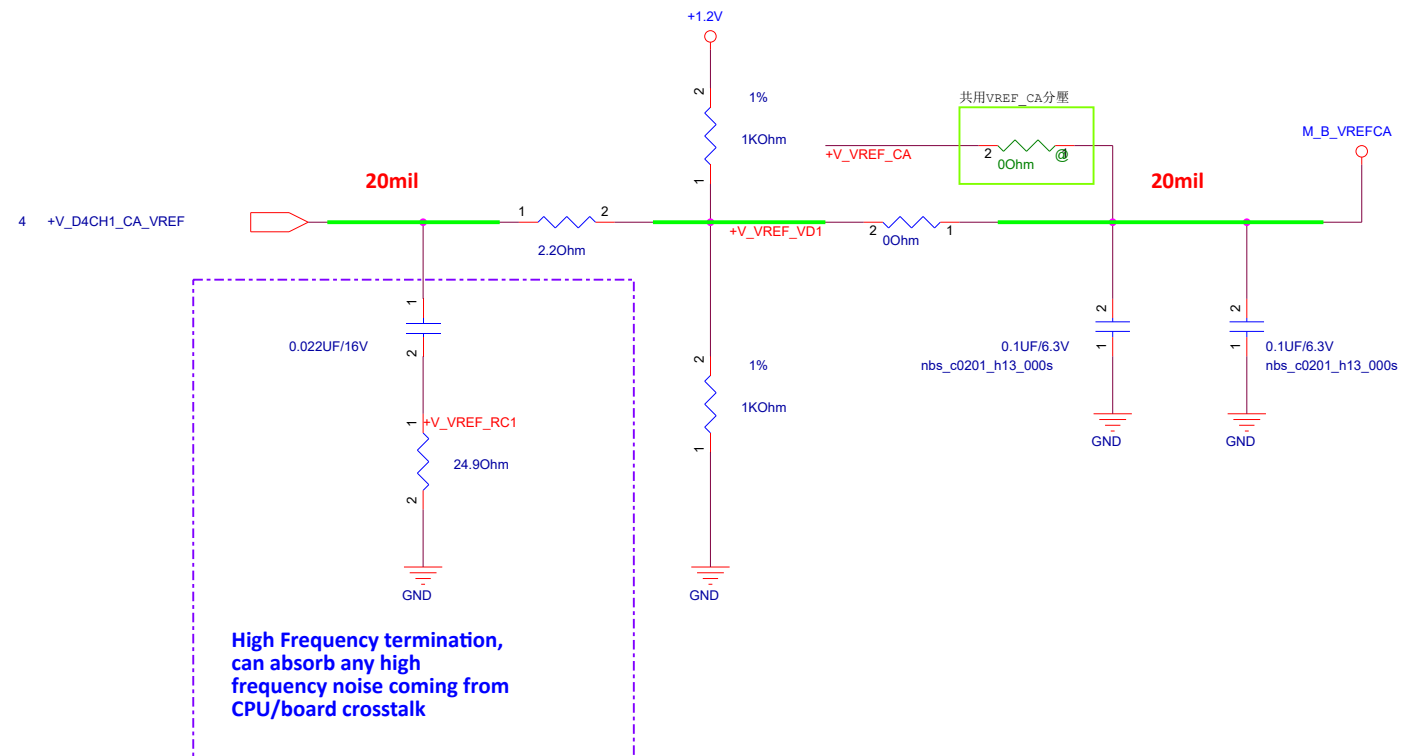
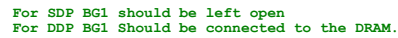


Figure 4-22. CFL-H DDR4 SO-DIMM V_{REF-CA} Overview

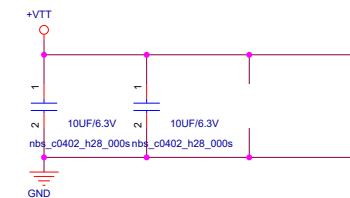
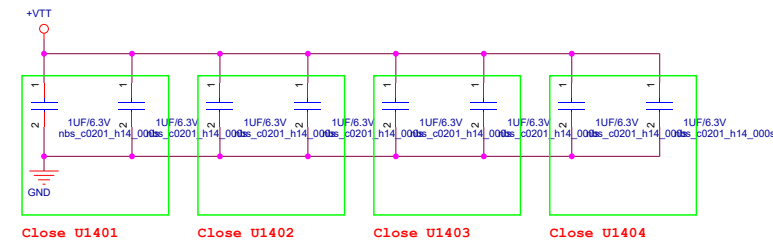
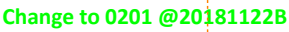


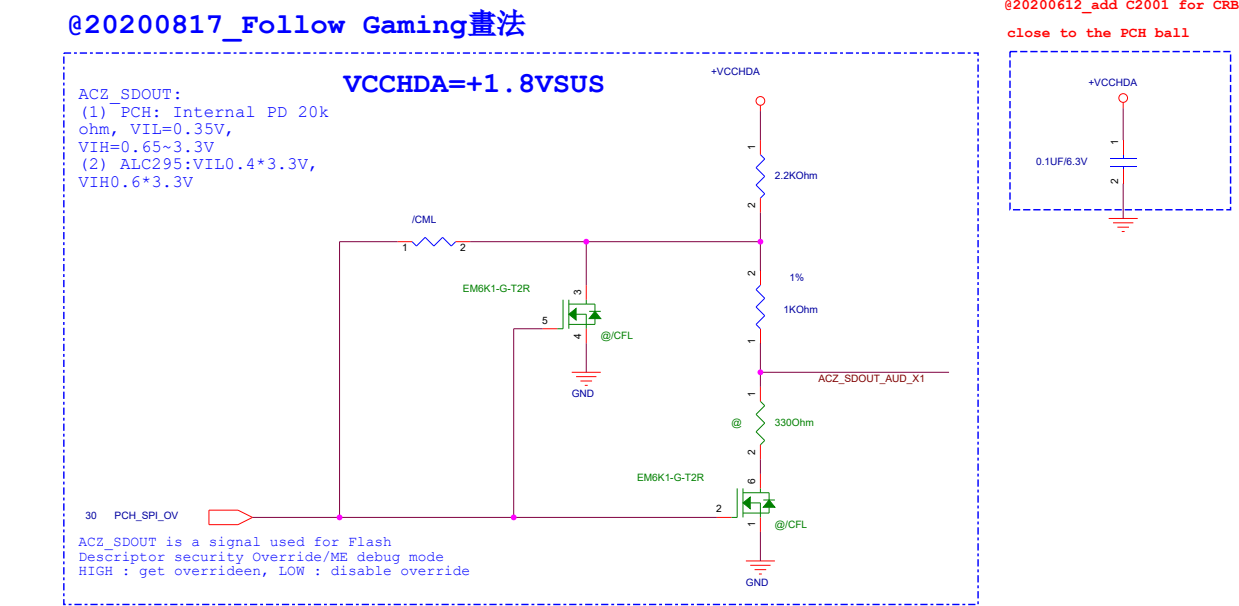
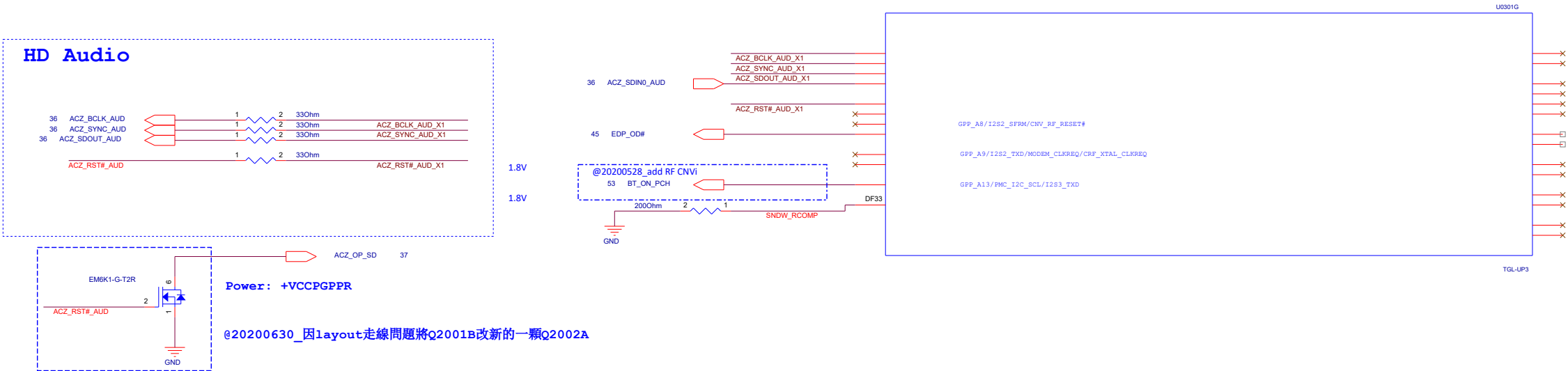
SO-DIMM1 Vref





Memory Configuration	Power Domain	Decoupling Location	Qty x μ F (size)	Note
DDR4 Memory Down x8- 8 Devices per Channel	VDDQ/VDD (shorted)	4 as near each x8 DRAM device as possible	64x 1 μ F (0402) (min of 48 stuffed)	
		Distributed around the DRAM devices	20x 10 μ F (0603) (min of 12 stuffed)	
	VPP	2 as near each x8 DRAM device as possible	32x 1 μ F (0402)	
		Distributed around the DRAM devices	10x 10 μ F (0603)	
	VTT	Distributed along termination resistors	32x 1 μ F (0402)	
		Distributed evenly across domain	8x 10 μ F (0603)	



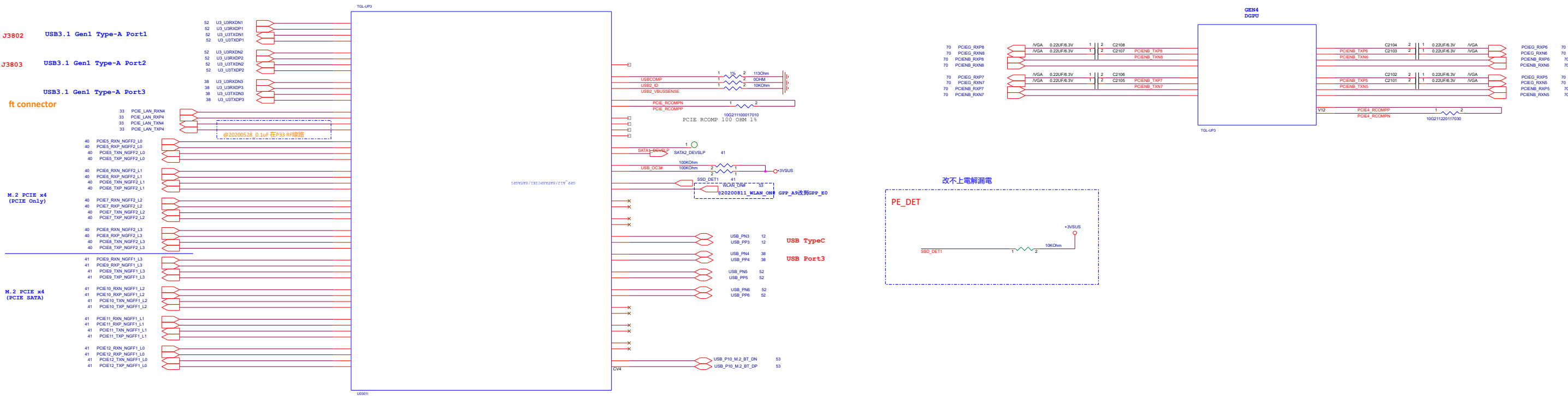


U3001G

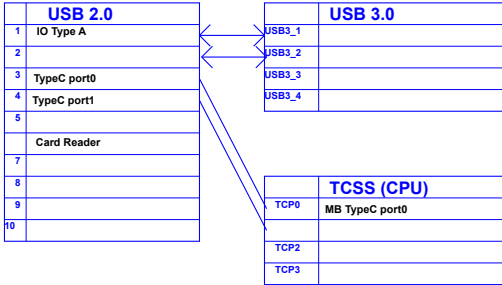
U3001G

U3001G

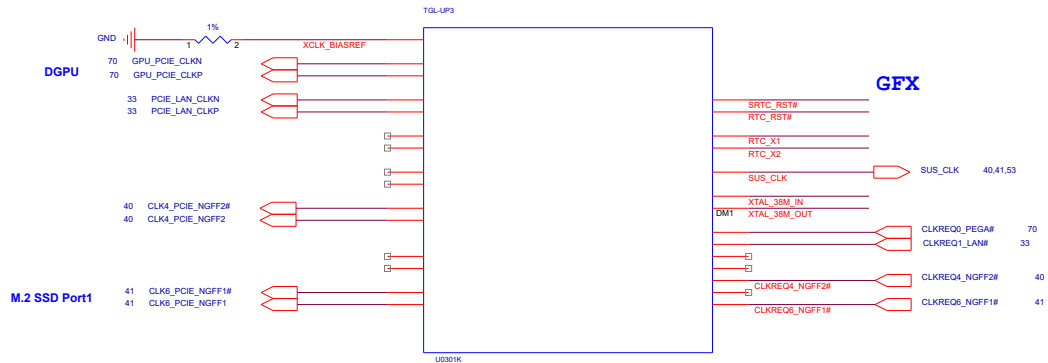
U3001G



PCI-E* X1	PCI-E USAGE SERIAL/OPTION	Co-lay	Clock
PCI-E 1	N/A		
PCI-E 2	N/A		
PCI-E 3	N/A		
PCI-E 4	N/A		
PCI-E 5	N/A		
PCI-E 6	N/A		
PCI-E 7/DATA 0	N/A		
PCI-E 8/DATA 1A	N/A		
PCI-E 9	N/A		
PCI-E 10	N/A		
PCI-E 11/DATA 0	N/A		
PCI-E 12/DATA 1A	N/A		
PCI-E 13	PCI-E SSD		
PCI-E 14	PCI-E SSD		
PCI-E 15/DATA 1B	PCI-E SSD		
PCI-E 16/DATA 2	PCI-E SSD	SATA SSD	

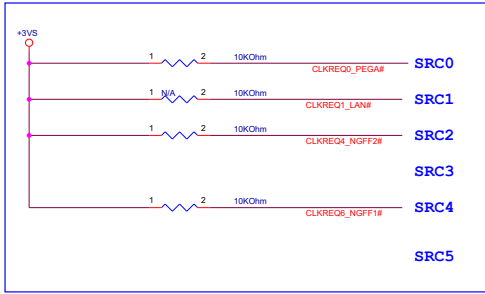


Vinafix.com

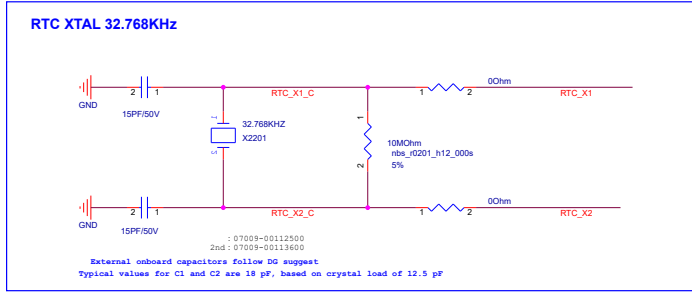


CLKOUT_PCIE_P/N [6:4, 2:1] = Support up to PCIe Gen3
CLKOUT_PCIE_P/N [3, 0] = Support up to PCIe Gen4

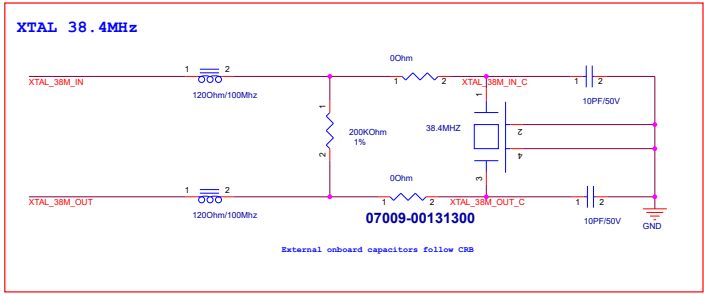
• CLKOUT_PCIE_P/N [3, 0] = Must be used for PCIe* Gen4 support
Any un-used CLKOUT_PCIE_P/N differential pair not being routed on a platform should be configured as "Disabled" through the Intel® Flash Image Tool (FIT) tool. The CLKOUT_PCIE_P/N differential pairs are called out as CLKOUT_SRC differential outputs in FIT as discussed in the SPI Programming Guide.



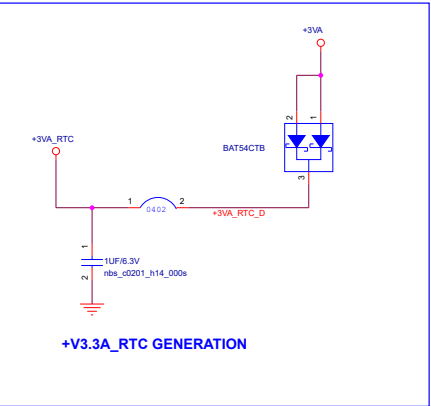
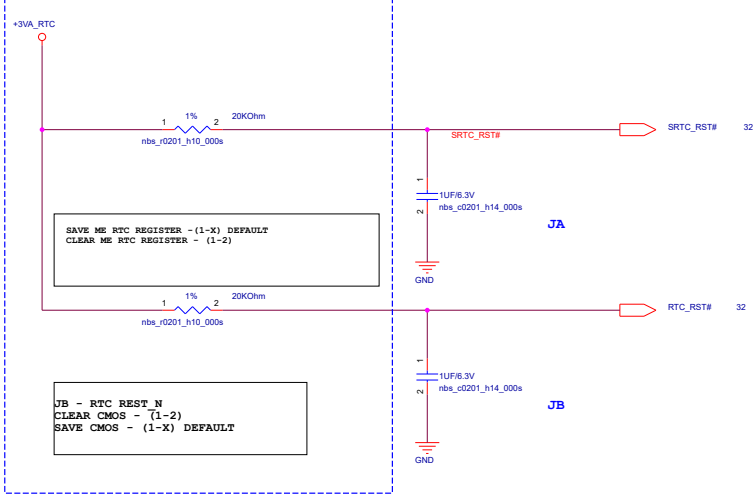
@20200630_XTAL change 07009-0011800 15PF for UX482



@20200630_将C2201 C2202 Change 10PF for UX482 R1.1

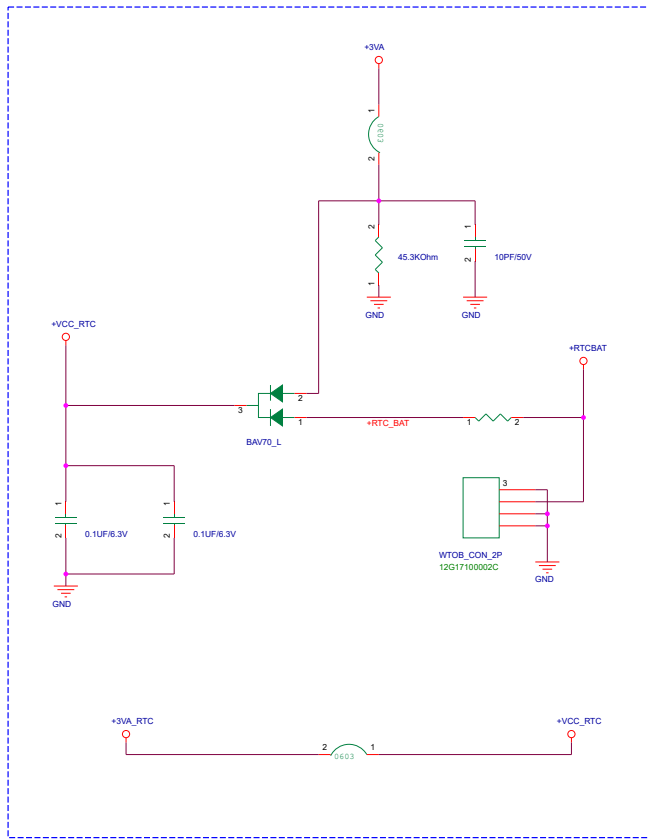


@20200611_R2209_R2210 由27K改20K for CBB

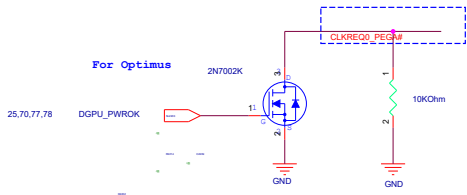


Justin : No used divided resisters. PCH has Rload inside and +3VA PU will cause VCCRTC drop to 2.7V in S0
VCCRTC must not exceed 3.3V and sustained operation at voltages below 3.0V is not recommended
Intel suggested to use diode circuit for long life reliability

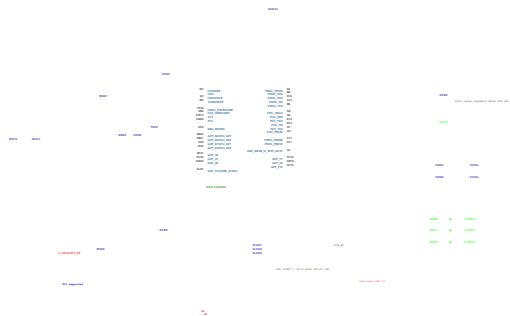
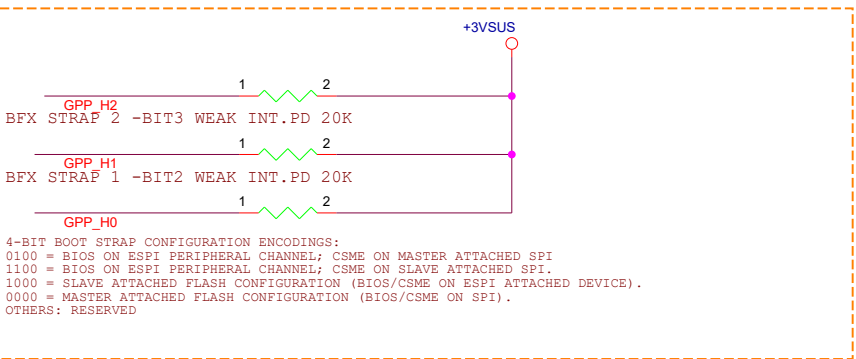
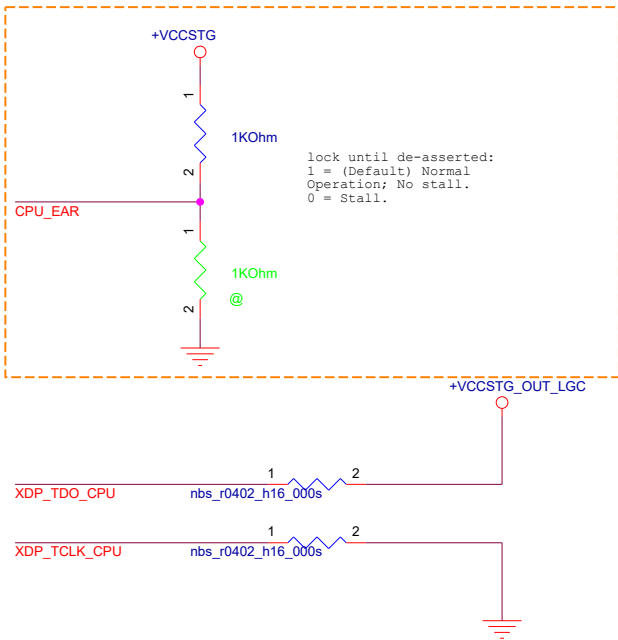
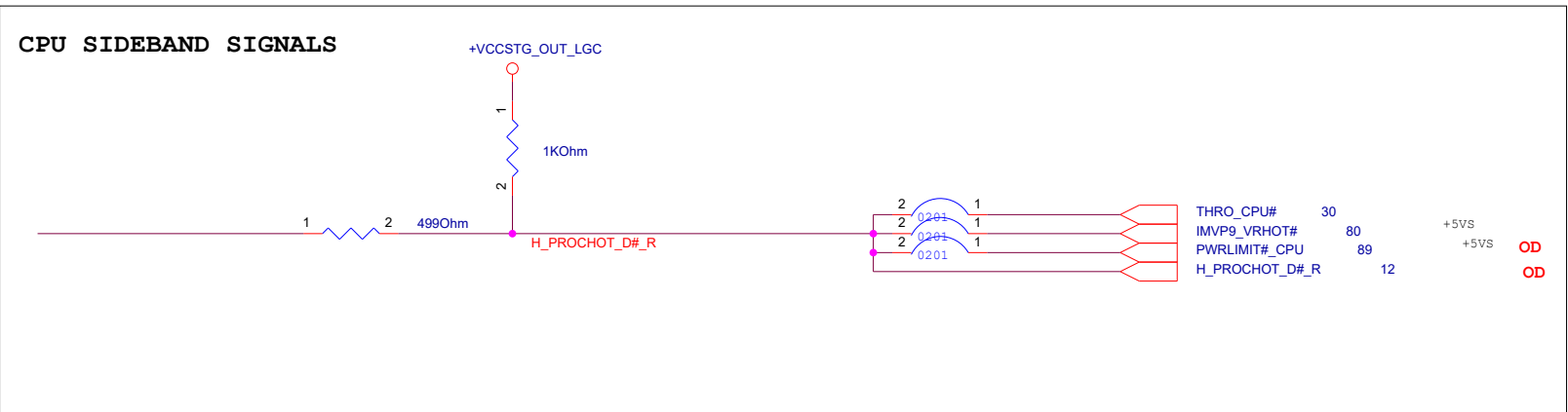
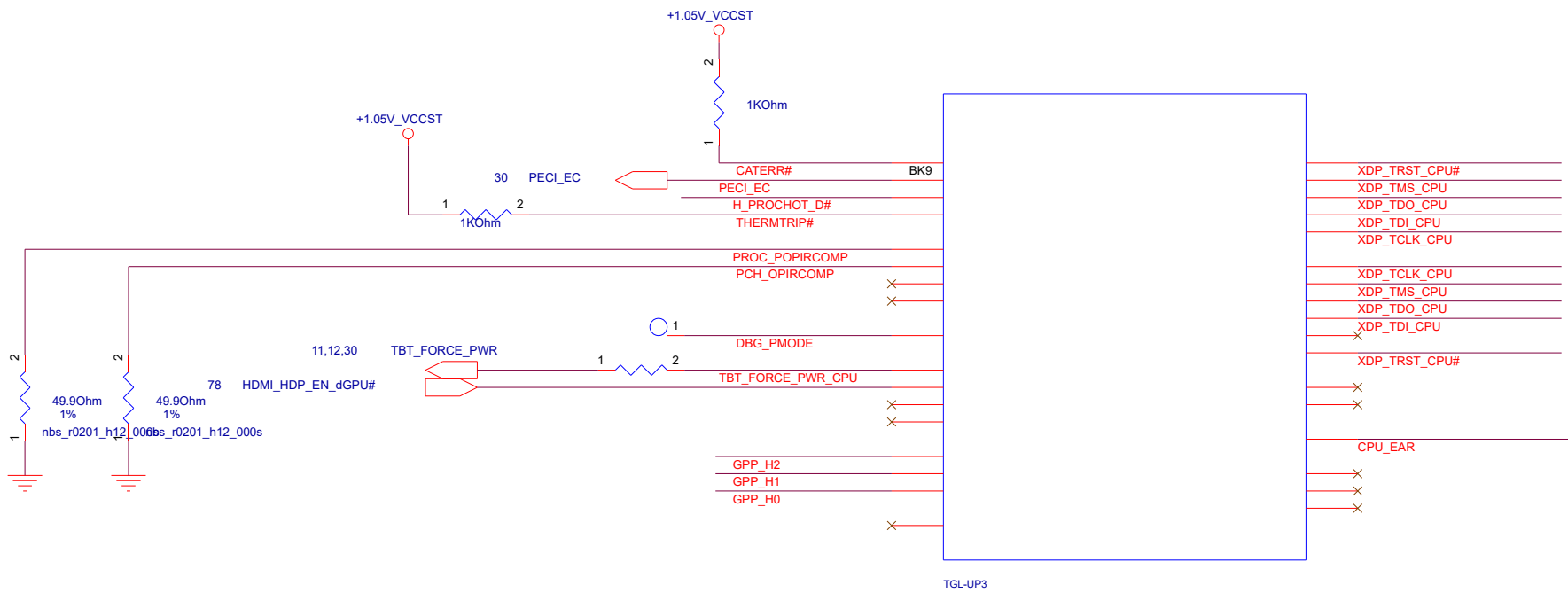
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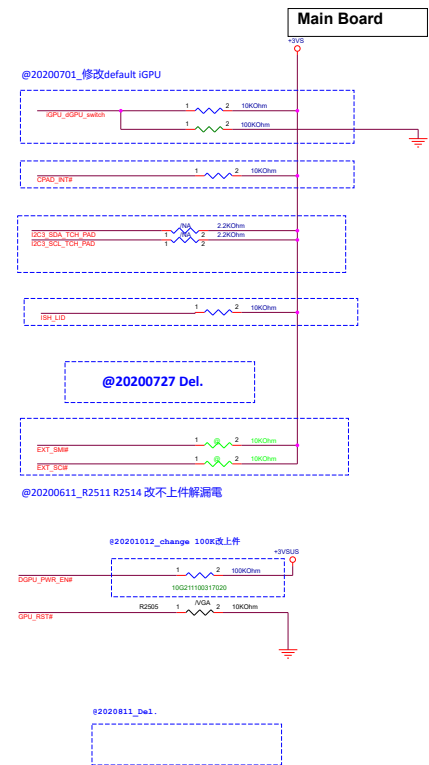


@20200630_change name CLKREQ*_PEGA#

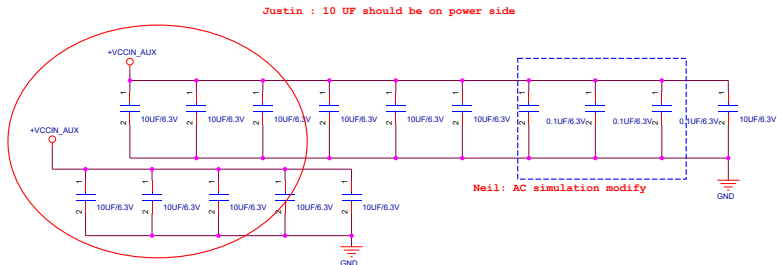
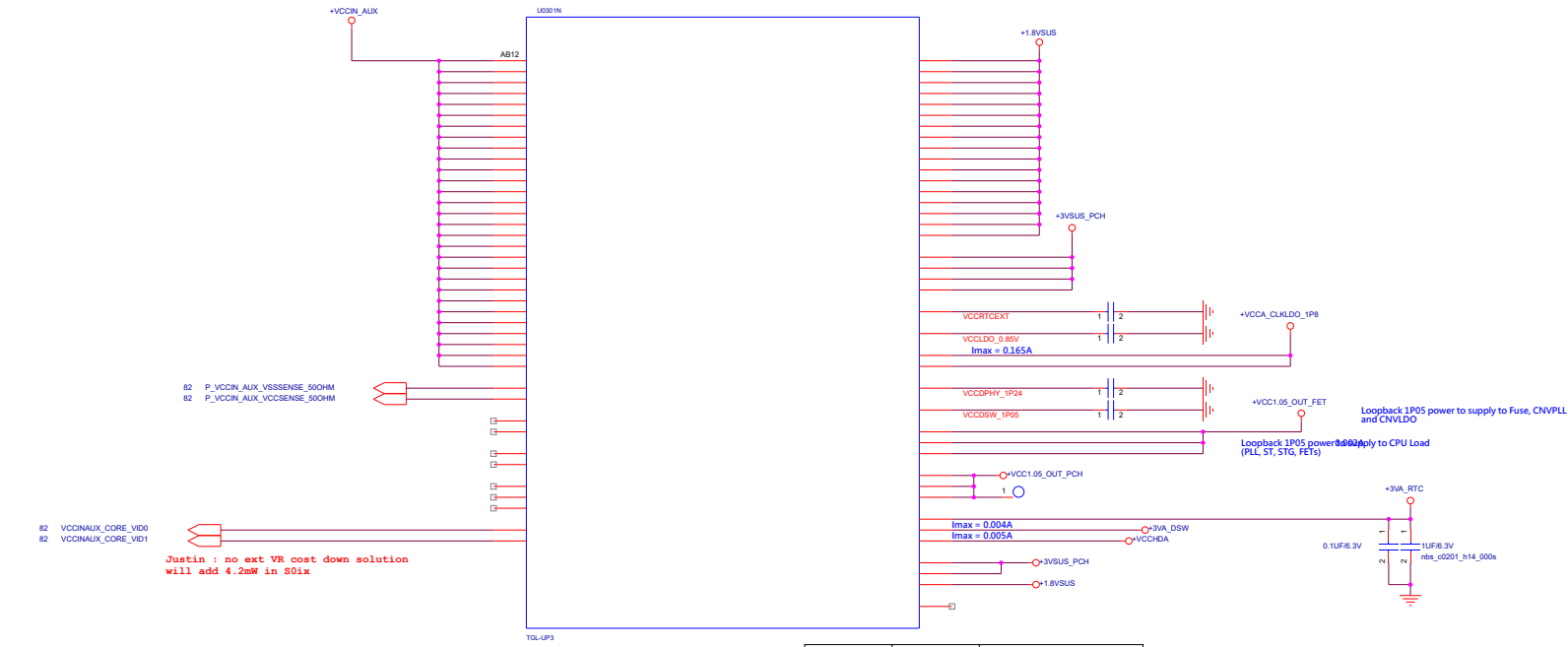


Main Board

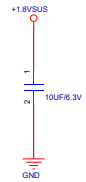
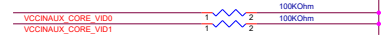




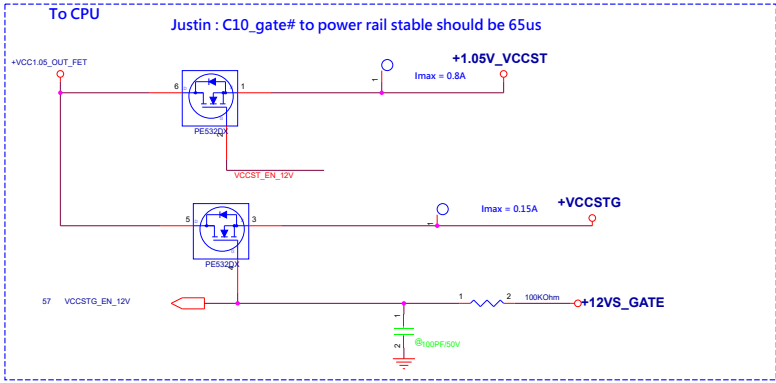
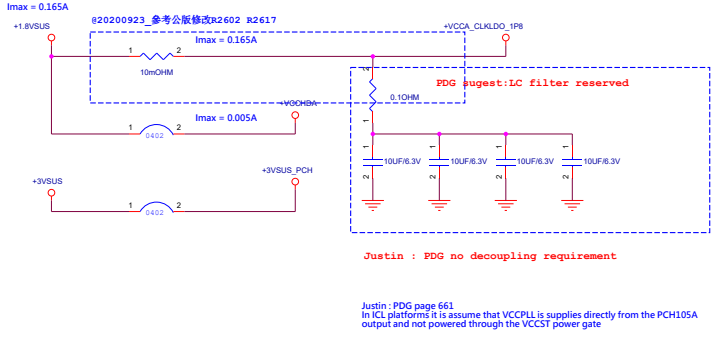
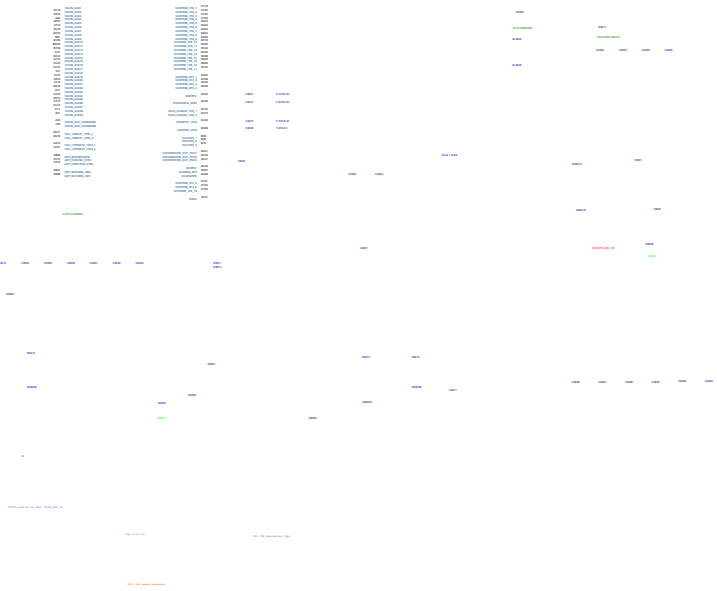
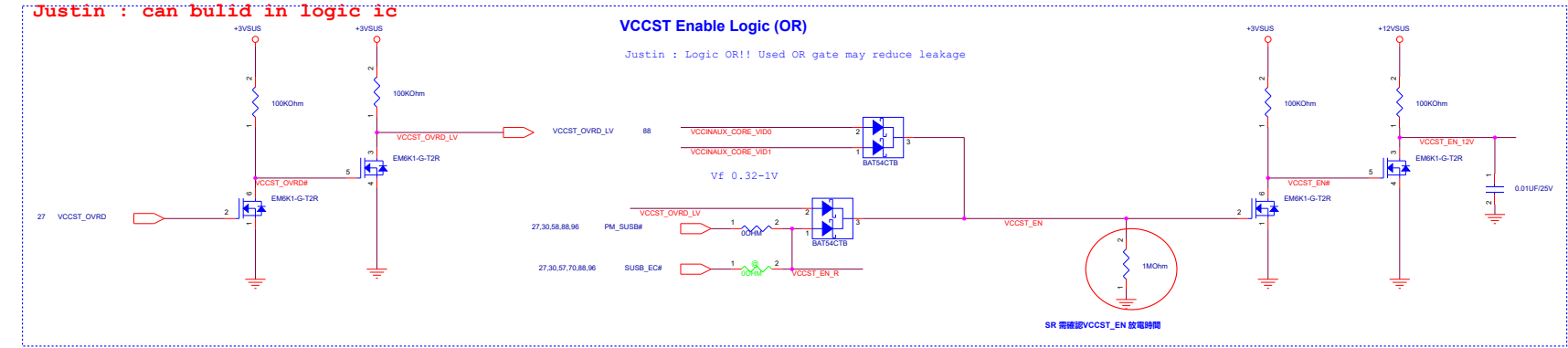
			DIMM_SEL#			Key Part List
			opt_c14	opt_c13		
			2	1		
03012-00070200	目前线路		0	0	0	: R2508 / R2510 / R2513 不上件: R2509 / R2512 / R2515
			0	0	1	
		MEMO 8Gb	0	1	0	: R2508 / R2512 / R2513 不上件: R2509 / R2510 / R2515
03012-00040700				1	1	不上件: R2509 / R2512 / R2513 不上件: R2508 / R2510 / R2515
				1	0	
03012-00070300	SRU1	Hywin 16Gb	1	0	1	: R2508 / R2510 / R2515 不上件: R2509 / R2512 / R2513
			1	1	1	



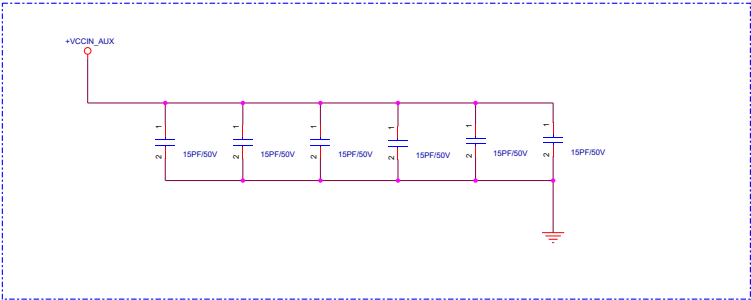
VID1	VID0	VCCIN_AUX
	0	0V
0	1	1.1V
1	0	1.65V
1	1	1.8V

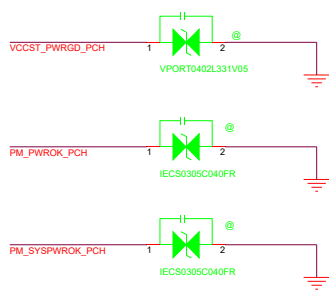
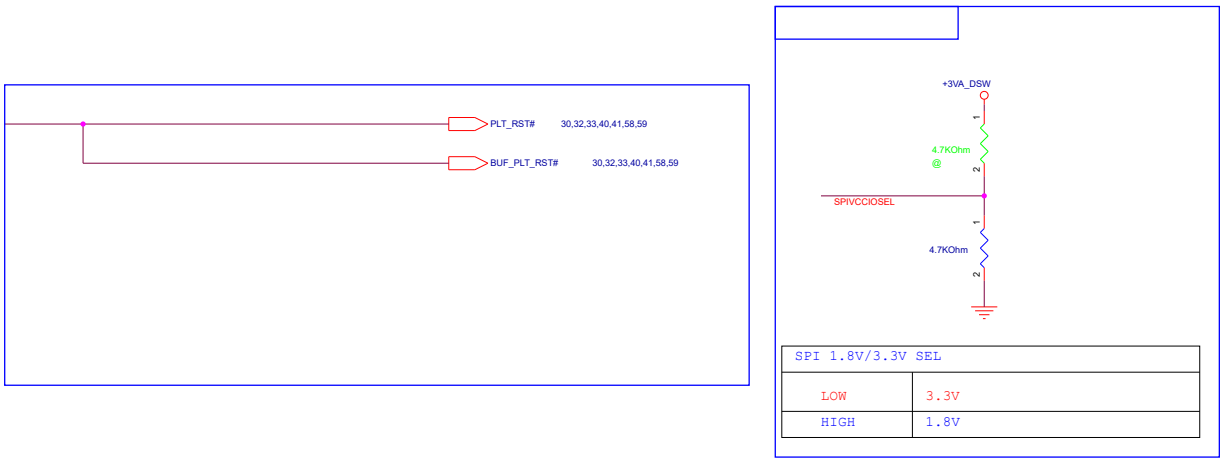
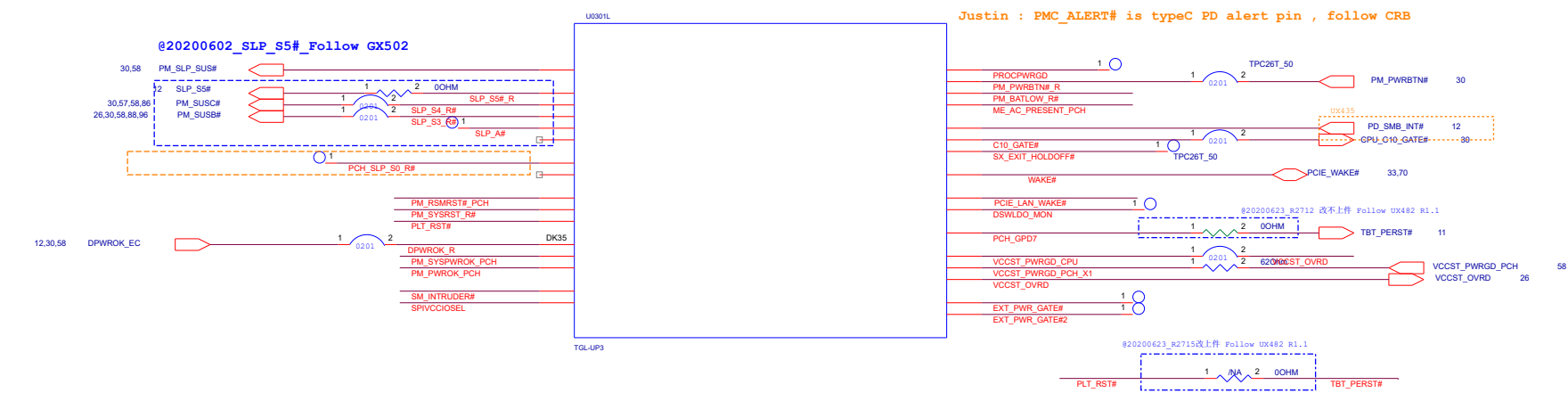


Justin : can bulid in logic ic

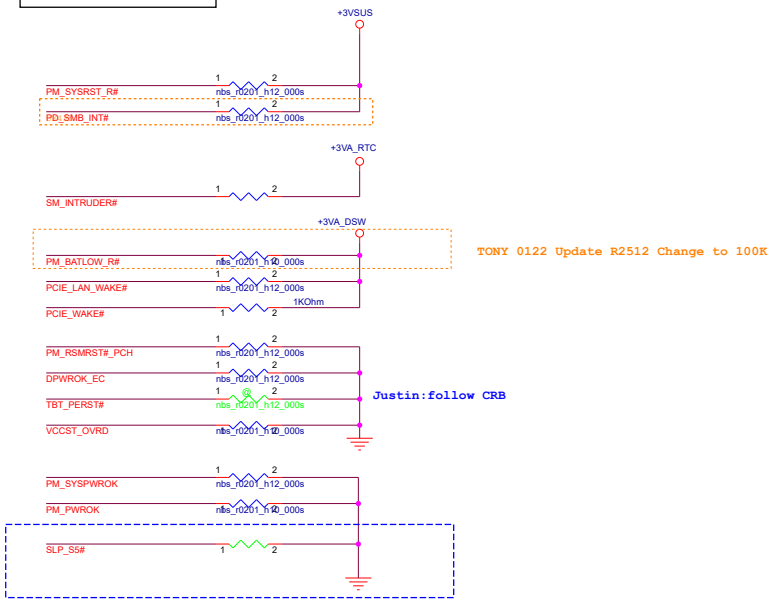


@20200616_add C2683~88 : 15PF for EMI/RF



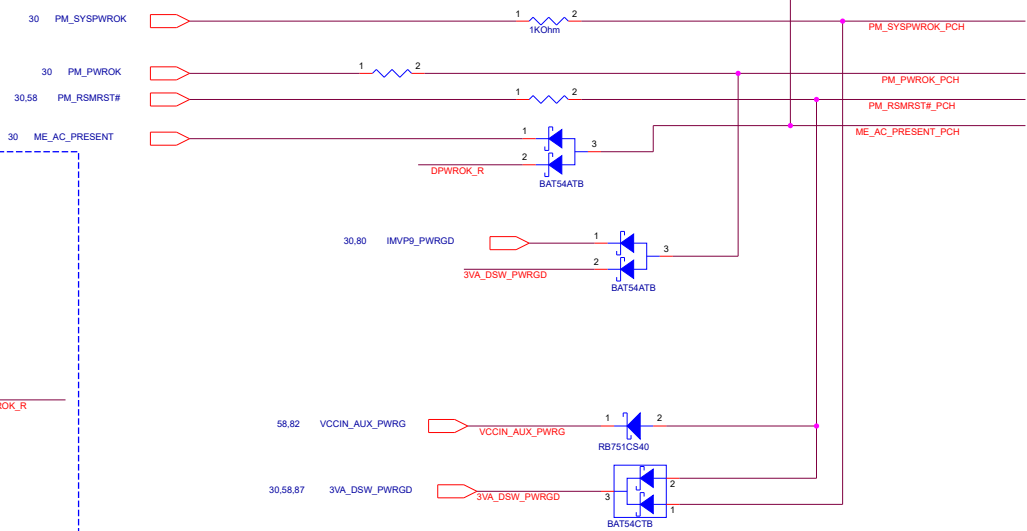
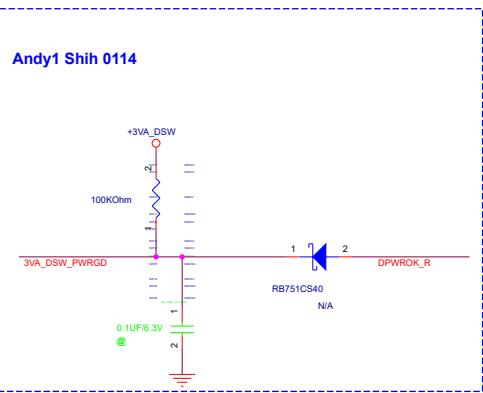
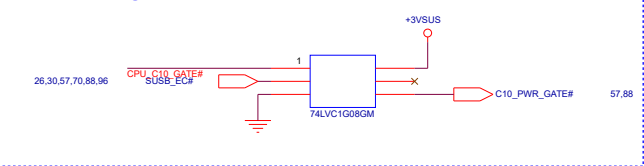


Main Board

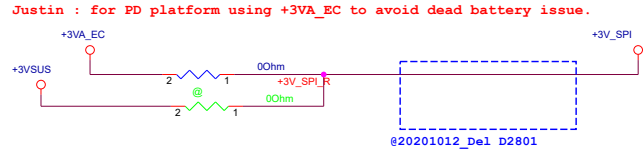


Justin : change to logic IC

C10_Gate Logic (AND)

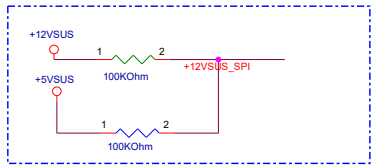


Power failure solution (S0-G3,S5-G3):



EC G3 flash sharing with Wire-OR Topology
Justin :Follow DG 6.12.3.2

tion aviod SPI leakage



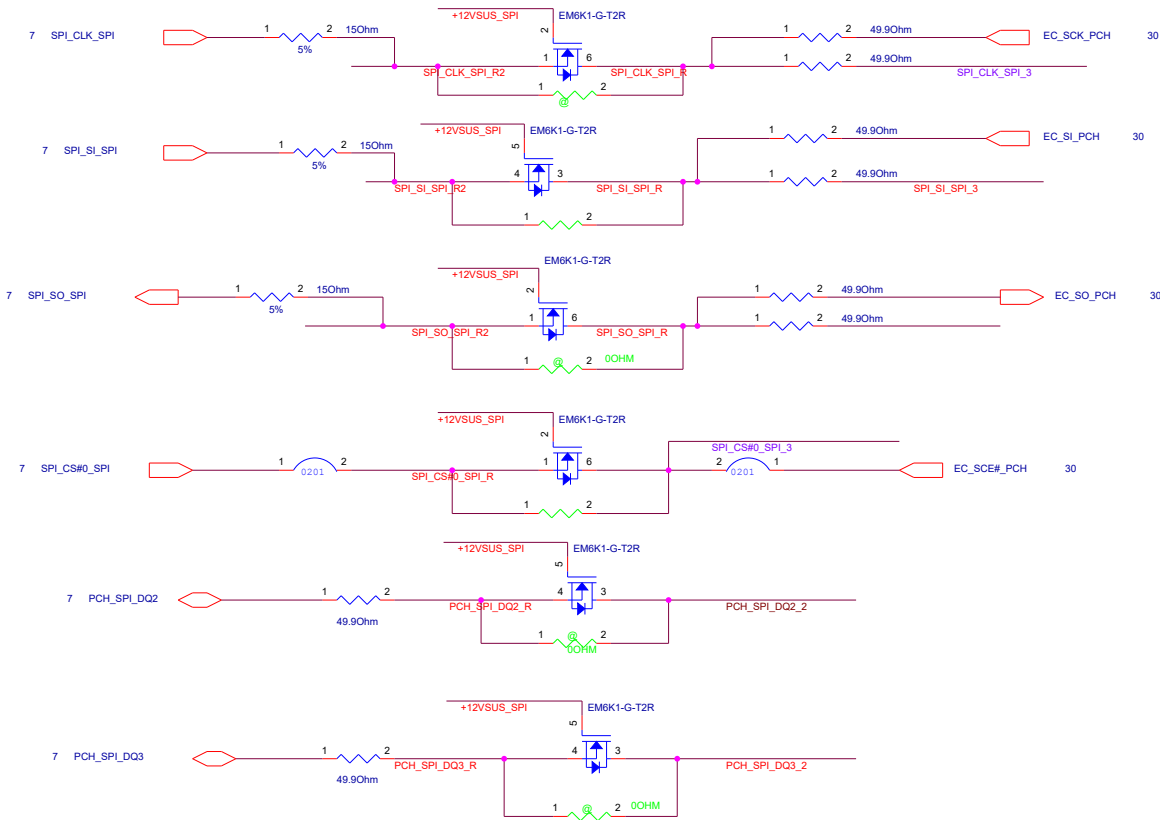
@20200611_新增R2810 Pull 5VSUS
並將R2815改不上件,解漏電

+3VA_EC

EC (SMB1)

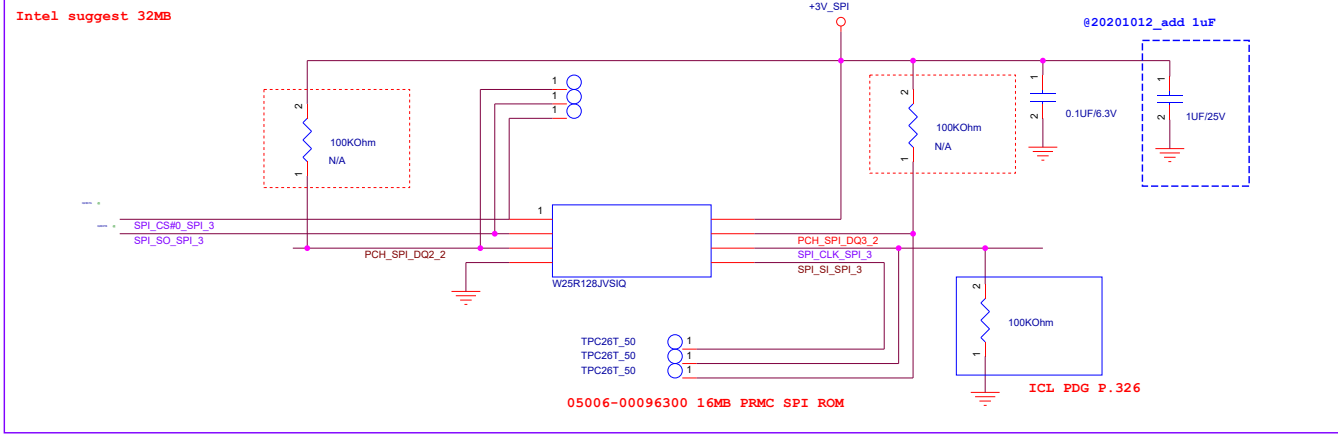
ADDR 0x7E

EC,SPI ROM Side

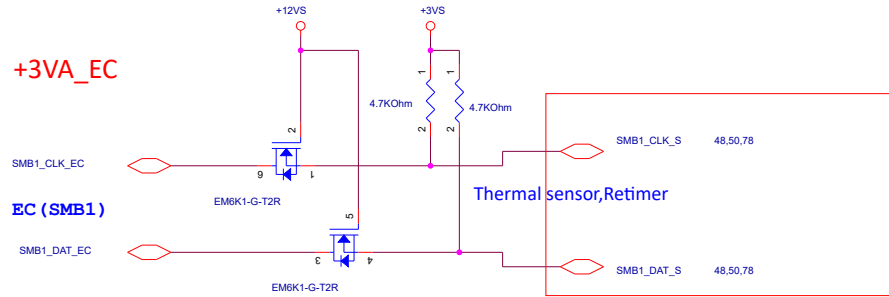


@20200709_modify 05006-00096300 16MB PRMC SPI ROM

Intel suggest 32MB

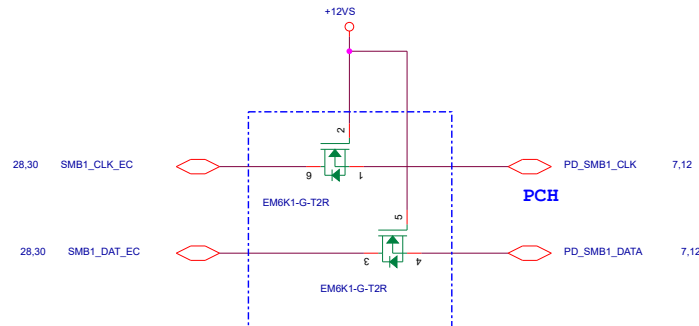


@20200602 Remove SMB_CLK to AMP NVVDD CLK Switck

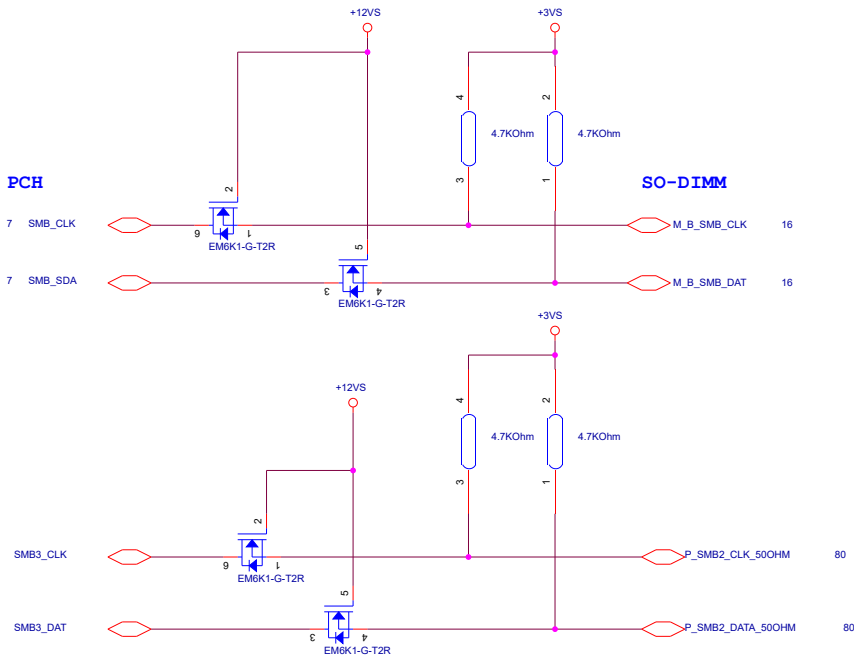


CPU Thermal sensor

VRAM Thermal sensor



@20200707_改不上件



EC 8585

Only 3V Tolerance

Can be adjusted to Open-Drain for port:

EC Require

GPB[0,1,2,3,4,5,6]

GPC[0,4,5,6,7]

GPC[0,4,6,7]

GPS[0]

GPS[6,7]

GPS[7]

GPI[0,7]

GPI[0,7]

GPI[0,7]

GPA0-GPA3

GPB0-GPB7

GPC0-GPC7

GPS0-GPS7

GPD0-GPD7

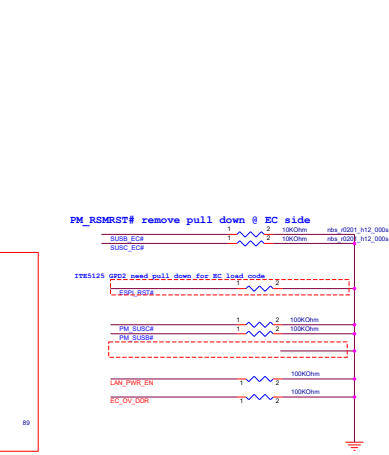
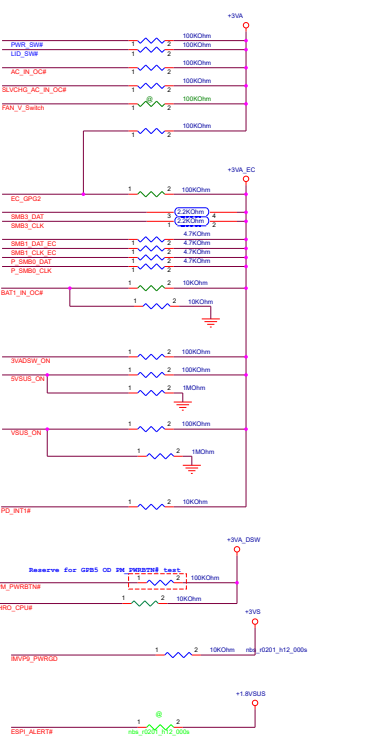
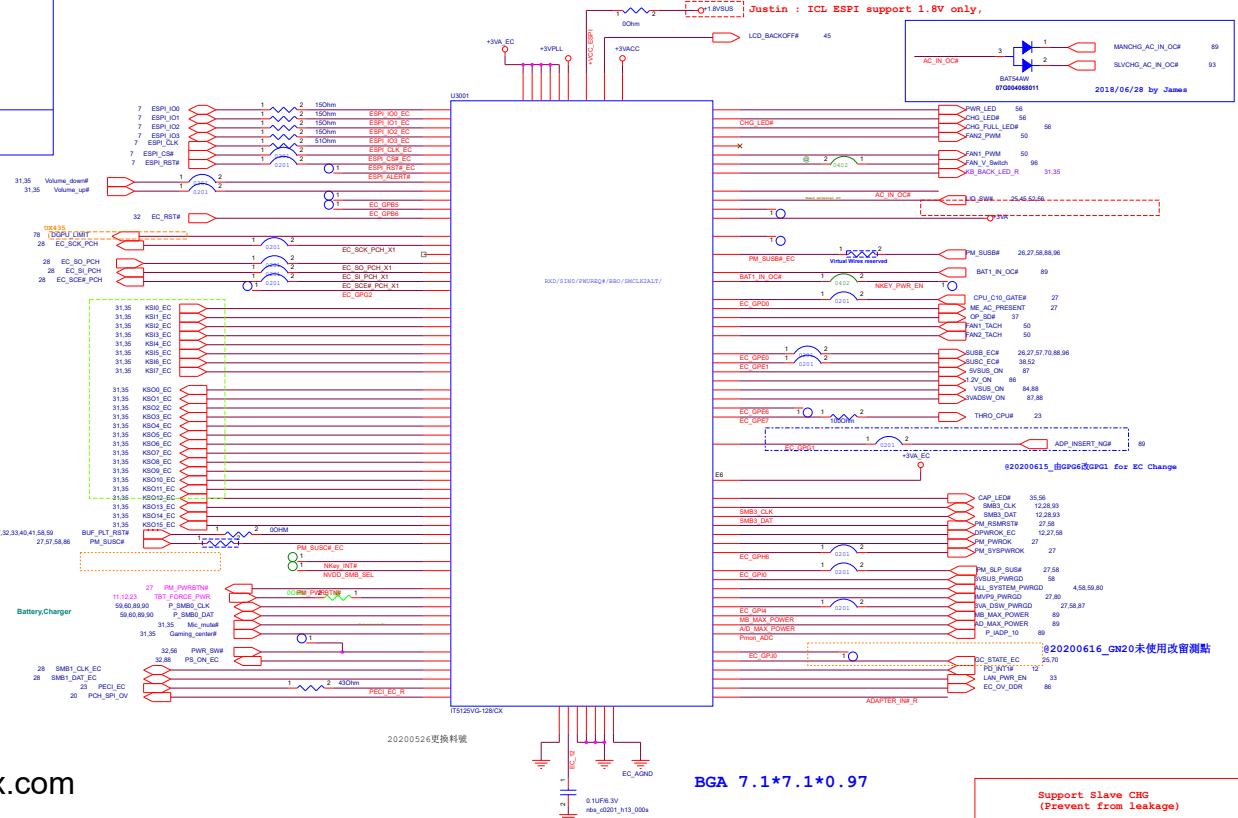
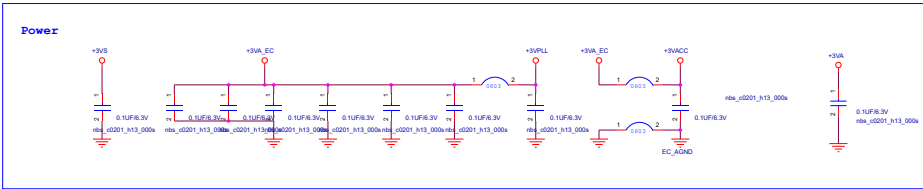
GPE0-GPE7

GPF0-GPF7

GPG0-GPG7

GPH0-GPH7

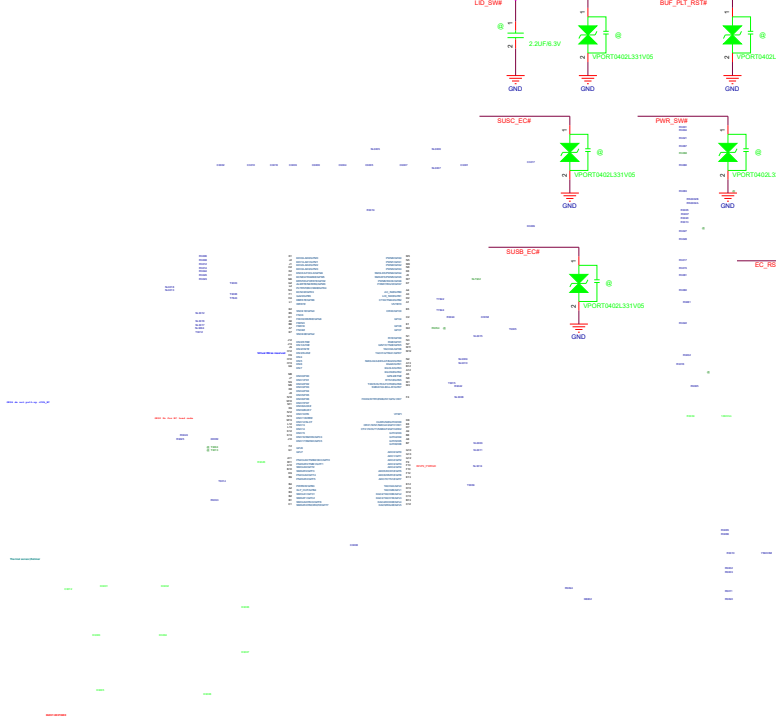
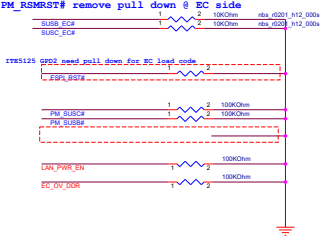
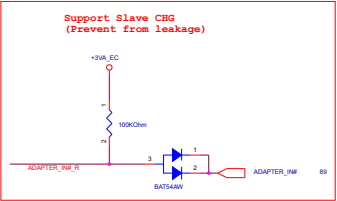
GPI0-GPI7

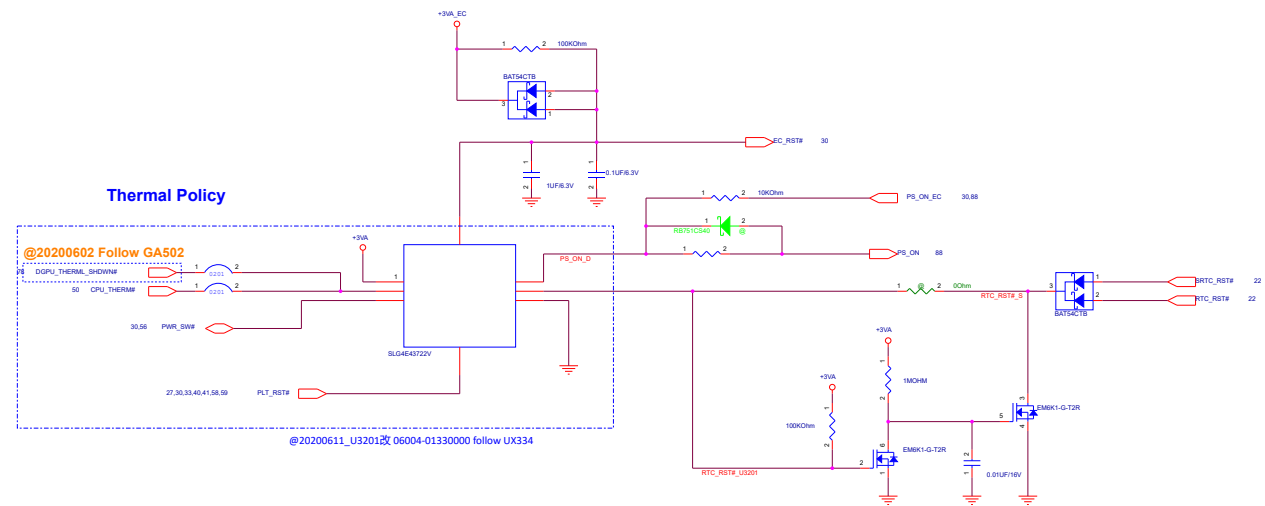


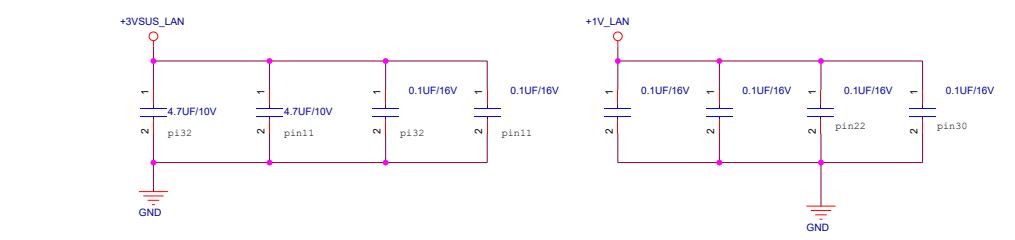
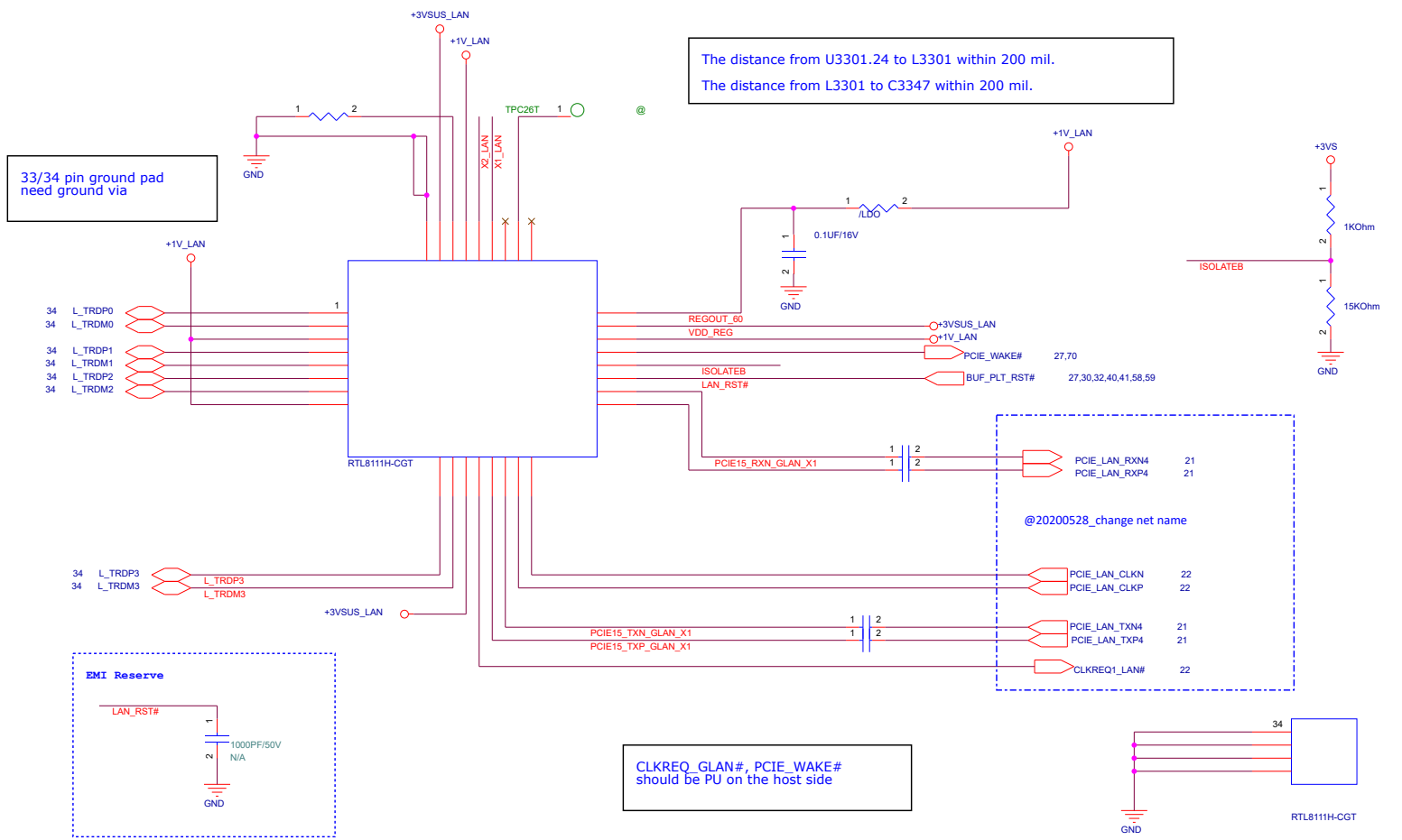
Vinafix.com

BGA 7.1*7.1*0.97

IT5125VG-192/CX (192KB) (06037-00370200)

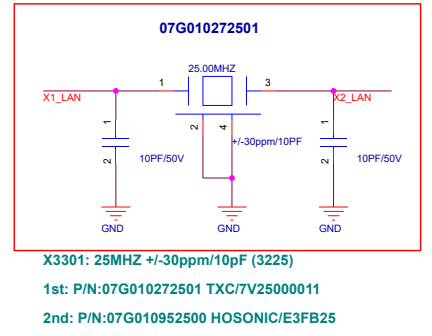




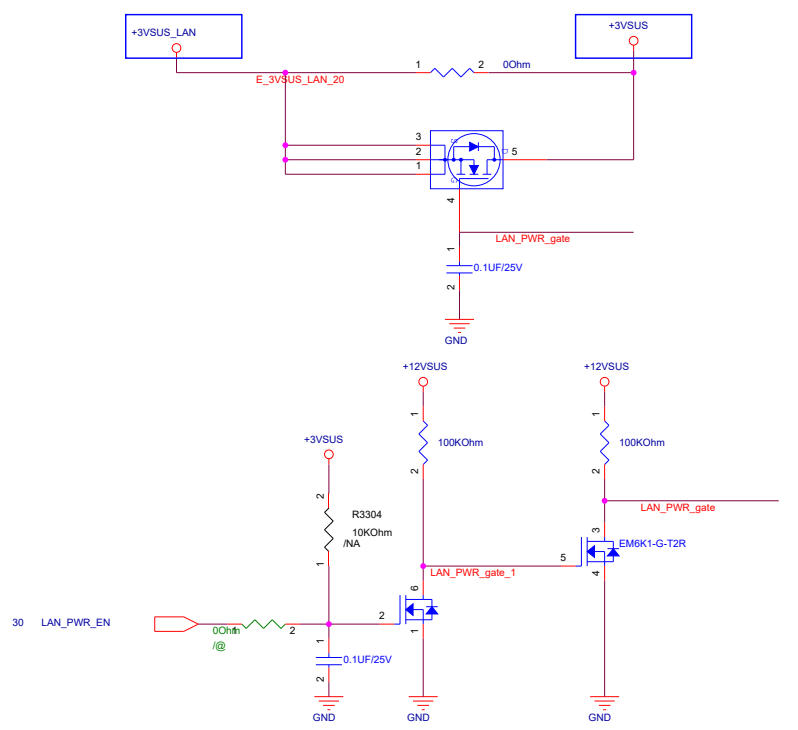


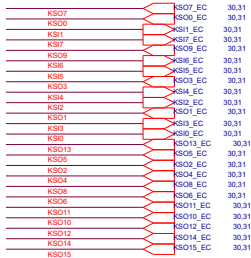
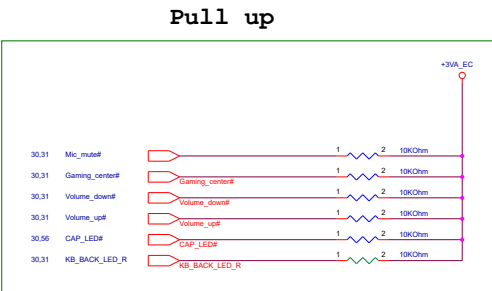
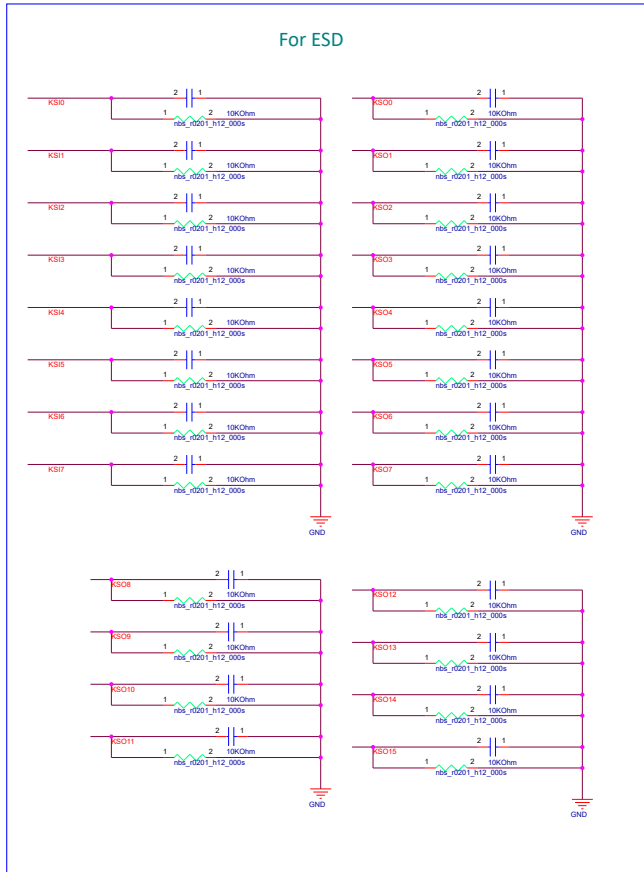
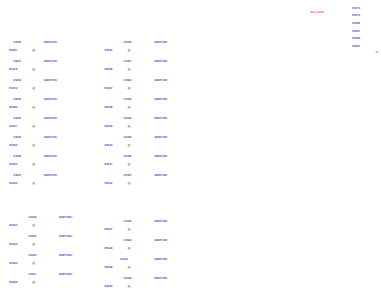
Main Board

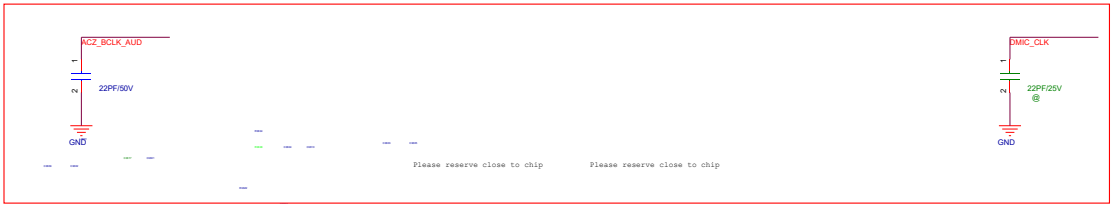
@ 20200615 換回較常用XTAL 但體積較大 for GA502 GX502



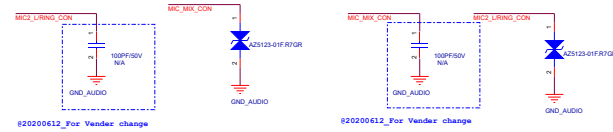
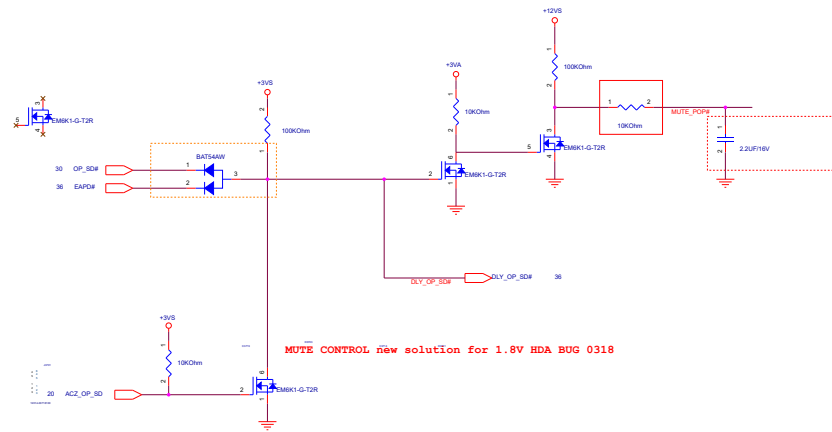
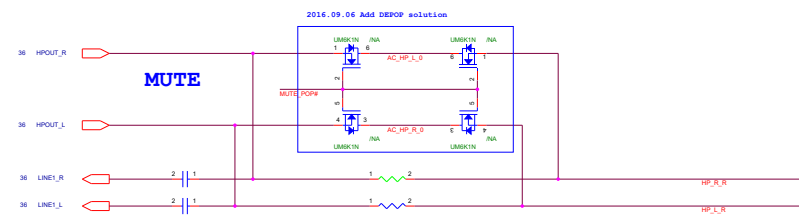
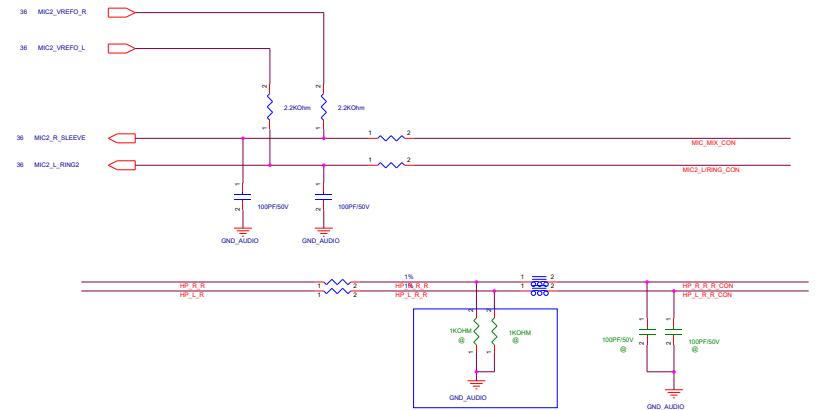
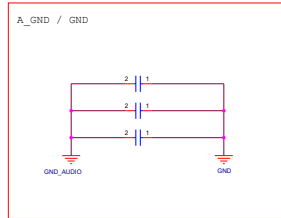
Realtek suggests 3V_LAN raise time 1ms







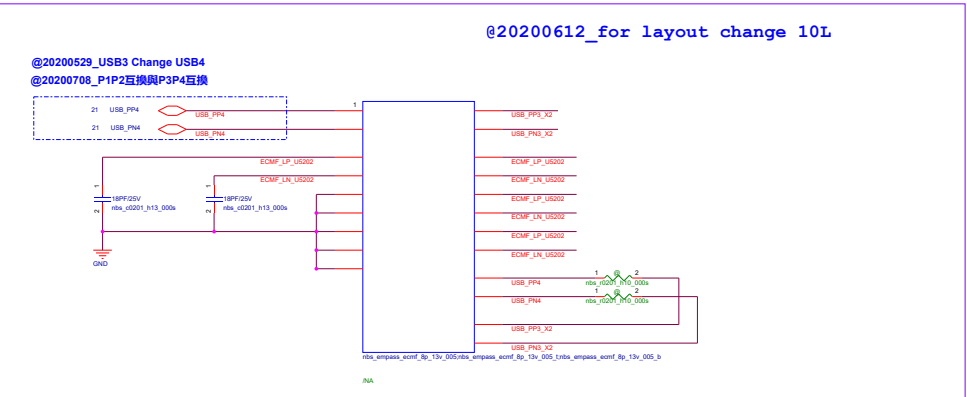
Main Board



USB3.1_Port3



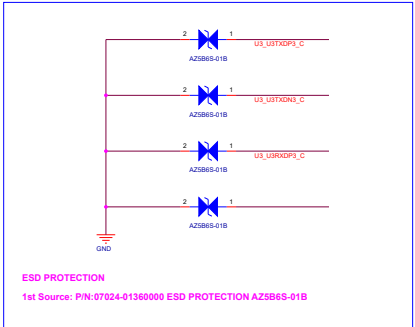
USB2.0 EMI-Protection With ECMF(PCB 1.05mm_10Layer)



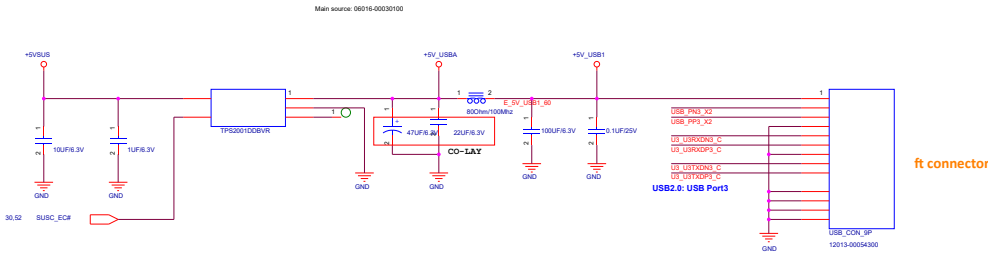
Note : Please check your project must matching the thickness , DF and DK value of PCB every layer

3. Pin7 Pin8 Pin11 Pin12 must be connected to system ground

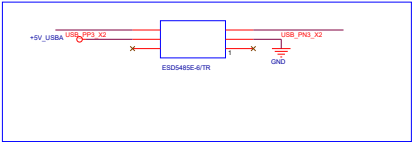
USB3.0 ESD-Protection

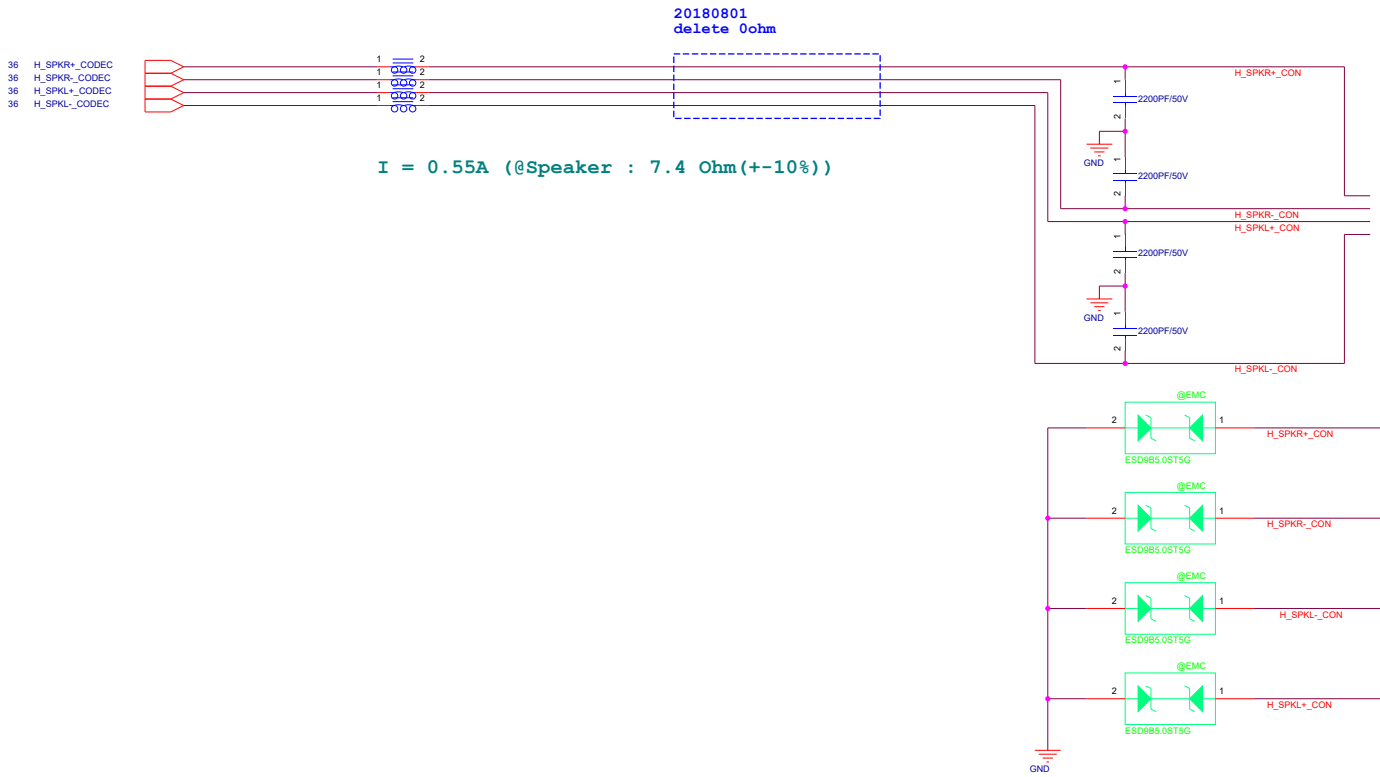


Vinafix.com

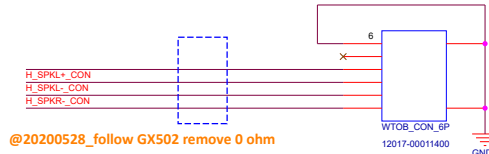


USB2.0 ESD-Protection

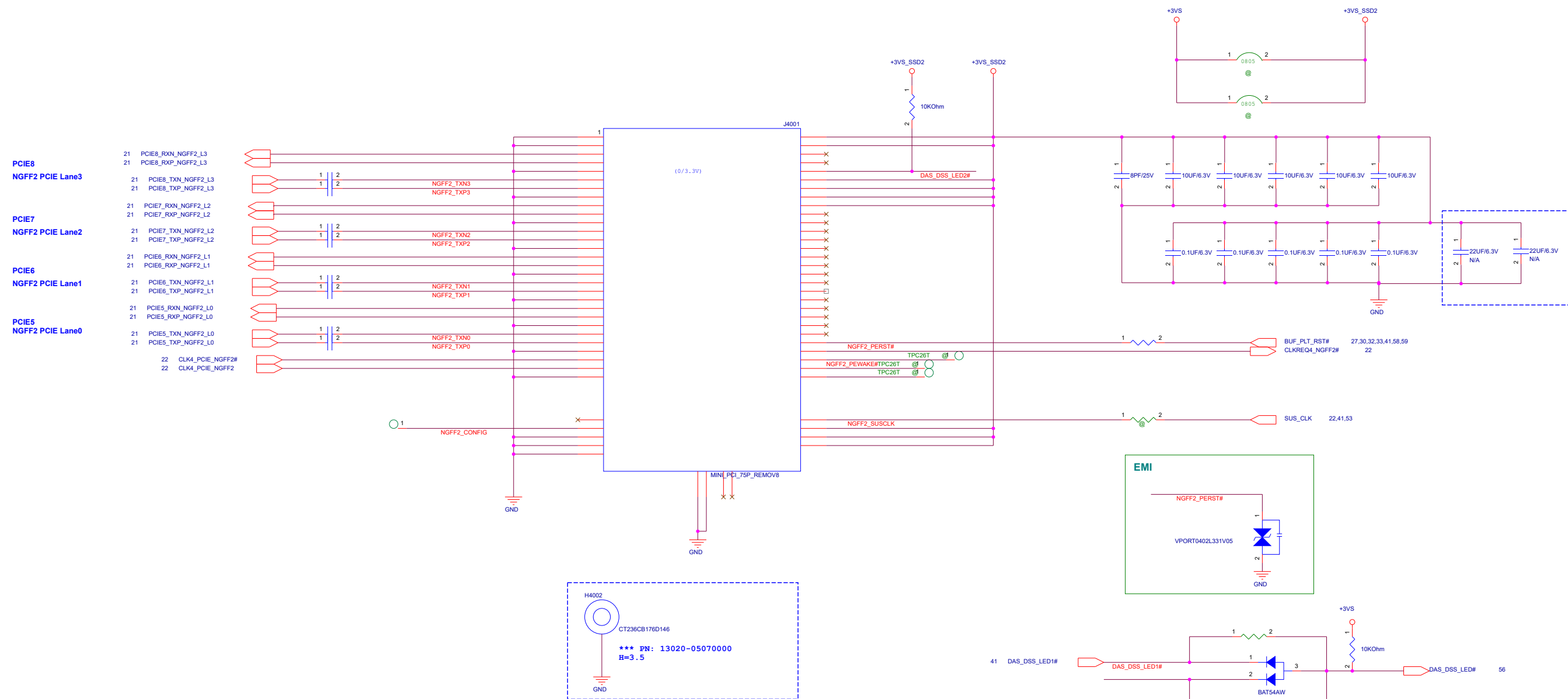




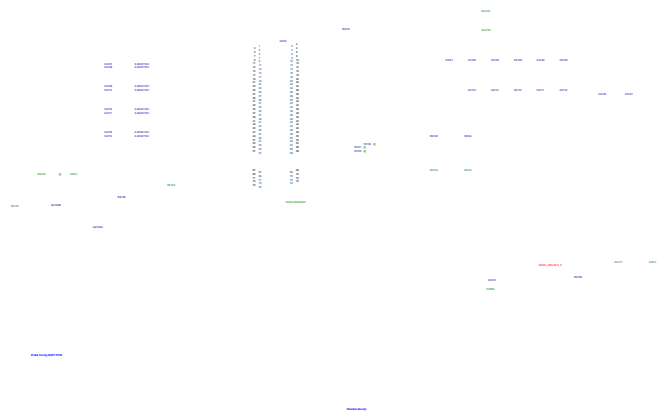
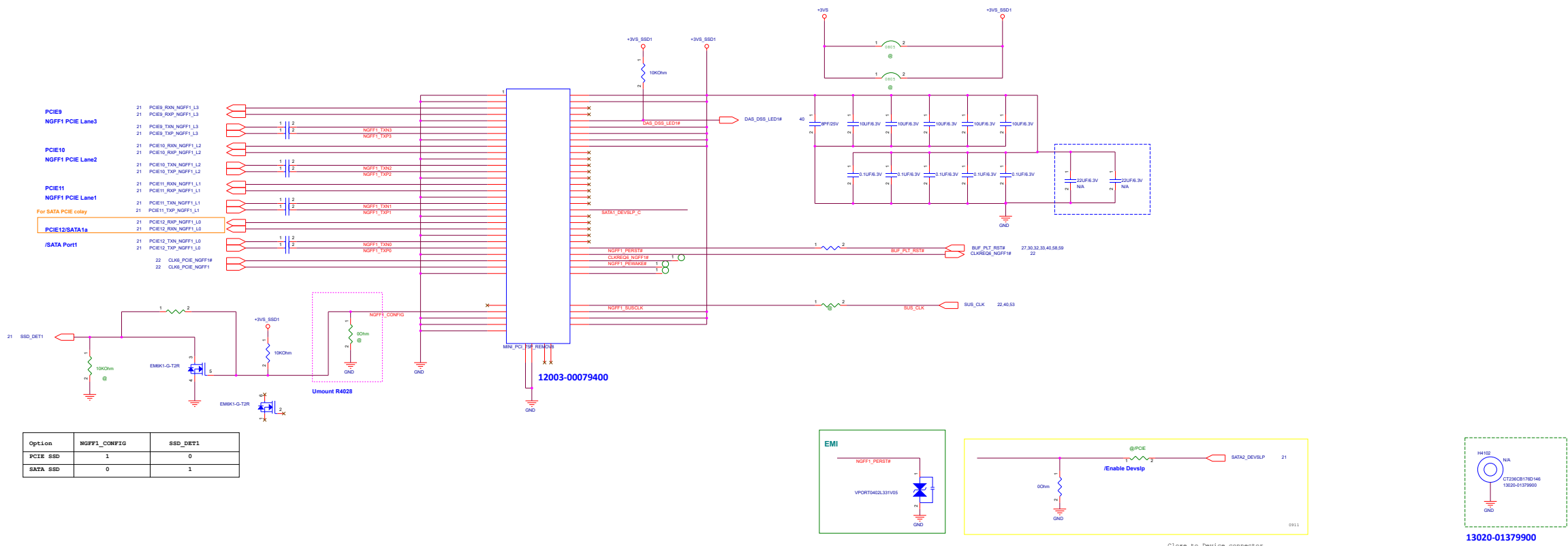
INTERNAL SPK1 Conn.
SPK L+ L- R+ R- trace width
Speaker 4 ohm
Max = 2W / Channel

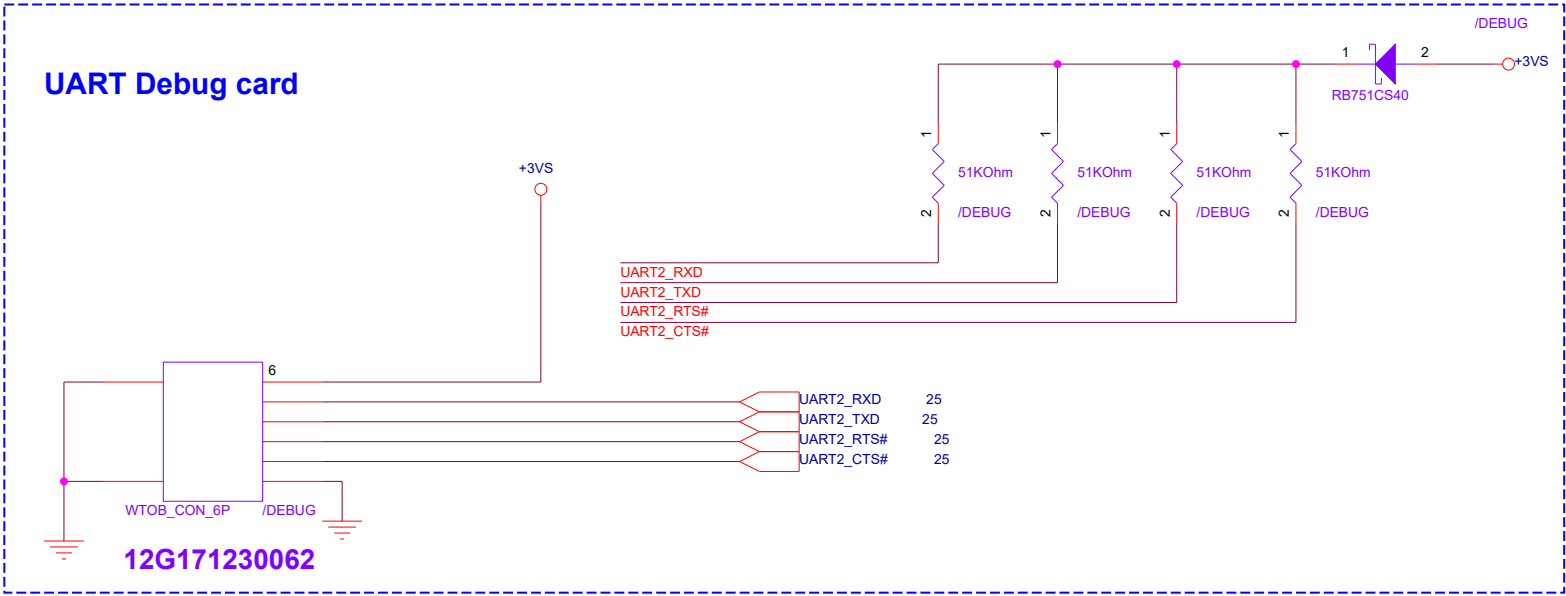


2 nd NGFF PCIE x4 (PCIE only)

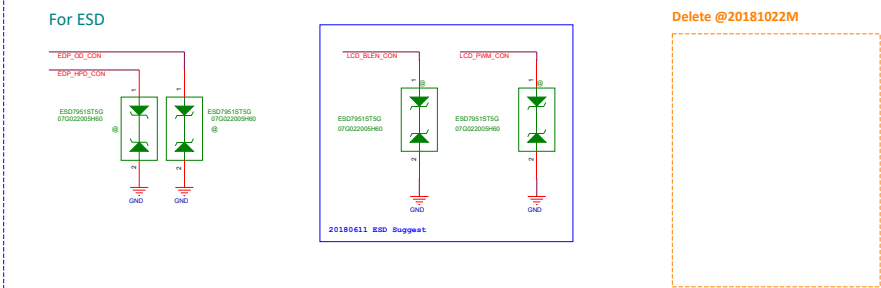
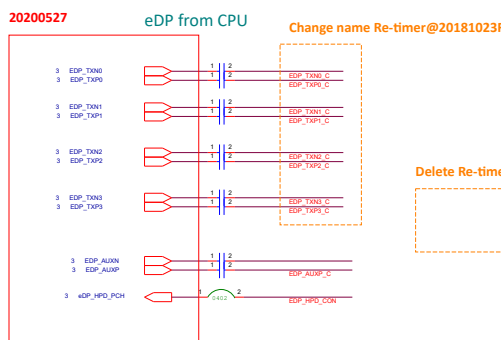
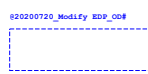
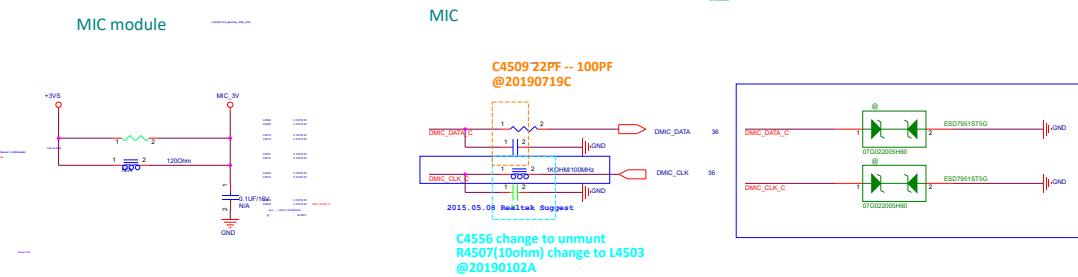
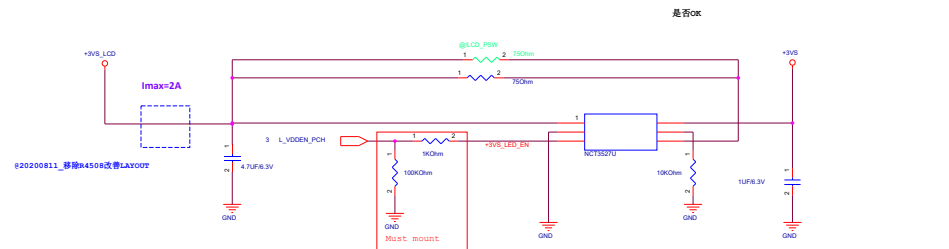


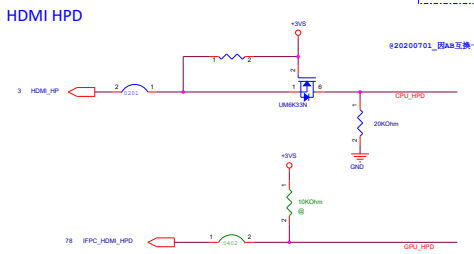
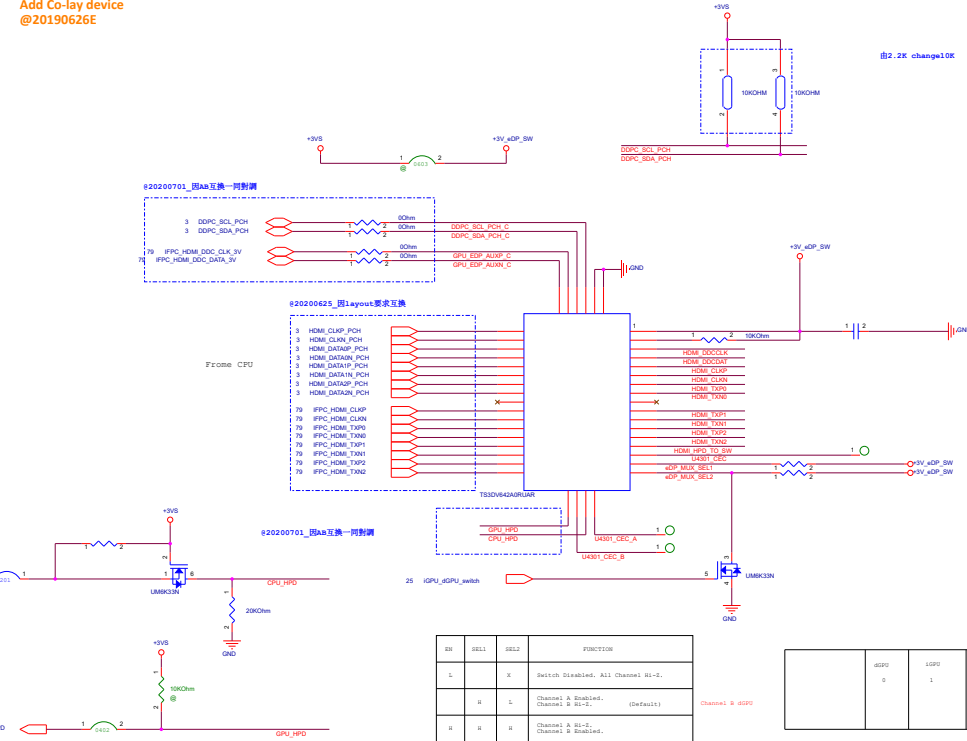
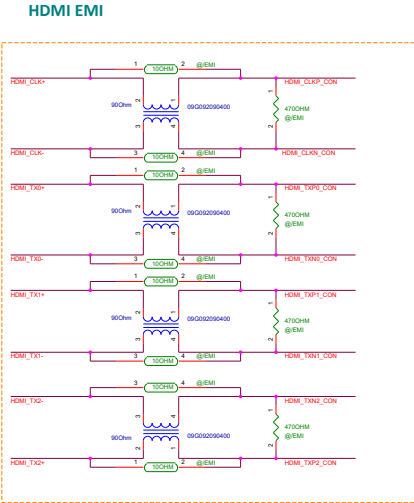
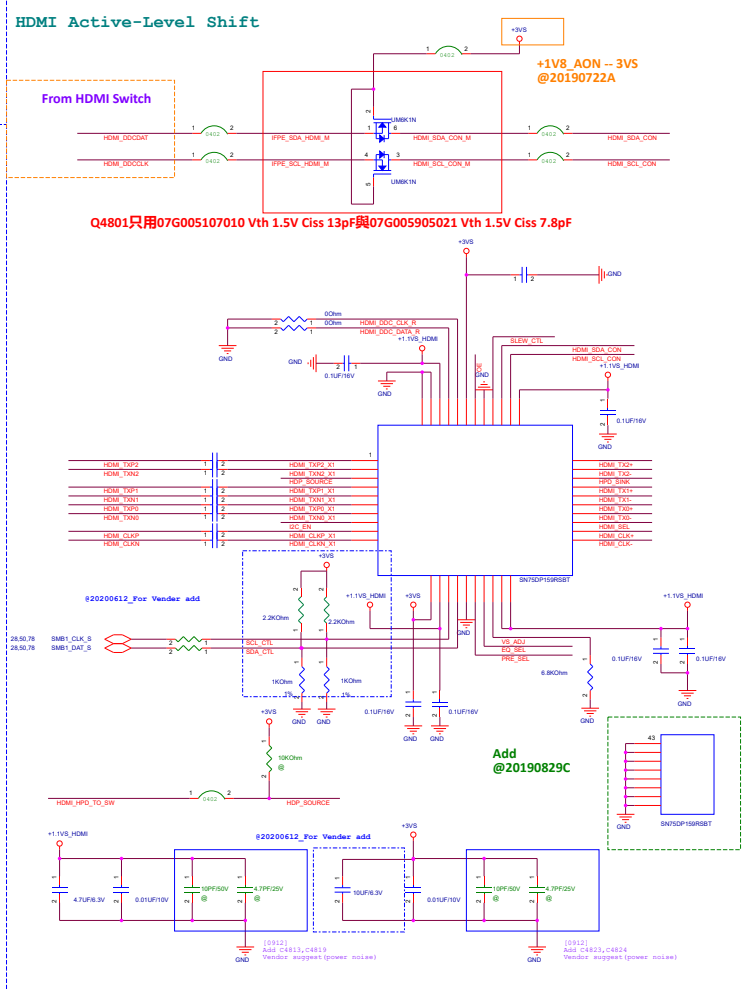
@20200702_layout空間關係調高更換J4001 H4002





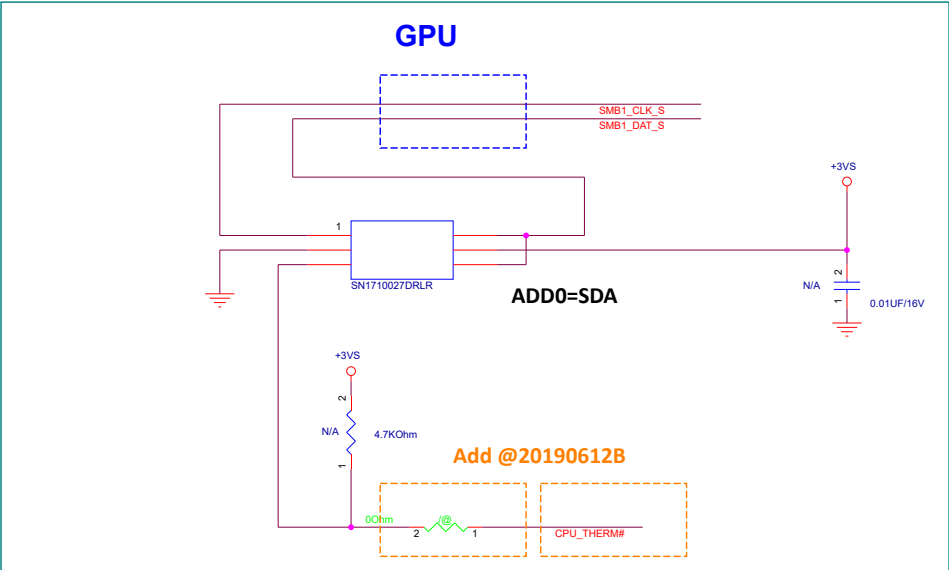
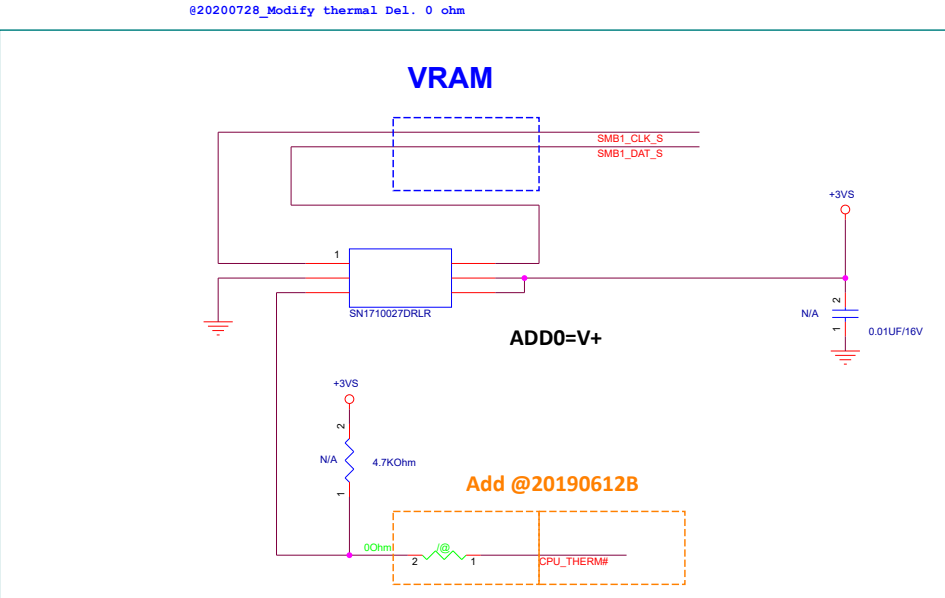
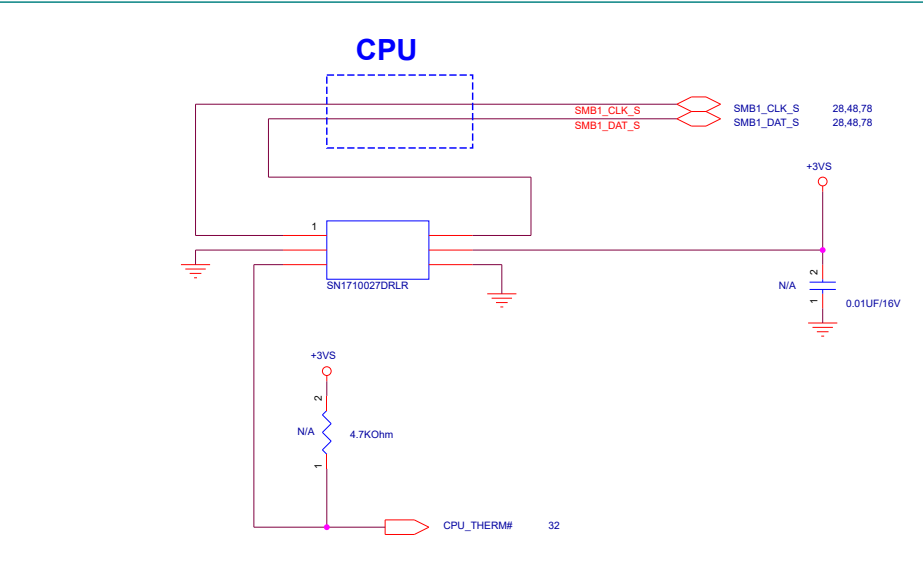
Jigboard4 debug guide
DIP SW to 0000 : BIOS Flash
DIP SW to 0010 : Keyboard CONN Port80
DIP SW to 1000 : SMBUS CONN Port80 BIOS DUMP (by Postcode monitor)





Thermal Sensor : SN170027

Pin function Supply voltage.: 1.62 V to 3.6 V

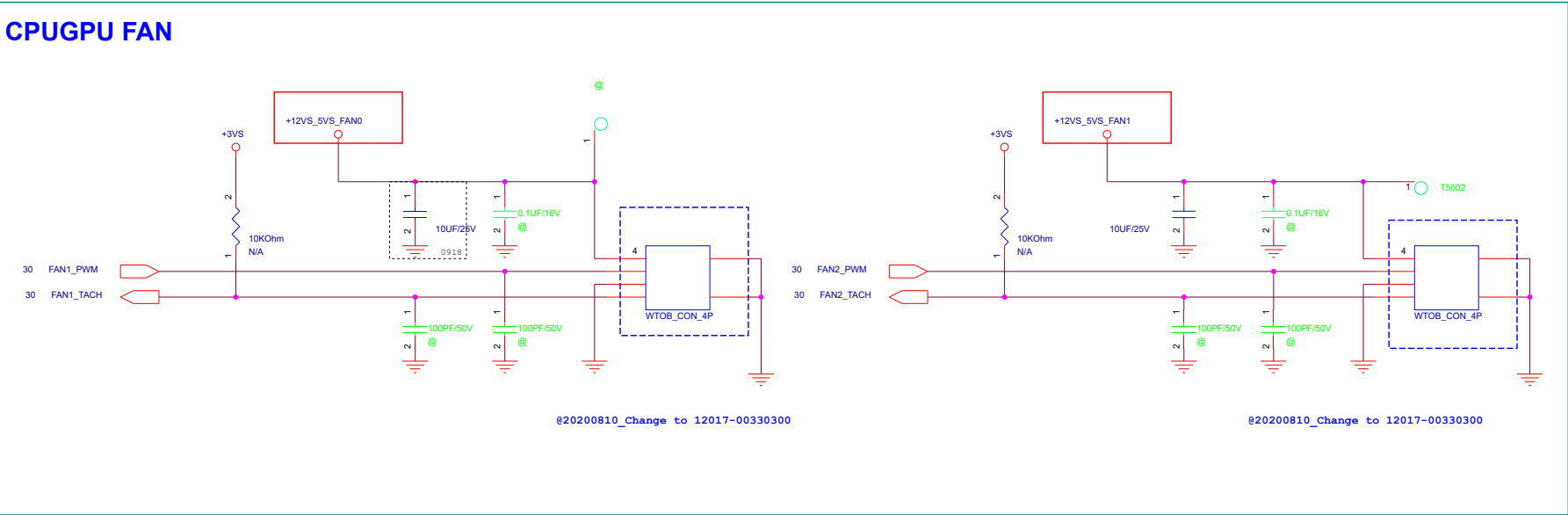


SMBUS addr=10010000 (90)

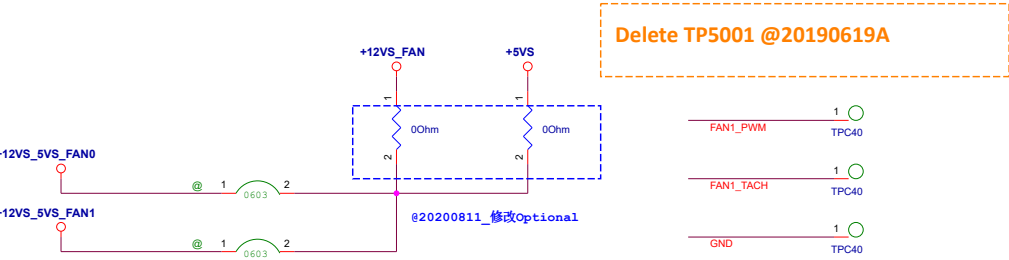
Near VRAM

Near GPU

SMBUS addr=10010010 (92)



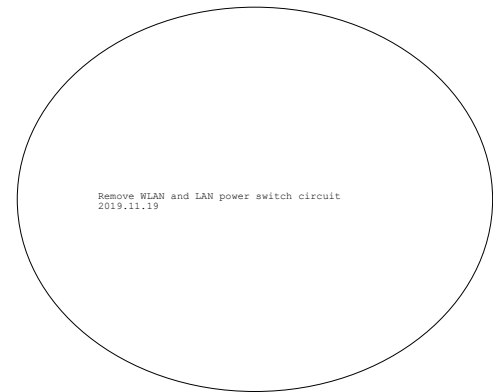
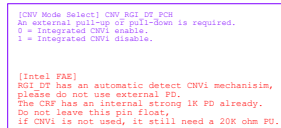
DEVICE TWO-WIRE ADDRESS	ADD0 PIN CONNECTION	Output
1001000	90	Ground
1001001	91	V+
1001010	92	SDA
1001011	93	SCL



Delete TP5001 @20190619A

- FAN1_PWM TPC40
- FAN1_TACH TPC40
- GND TPC40

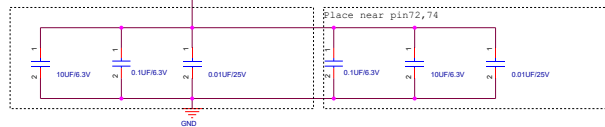
11

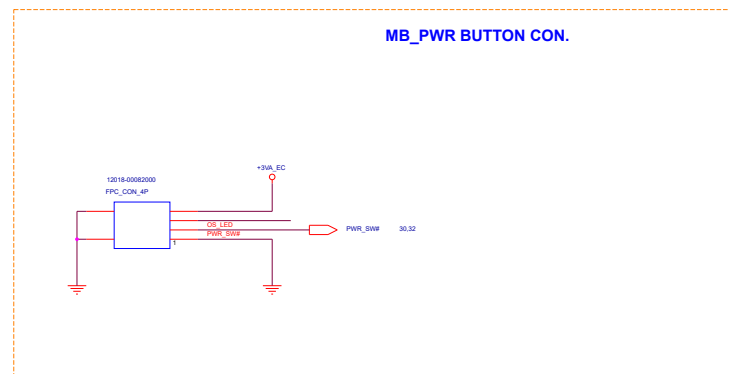
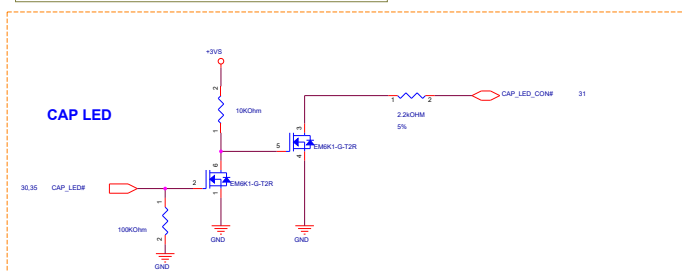
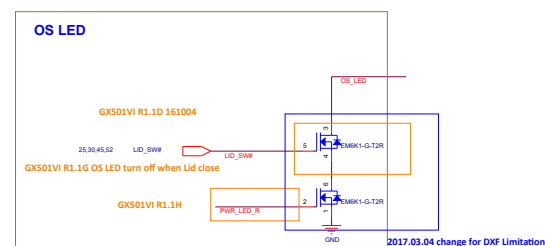
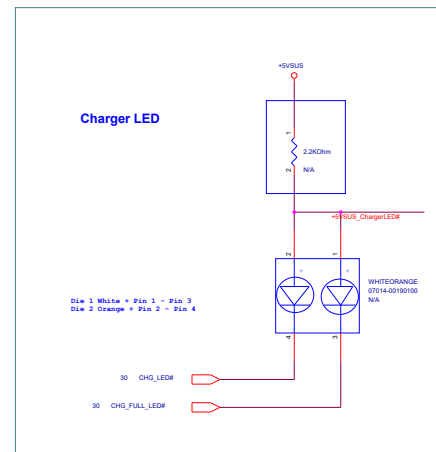
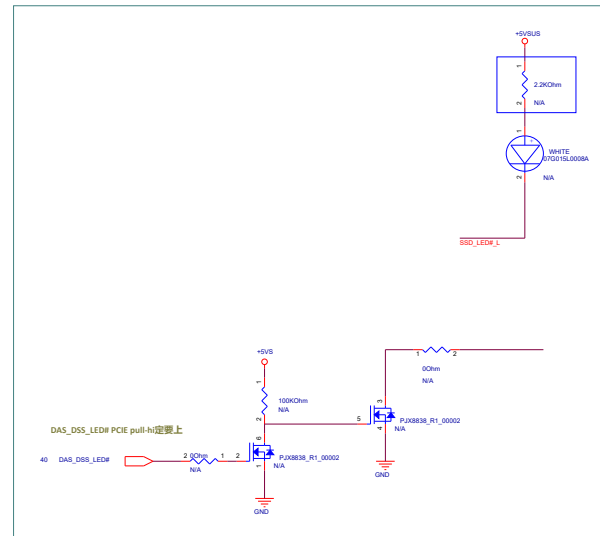
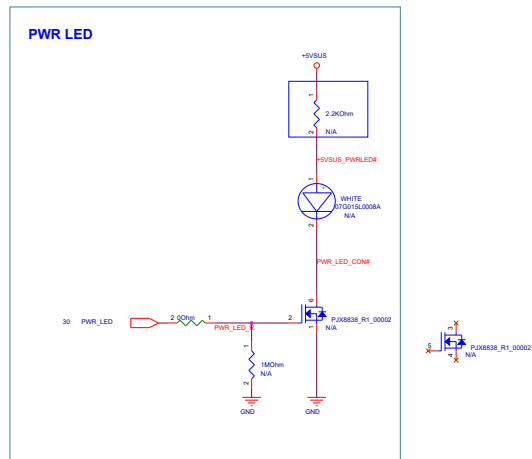


The first step in the process of developing a business plan is to conduct a thorough market research. This involves identifying the target market, understanding the needs and preferences of the customers, and analyzing the competitive landscape. Once the market research is complete, the next step is to develop a clear and concise business plan. This plan should outline the company's mission, vision, and goals, as well as the strategies and tactics for achieving them. The business plan should also include a detailed financial forecast, including projected revenue, expenses, and profit.

After the business plan is developed, the next step is to secure the necessary funding. This can be done through a variety of sources, including banks, venture capitalists, and angel investors. Once the funding is secured, the next step is to launch the business. This involves setting up the company's legal and administrative structure, hiring staff, and establishing a marketing and sales strategy.

Finally, the business should be monitored and evaluated regularly to ensure that it is on track to achieve its goals. This involves tracking key performance indicators (KPIs) and making adjustments as needed.

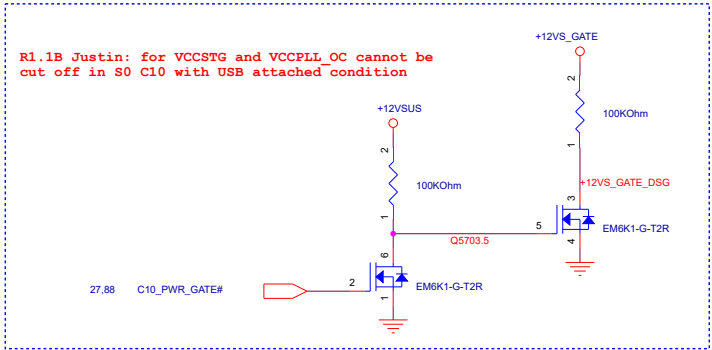
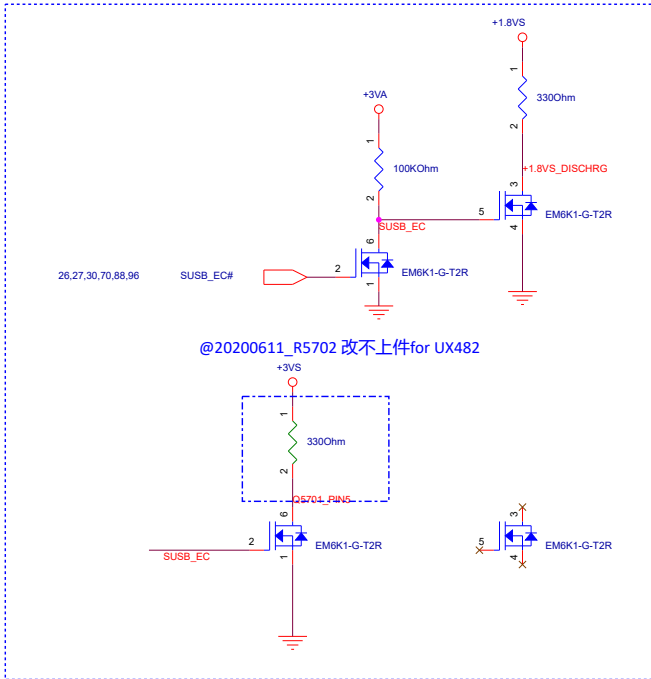
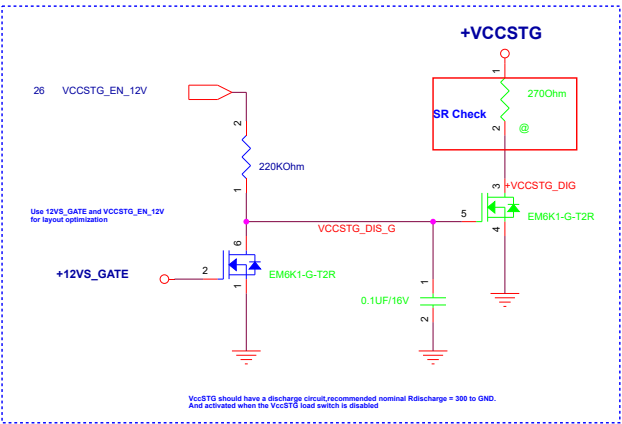
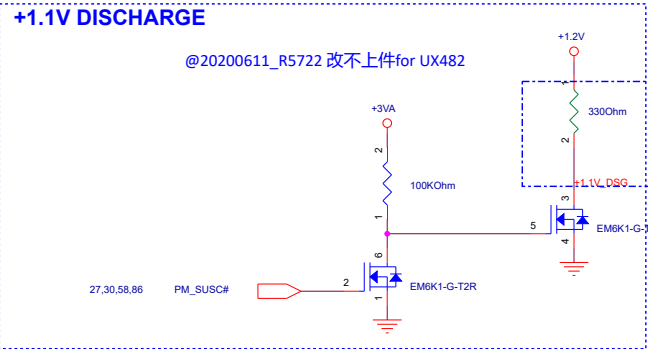




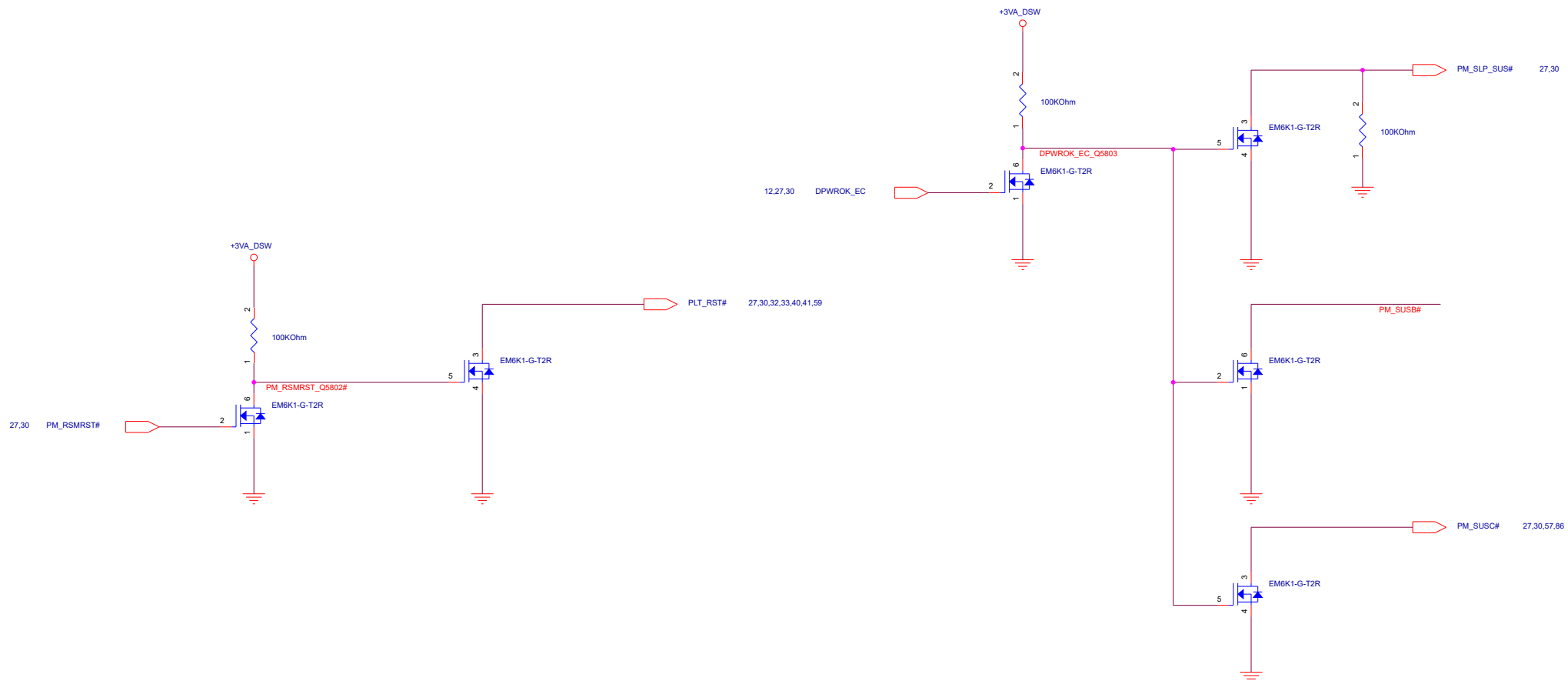
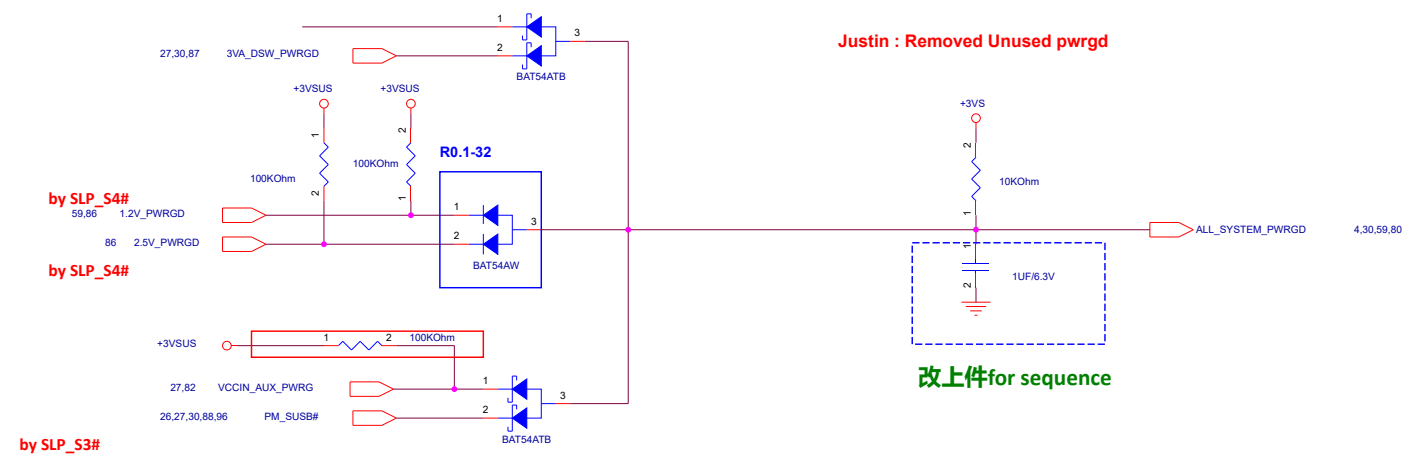
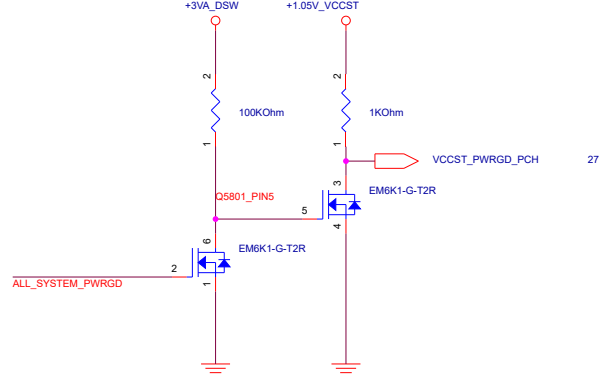
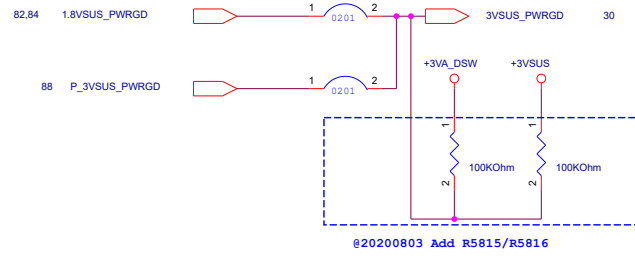
@20190731C

FP No	GA502 FP Pwrbtn	GA502 小板	GA502 小板 pin No
10	LED+	LED+	4
9	LED-	LED-	3
8	PWRBTN	PWRBTN	2
7	GND	GND	1
6	USB_D-	-	-
5	USB_D+	-	-
4	GND	-	-
3	SSO	-	-
2	ATC	-	-
1	RESETn	-	-

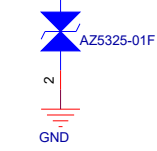
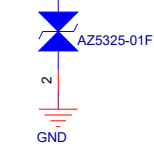
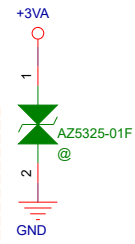
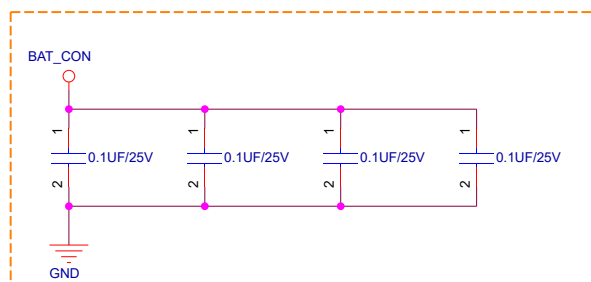
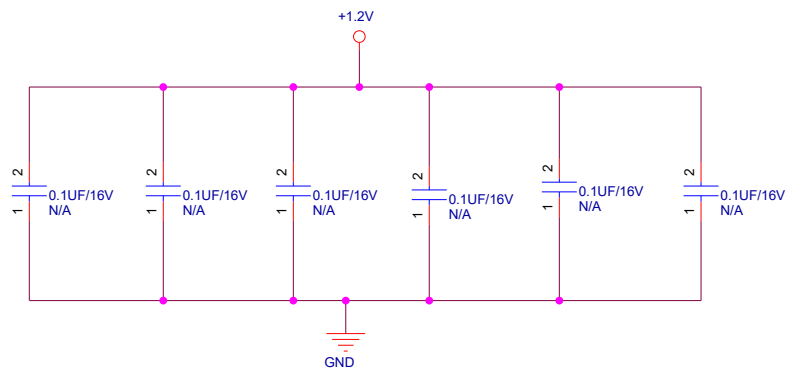
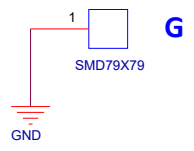
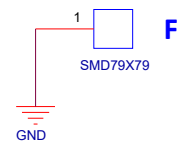
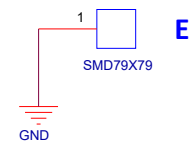
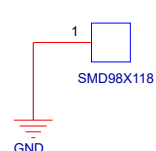
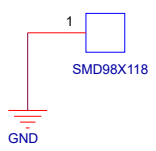
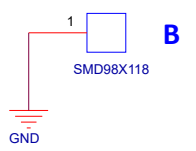
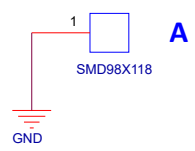
Justin : Removed no used Discharge circuit
1.8V ,VCCIO,+5VS load switch already build in 180-260 ohm discharge function



Main Board



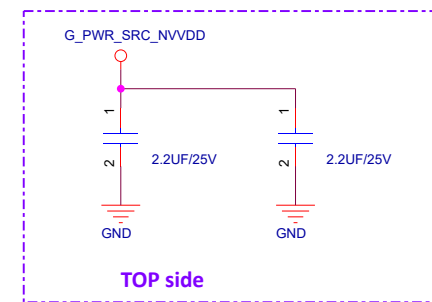
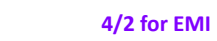
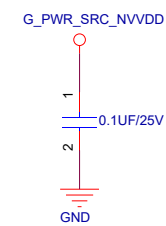
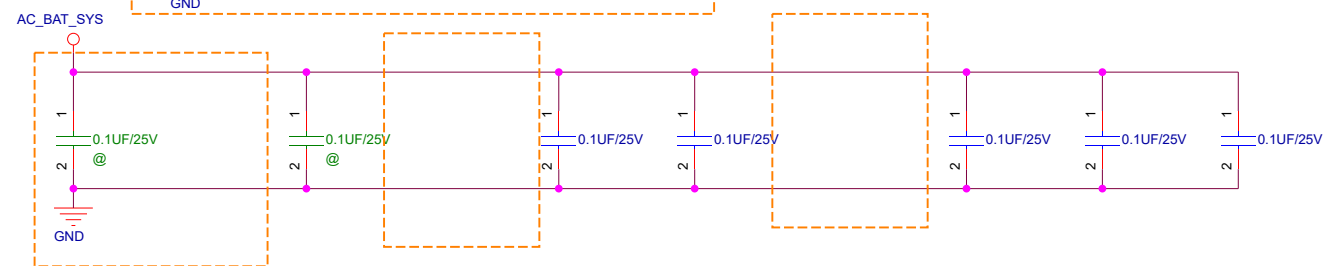
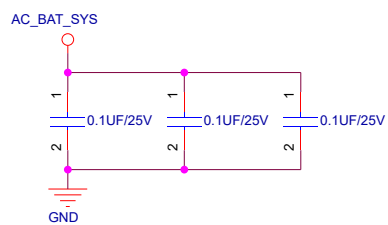
SMT EMI GASKET 2*1.5*2 13040-00850100



P_SMB0_CLK	30,60,89,90
P_SMB0_DAT	30,60,89,90

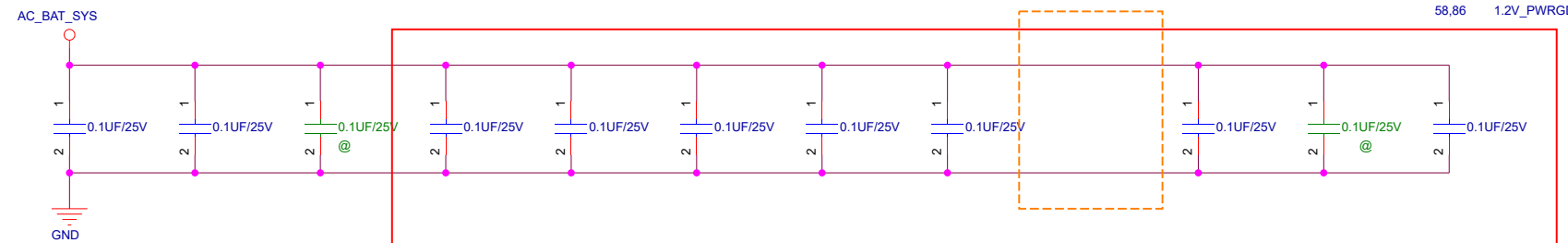
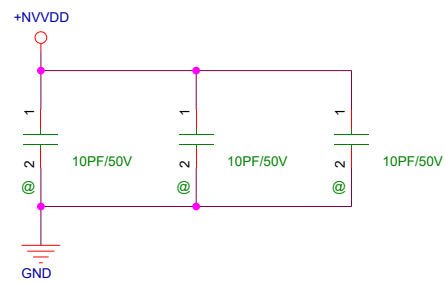
U6904, U6908(改裸銅), U6905(改裸銅) 移除
@20181122C

2017/04/05 EMI

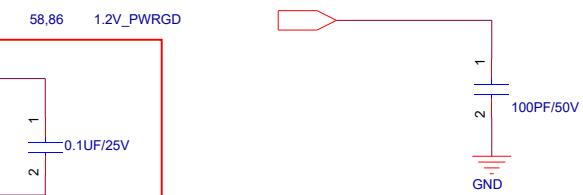


TOP side

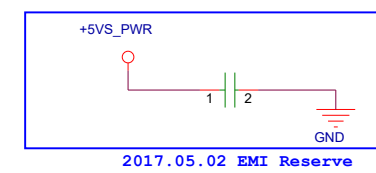
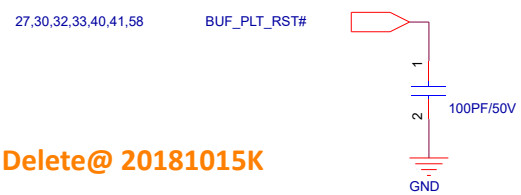
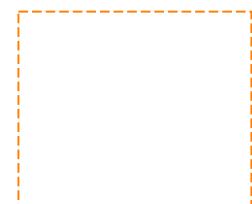
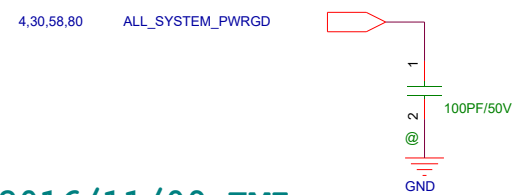
2016/07/27 EMI



GX501VI 1.1H



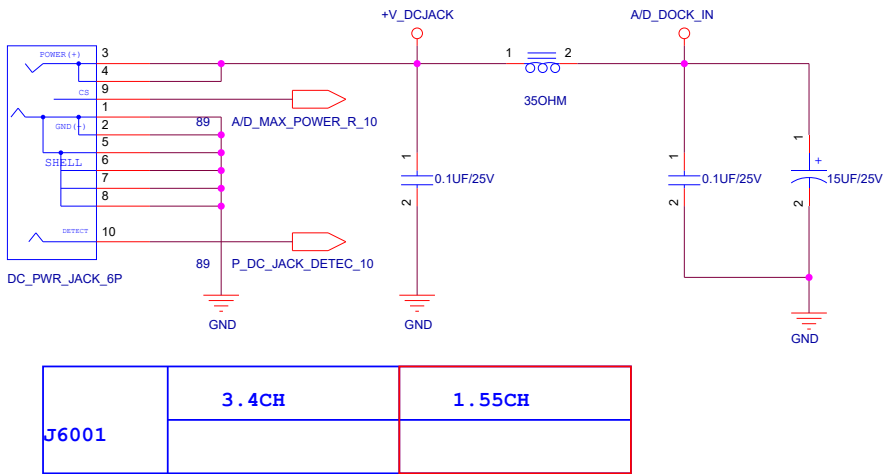
2016/11/09 EMI



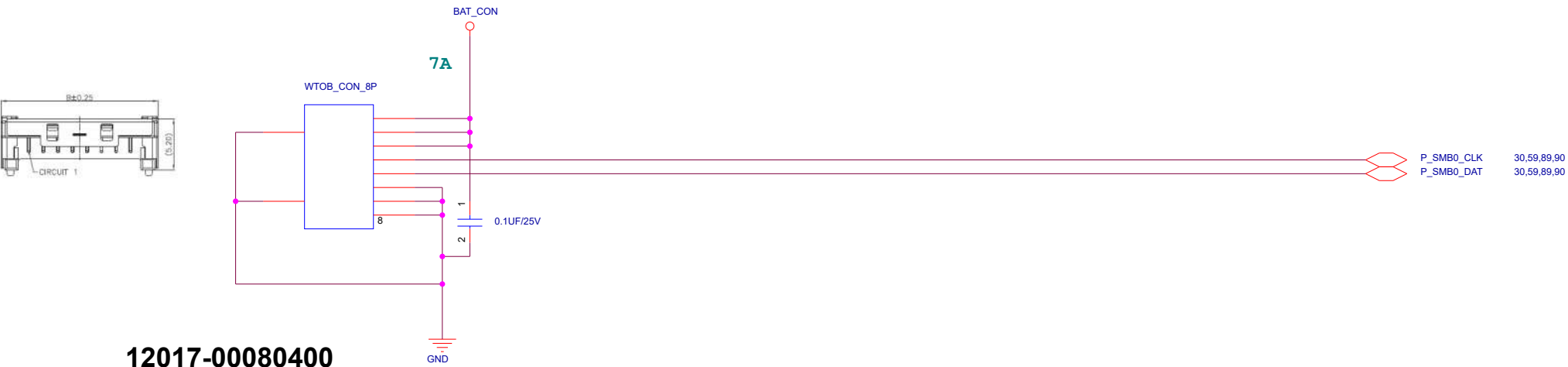
2017.05.02 EMI Reserve

DC-IN Connector

使用請詢用River_Hsu

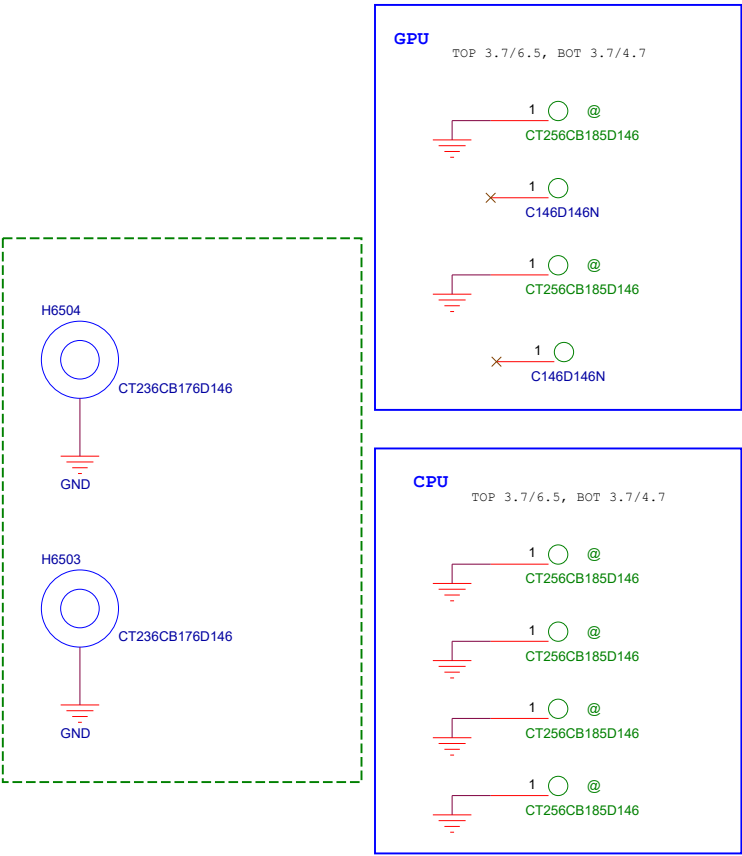
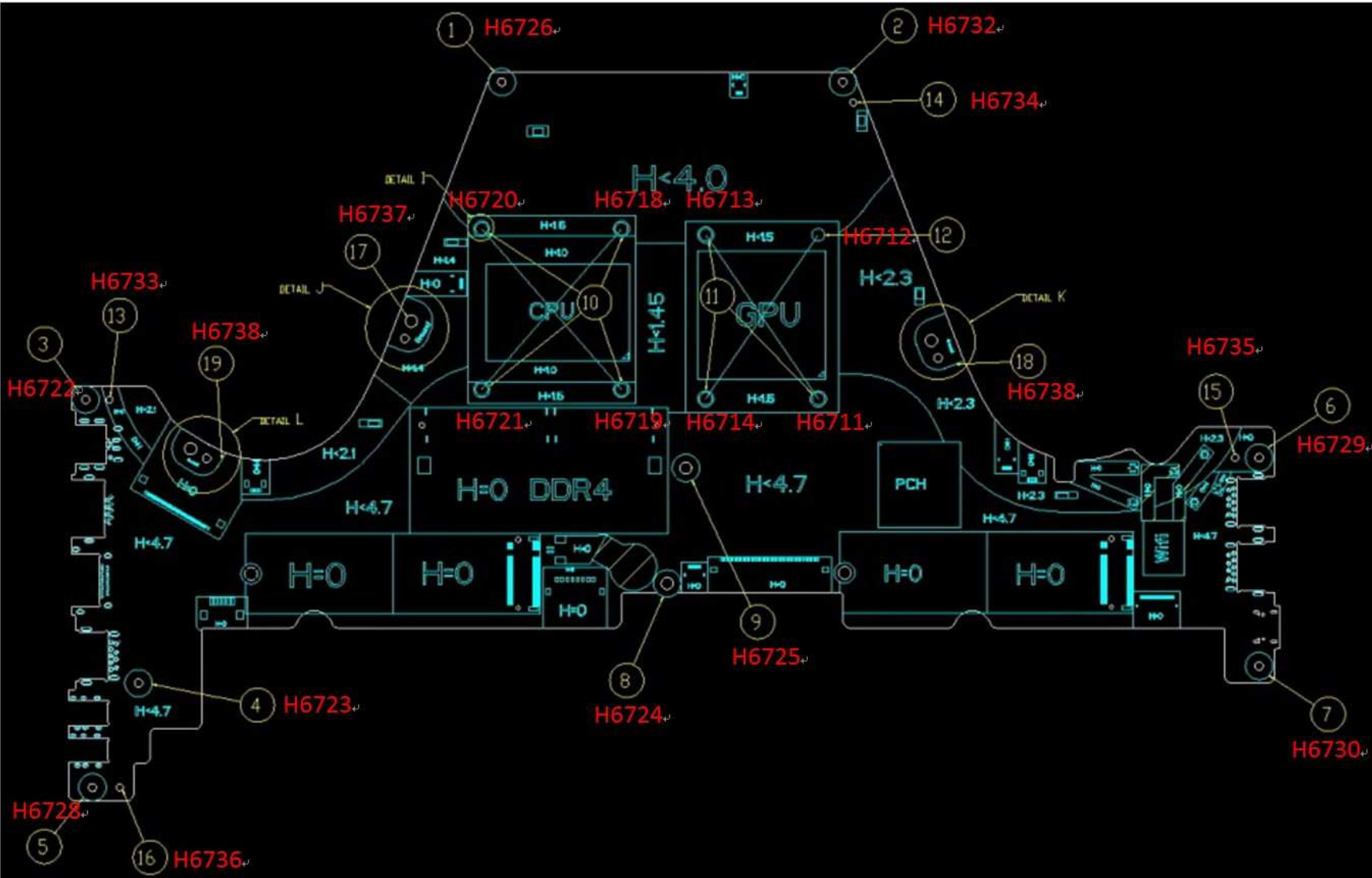


Battery Connector

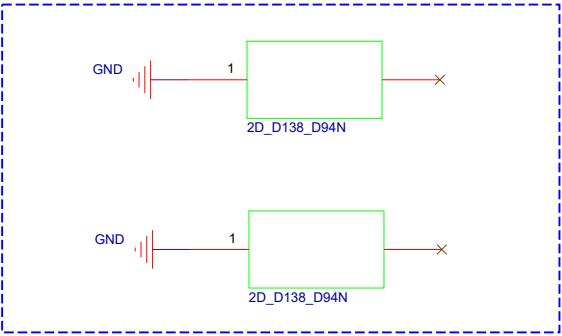


12017-00080400

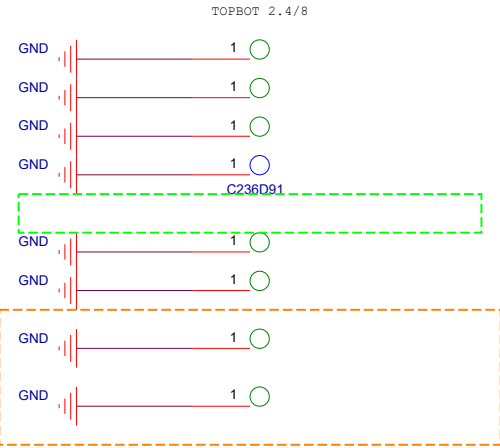
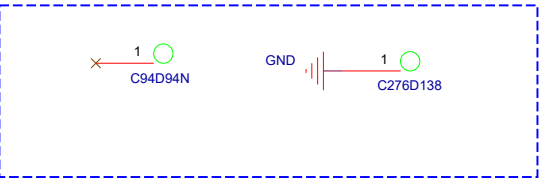
正確性與BAT1_IN_OC#是否預留！



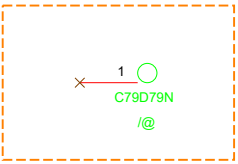
@20200707_Modify H6533H6535



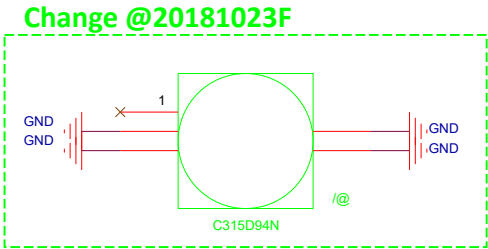
change H6501 H6502



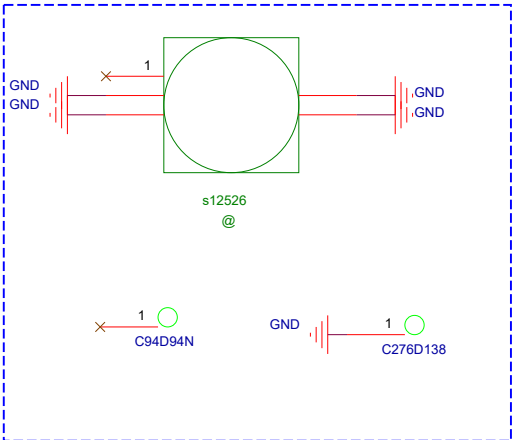
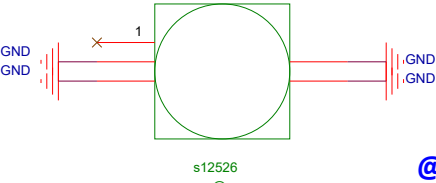
Add @20181029C



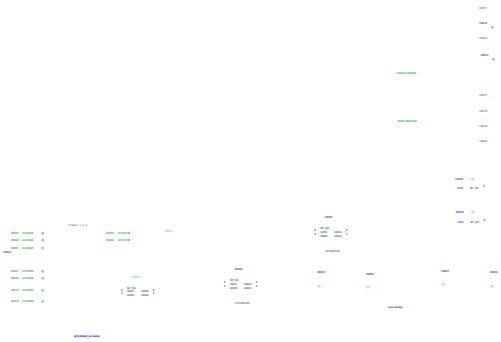
Change @20181023F
NC @20181030B



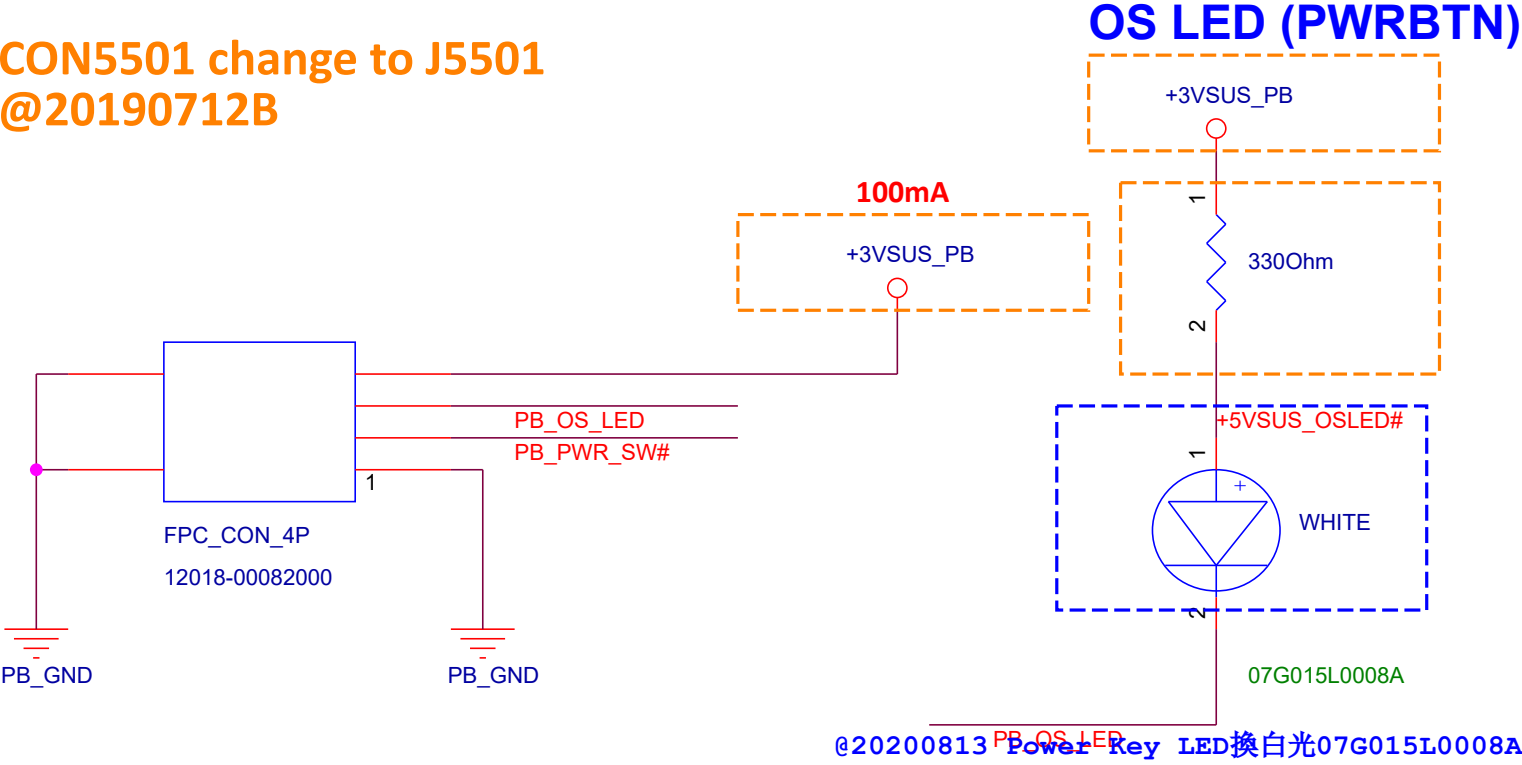
Change @20181023F



@20200706_del H6532 change H6506 H6505
add H6507

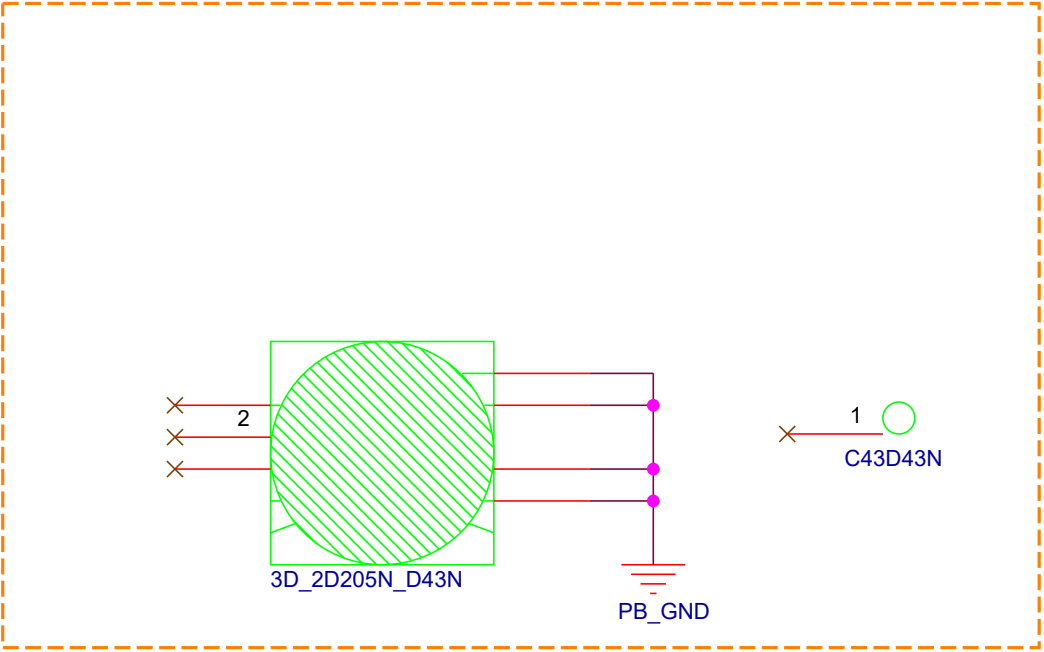
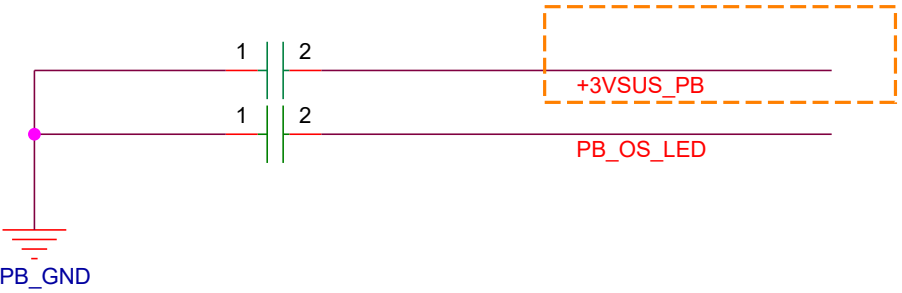
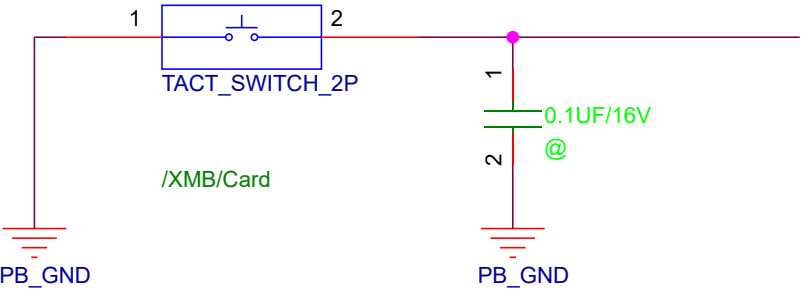


CON5501 change to J5501
@20190712B

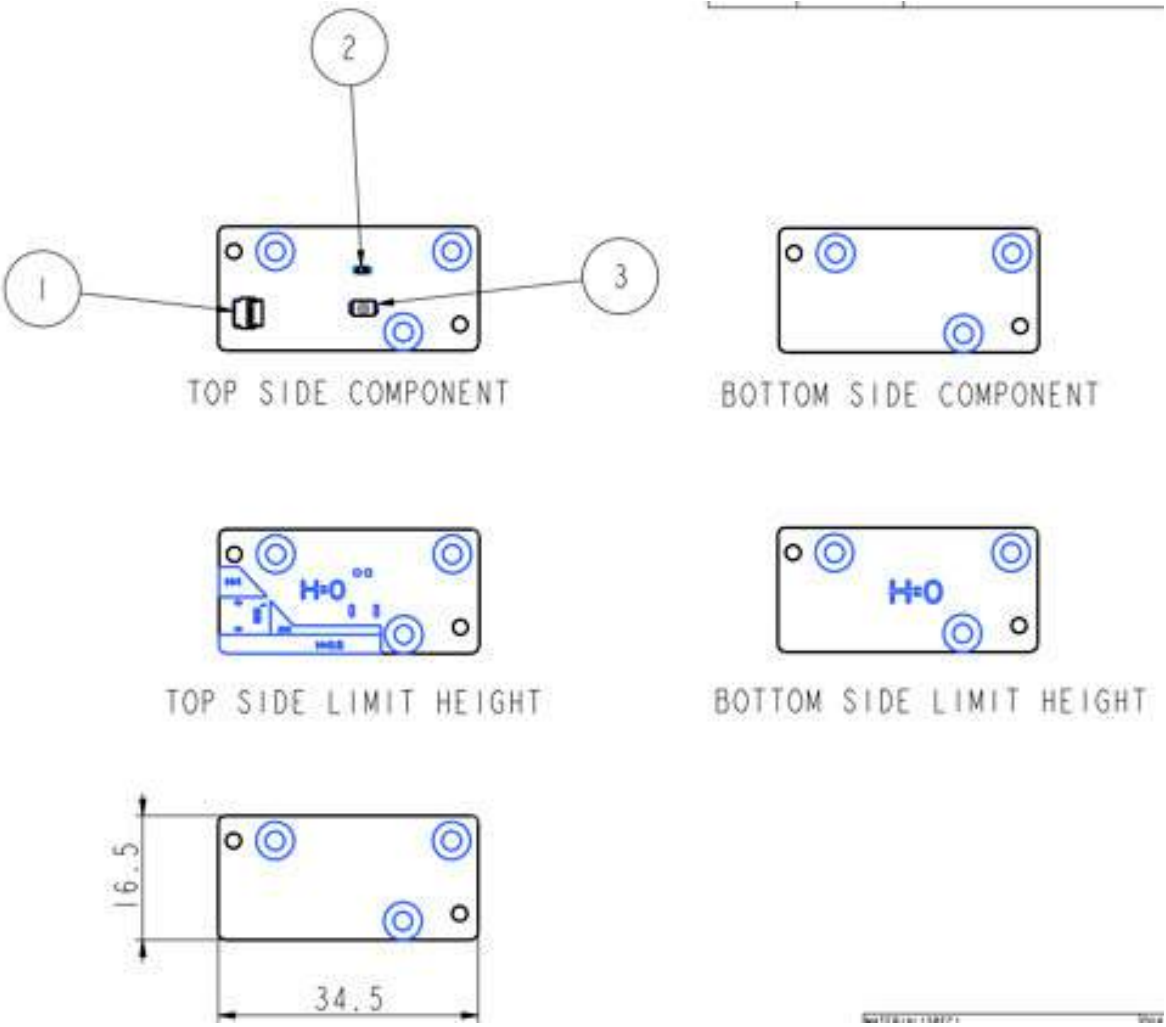


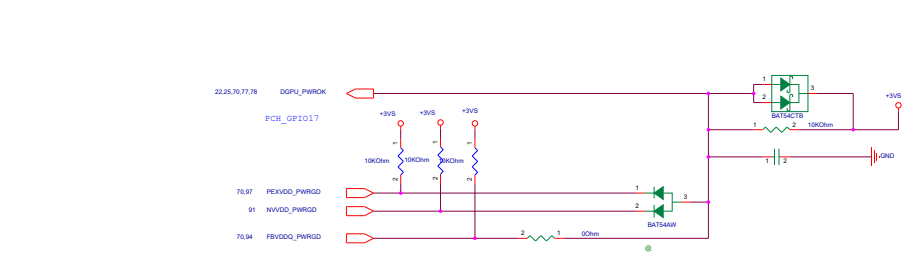
+5VSUS_PB -- +3VSUS_PB
R5510 750 OHM -- 330 OHM
@20190708A

POWER button

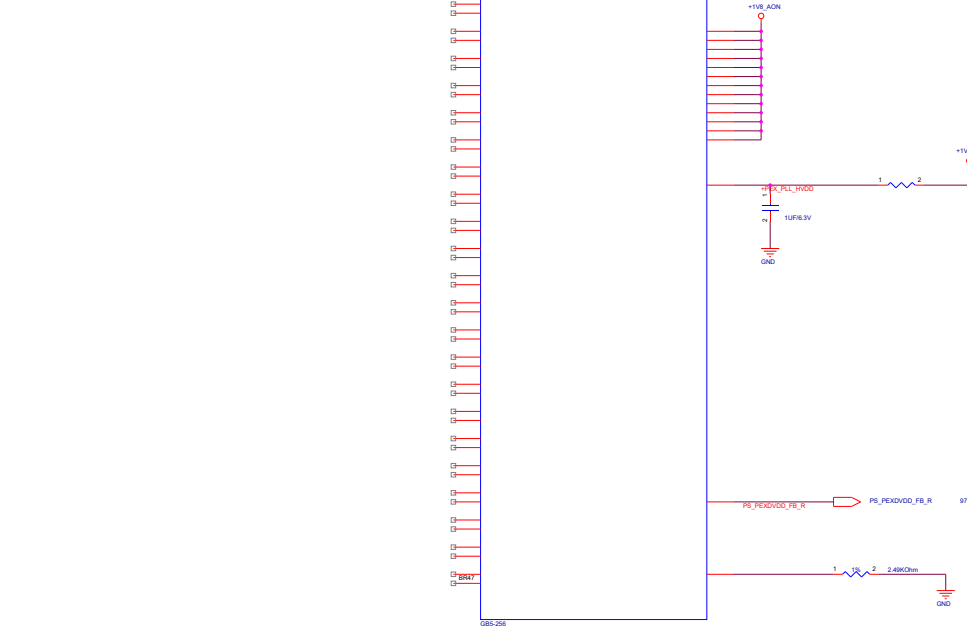
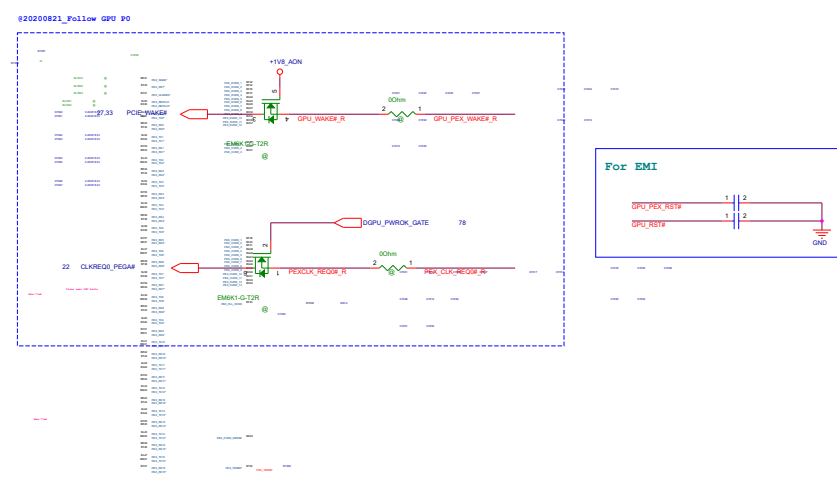
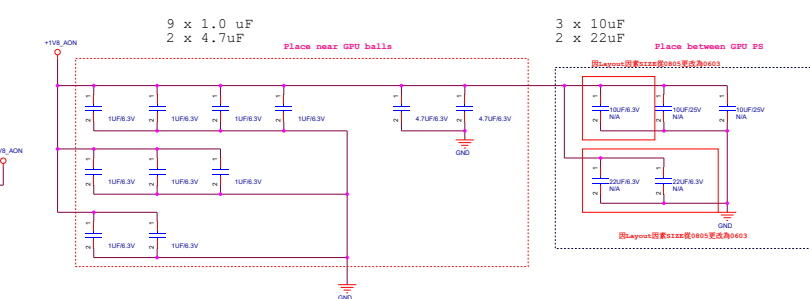
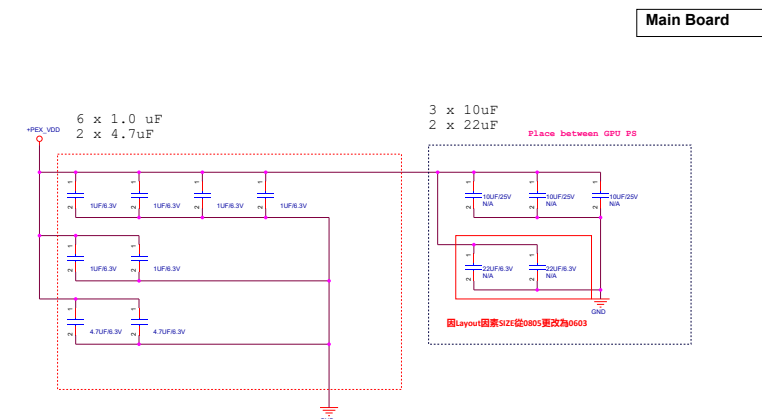
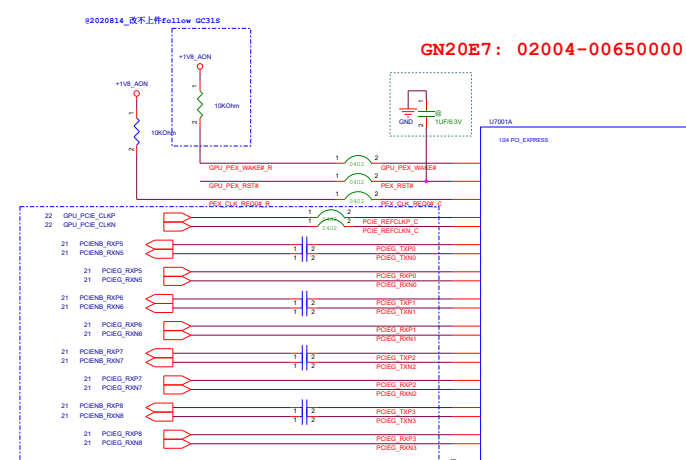
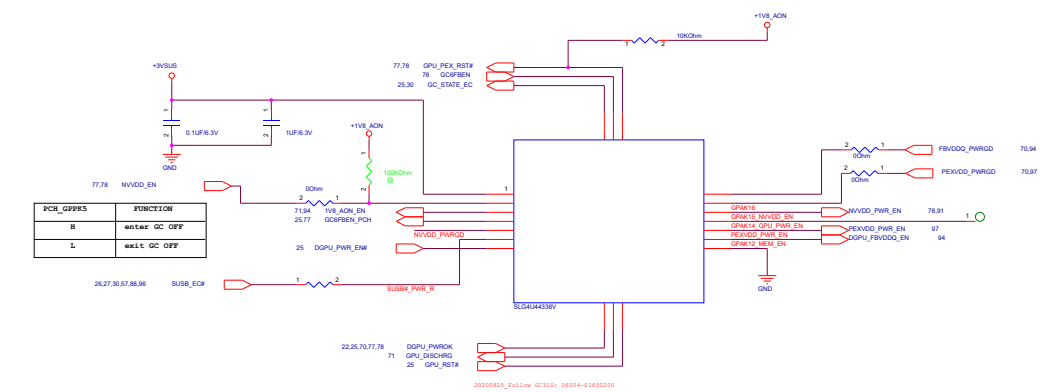


Vinafix.com



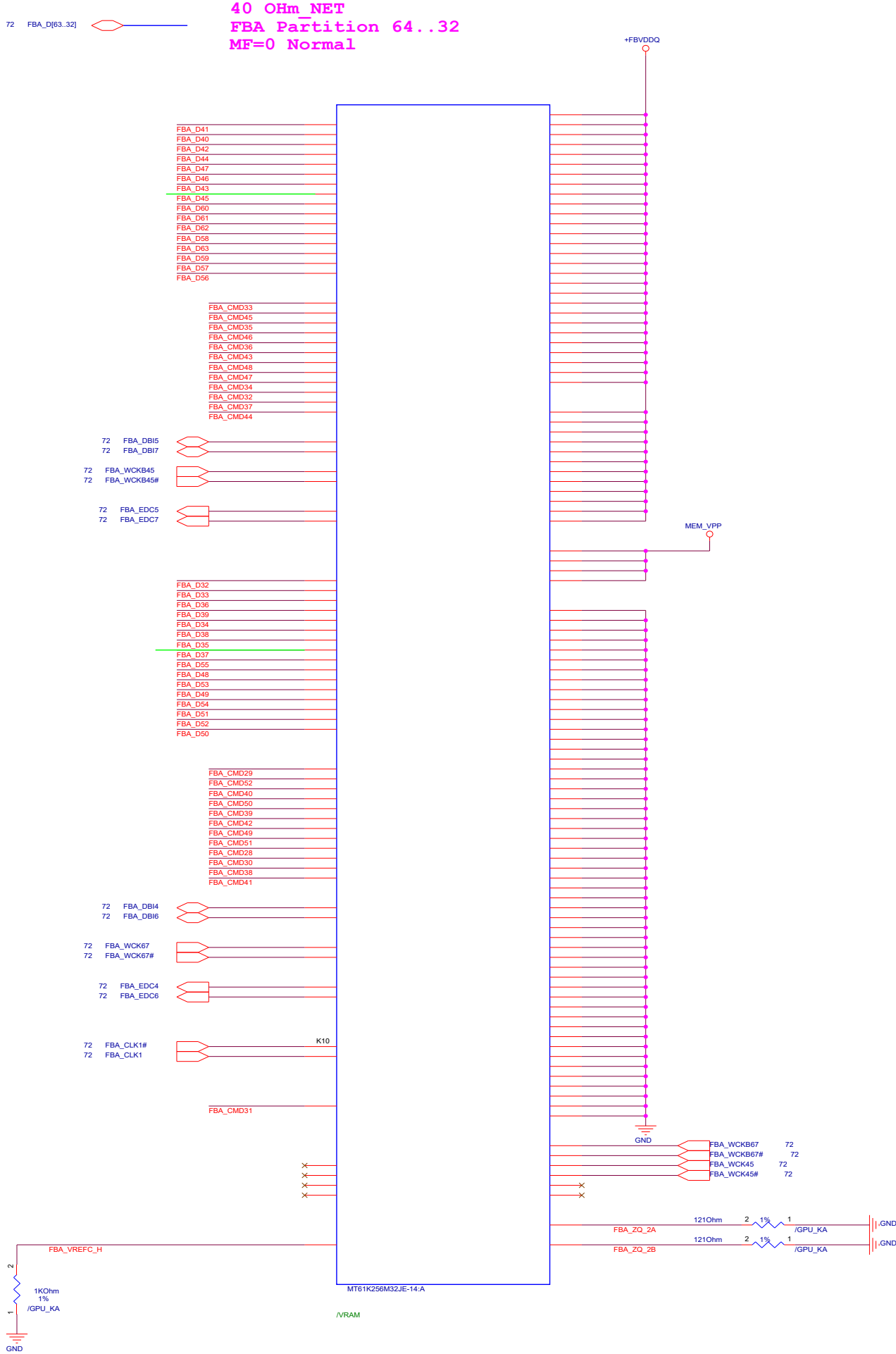
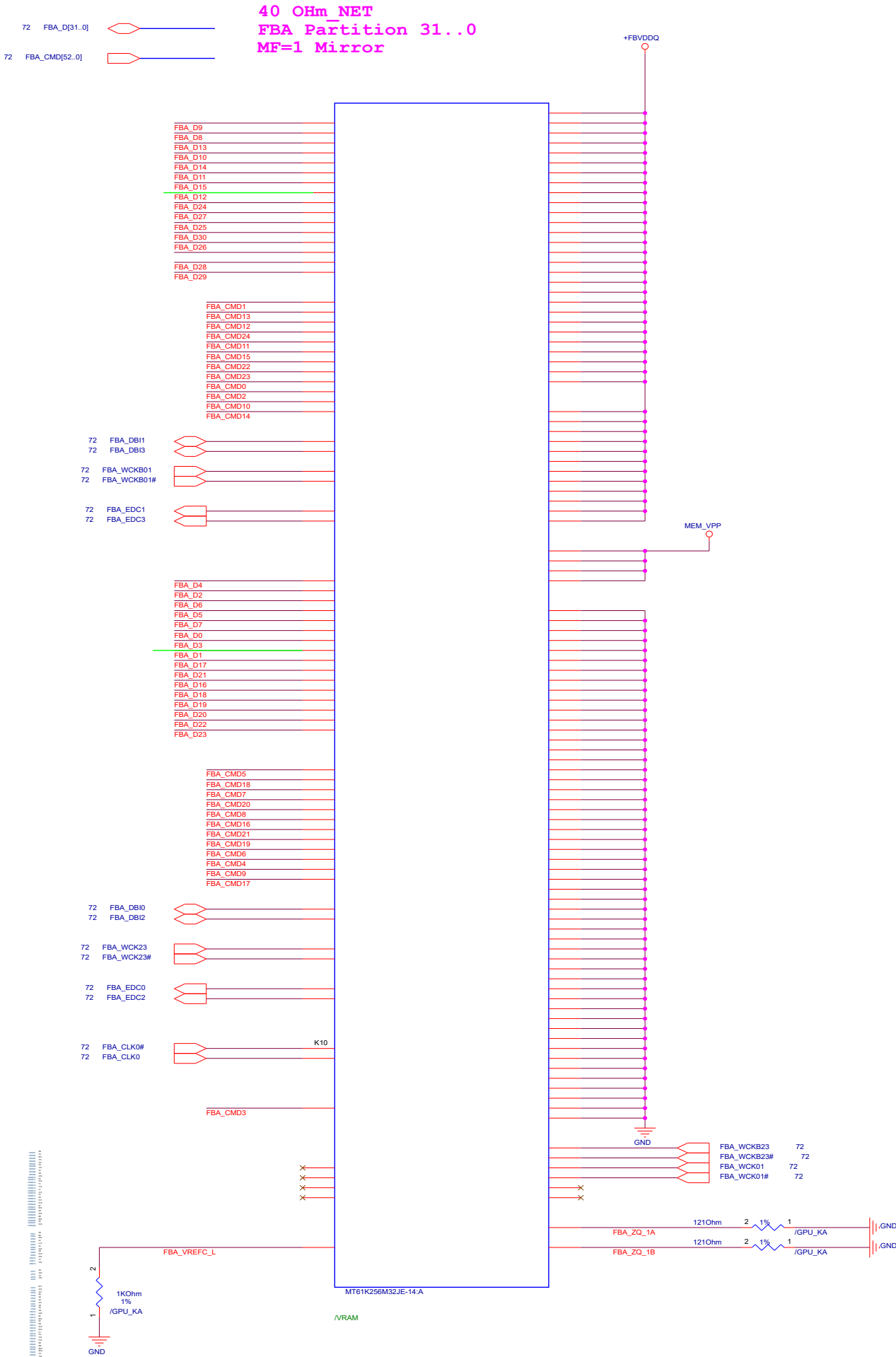


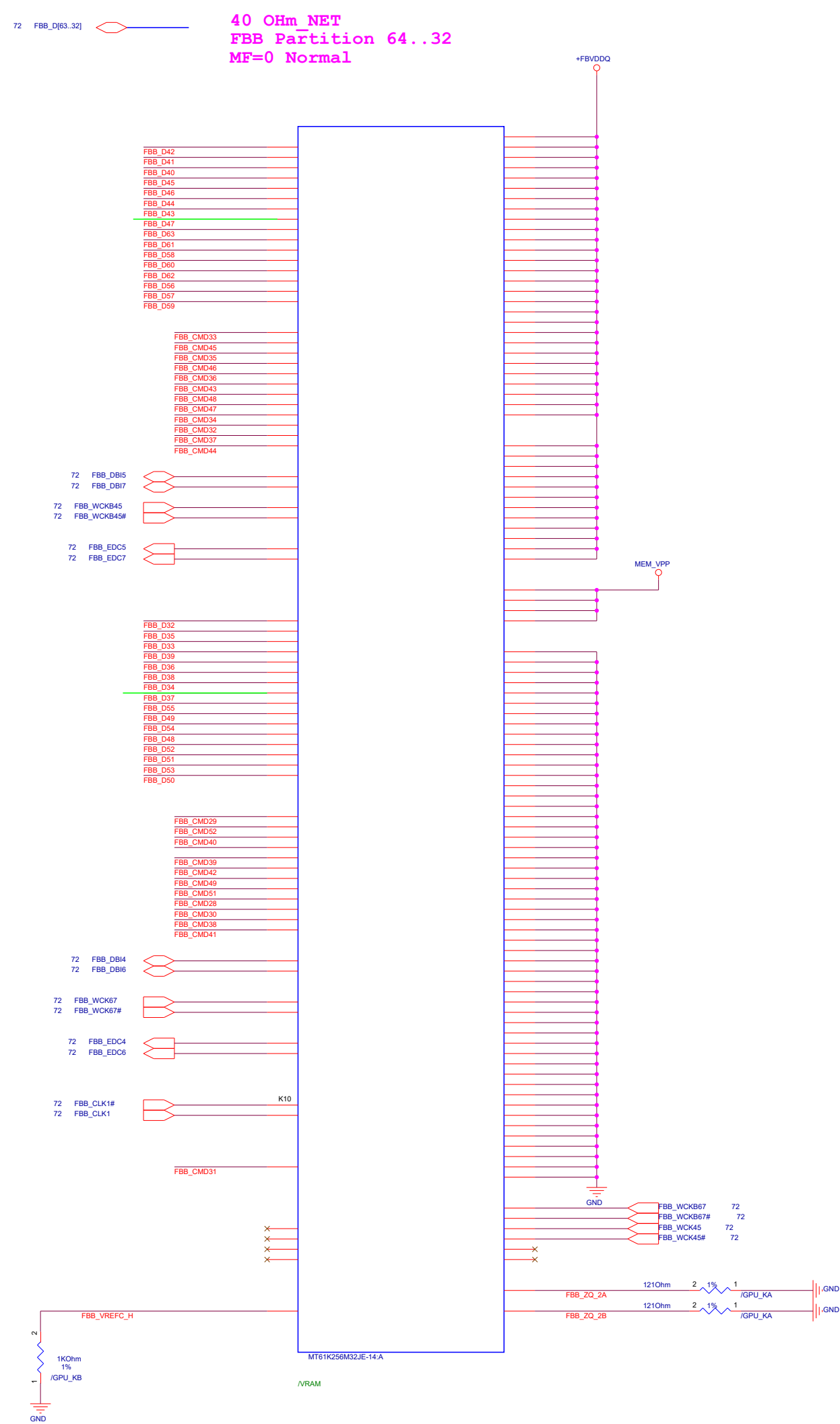
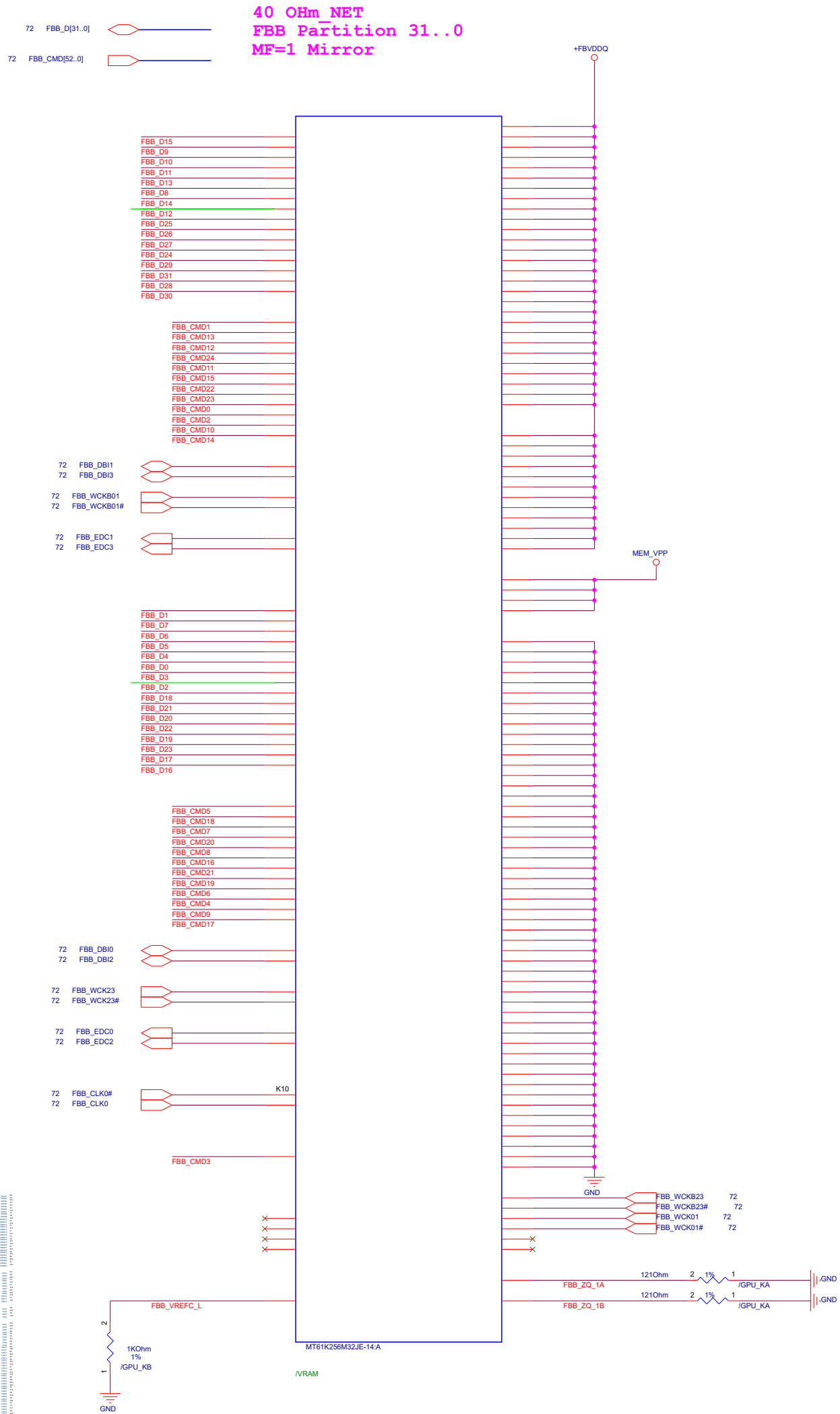
GPU POWER SEQUENCE CONTROL



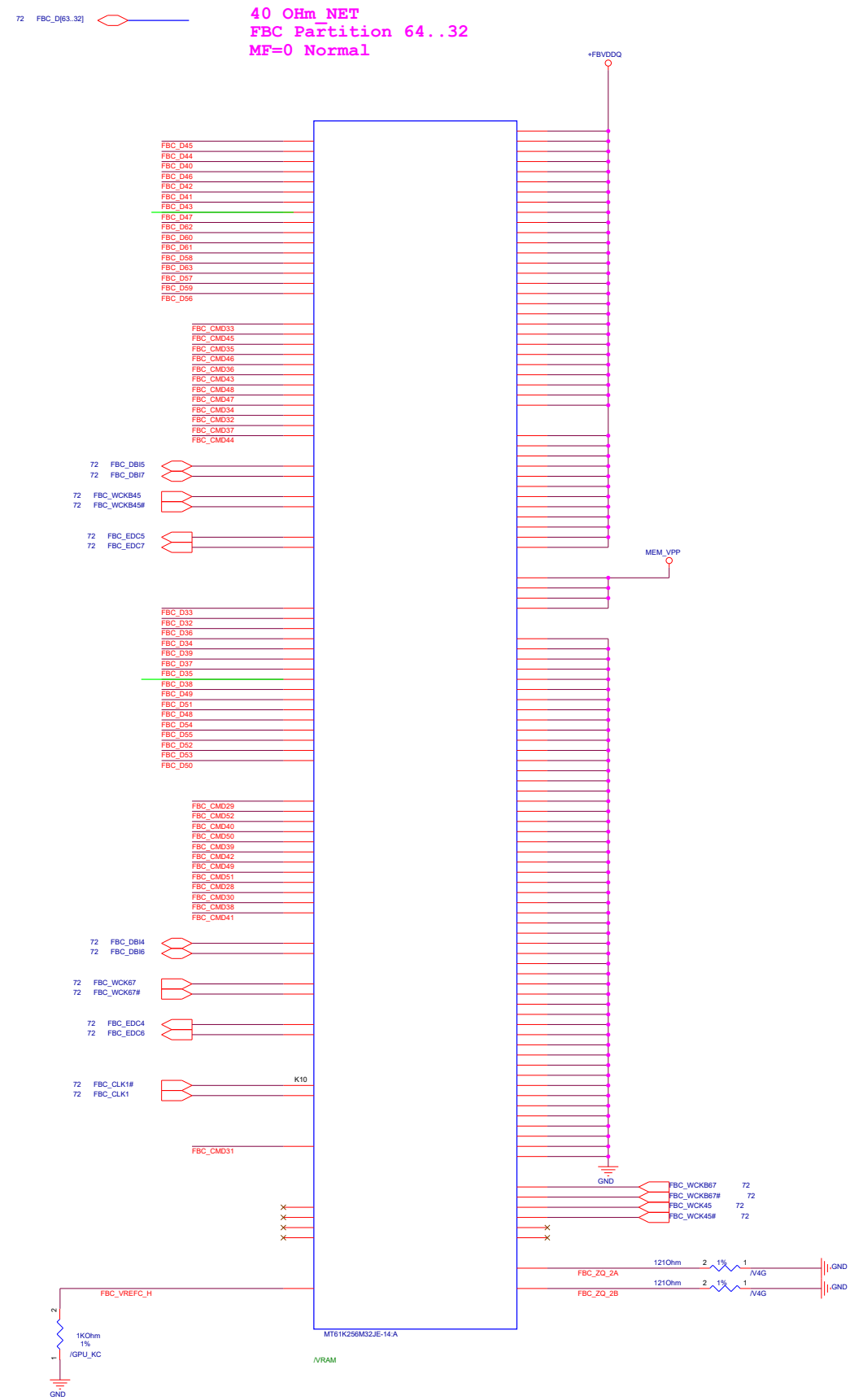
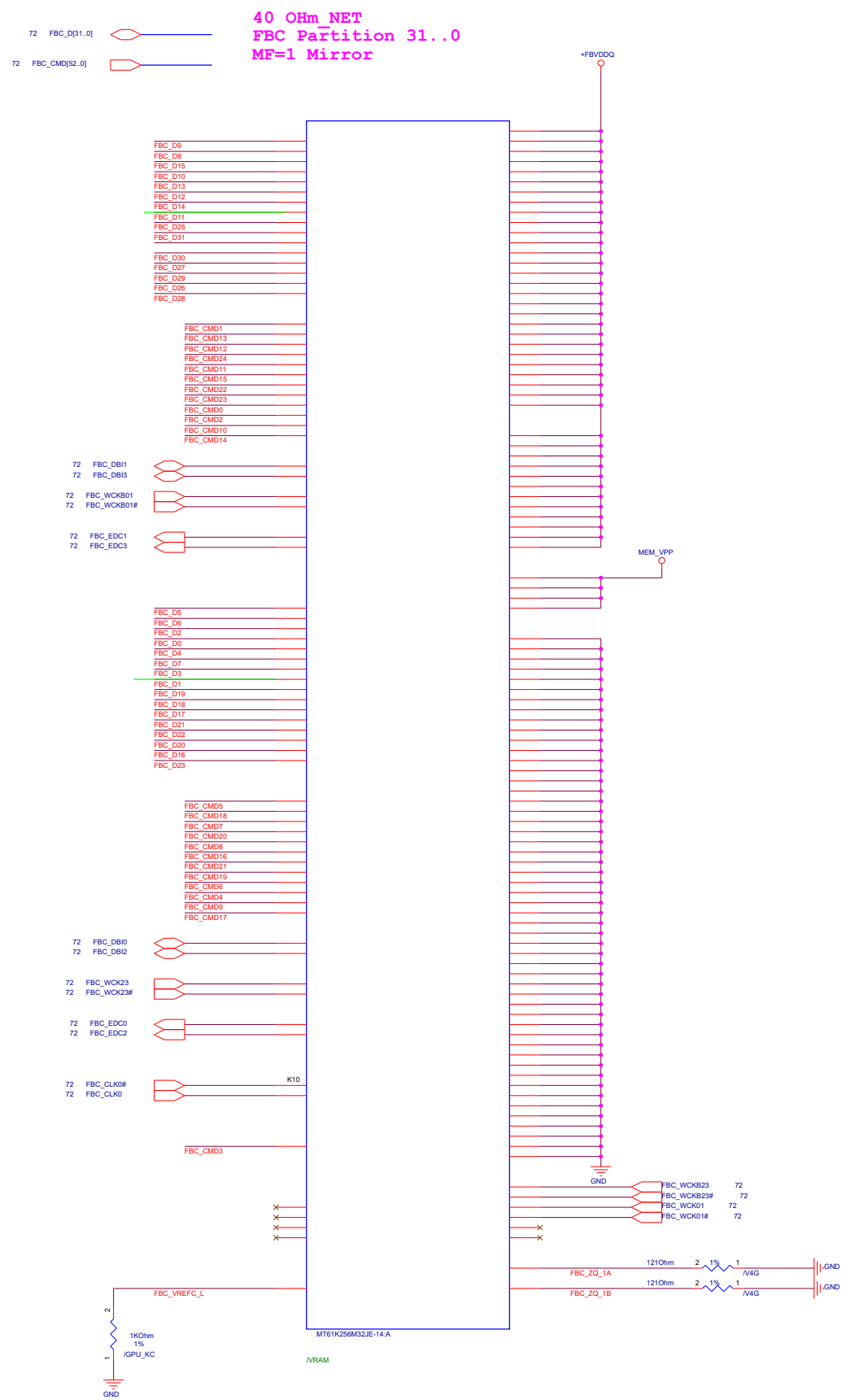


Samsung_256*32_K4Z80325BC : 03014-00010600(目前
Micron_256M*32_MT61K256M32JE: 03014-00010500





Samsung_256*32_K4Z80325BC : 03014-00010600 (目前
Micron_256M*32_MT61K256M32JE: 03014-00010500



40 OHm NET
FBD Partition 31..0
MF=1 Mirror

72 FBD_D[31..0]
72 FBD_CMD[52..0]

FBD_D14
FBD_D10
FBD_D15
FBD_D9
FBD_D13
FBD_D8
FBD_D12
FBD_D11
FBD_D26
FBD_D25
FBD_D24
FBD_D27
FBD_D28
FBD_D31
FBD_D30
FBD_D29

FBD_CMD1
FBD_CMD13
FBD_CMD12
FBD_CMD24
FBD_CMD11
FBD_CMD15
FBD_CMD22
FBD_CMD23
FBD_CMD0
FBD_CMD2
FBD_CMD10
FBD_CMD14

72 FBD_DBI1
72 FBD_DBI3
72 FBD_WCKB01
72 FBD_WCKB01#
72 FBD_EDC1
72 FBD_EDC3

FBD_D7
FBD_D6
FBD_D4
FBD_D5
FBD_D3
FBD_D0
FBD_D2
FBD_D1
FBD_D16
FBD_D22
FBD_D20
FBD_D21
FBD_D18
FBD_D23
FBD_D17
FBD_D19

FBD_CMD5
FBD_CMD18
FBD_CMD7
FBD_CMD20
FBD_CMD26
FBD_CMD16
FBD_CMD21
FBD_CMD19
FBD_CMD26
FBD_CMD4
FBD_CMD9
FBD_CMD17

72 FBD_DBI0
72 FBD_DBI2
72 FBD_WCK23
72 FBD_WCK23#
72 FBD_EDC0
72 FBD_EDC2

72 FBD_CLK0#
72 FBD_CLK0

FBD_CMD3

FBD_VREFC_L
1K0hm
1%
/GPU_KD
GND

MT61K256M32JE-14-A

+FBVDDQ

MEM_VPP

GND

GND

FBD_ZQ_1A 1210hm 2 1% 1 /VGG
FBD_ZQ_1B 1210hm 2 1% 1 /VGG

40 OHm NET
FBDPartition 64..32
MF=0 Normal

72 FBD_D[63..32]

FBD_D42
FBD_D45
FBD_D40
FBD_D44
FBD_D43
FBD_D46
FBD_D41
FBD_D47
FBD_D81
FBD_D56
FBD_D62
FBD_D63
FBD_D60
FBD_D59
FBD_D57

FBD_CMD33
FBD_CMD45
FBD_CMD35
FBD_CMD46
FBD_CMD36
FBD_CMD43
FBD_CMD48
FBD_CMD47
FBD_CMD34
FBD_CMD32
FBD_CMD37
FBD_CMD44

72 FBD_DBI5
72 FBD_DBI7
72 FBD_WCKB45
72 FBD_WCKB45#
72 FBD_EDC5
72 FBD_EDC7

FBD_D36
FBD_D33
FBD_D35
FBD_D32
FBD_D34
FBD_D39
FBD_D38
FBD_D37
FBD_D49
FBD_D48
FBD_D50
FBD_D51
FBD_D55
FBD_D52
FBD_D54
FBD_D53

FBD_CMD29
FBD_CMD52
FBD_CMD40
FBD_CMD50
FBD_CMD39
FBD_CMD42
FBD_CMD49
FBD_CMD51
FBD_CMD28
FBD_CMD30
FBD_CMD38
FBD_CMD41

72 FBD_DBI4
72 FBD_DBI6
72 FBD_WCK67
72 FBD_WCK67#
72 FBD_EDC4
72 FBD_EDC6

72 FBD_CLK1#
72 FBD_CLK1

FBD_CMD31

FBD_VREFC_H
1K0hm
1%
/GPU_KD
GND

MT61K256M32JE-14-A

+FBVDDQ

MEM_VPP

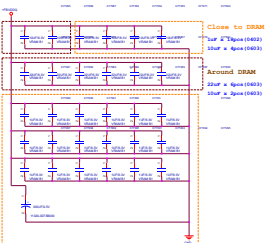
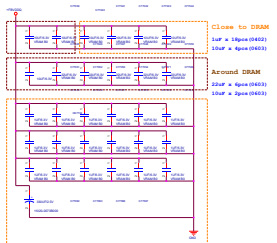
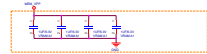
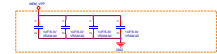
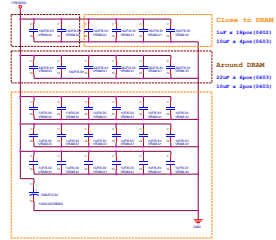
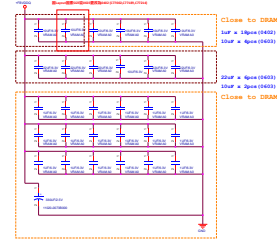
GND

GND

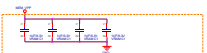
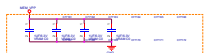
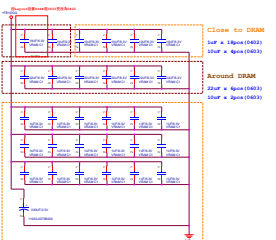
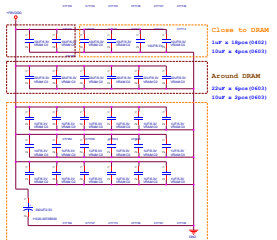
FBD_ZQ_2A 1210hm 2 1% 1 /VGG
FBD_ZQ_2B 1210hm 2 1% 1 /VGG

TV50DQ
VRAM side

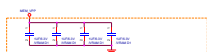
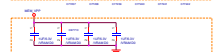
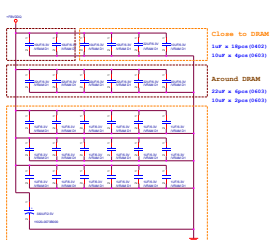
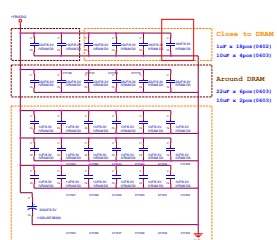
Channel A



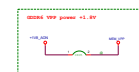
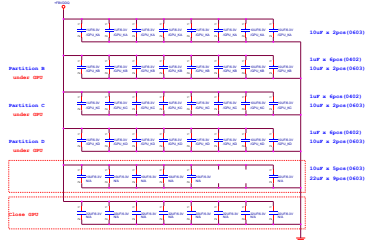
Channel C

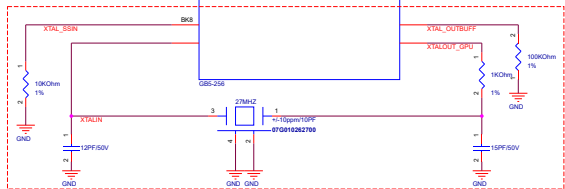
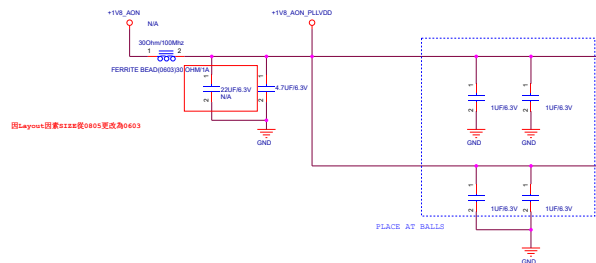
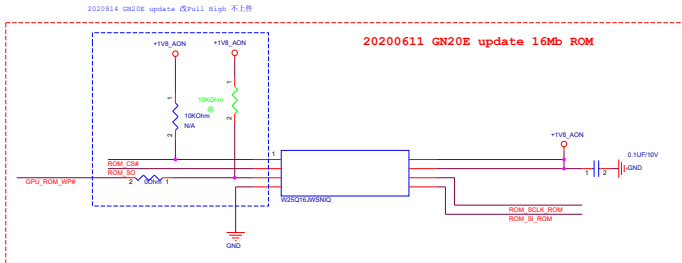
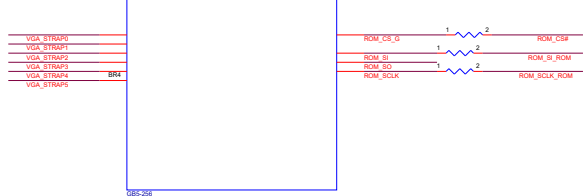


Channel D



GPU side





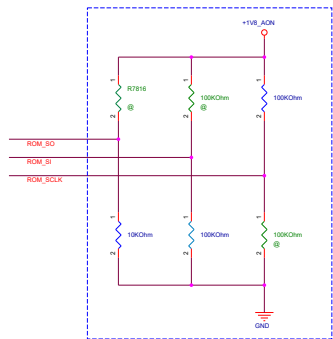
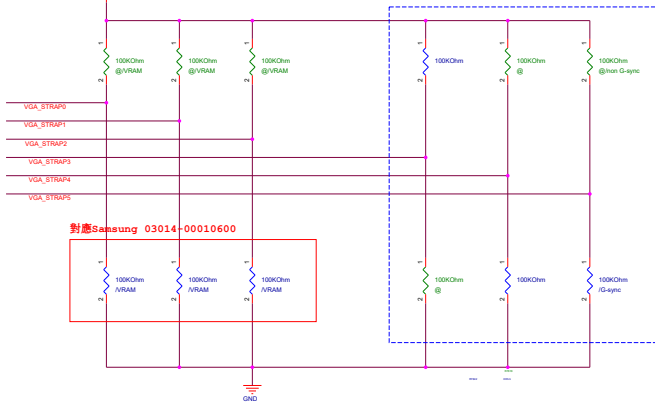
X7801: 27MHz +/-10ppm/10pF (3225)
1st: PN:07G010262700 TXC/VZ7000050

RAM0701: 27MHz +/-10ppm/10pF (3225)
1st: PN:07G010262700 TXC/VZ7000050

STRAP PIN

@20200715_follow NV FAE: HLL

@20200705_follow NV FAE: LH (Default)



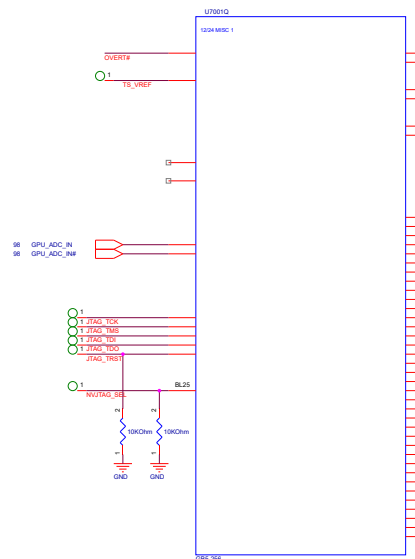
Level Option	Physical Configuration
1.0V (HIGH) Level	Populate
1.0V (MIDDLE) Level	Populate
1.0V (LOW) Level	Populate

Note 1: Resistor should be 100K Ohm. 1% tolerance is required.
Note 2: Resistor should be 100K Ohm. 1% tolerance is required.

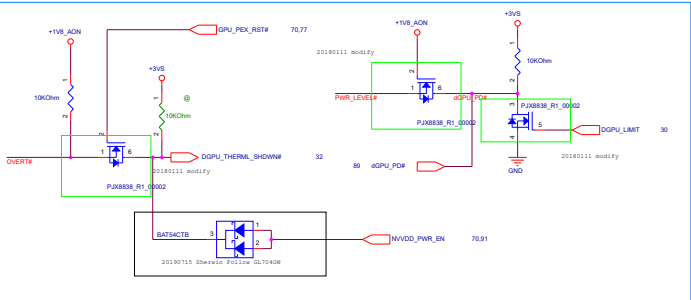
Strap Pins	Strap Pins	Strap Pins	Strap Pins
RAM_00	RAM_01	RAM_02	RAM_03
L	L	L	L
L	L	L	L
L	L	L	L

Default: LLL

VGA INT. Thermal sensor
address 0x9E and 0x9C

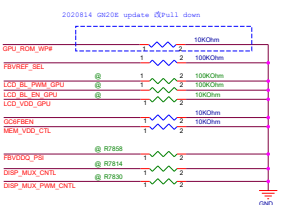
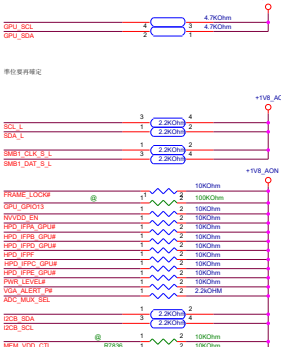


Thermal Protection



Strap Pins	Strap Pins	Strap Pins	Strap Pins
RAM_00	RAM_01	RAM_02	RAM_03
L	L	L	L
L	L	L	L
L	L	L	L

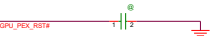
Strap Pins	Strap Pins	Strap Pins	Strap Pins
RAM_00	RAM_01	RAM_02	RAM_03
L	L	L	L
L	L	L	L
L	L	L	L



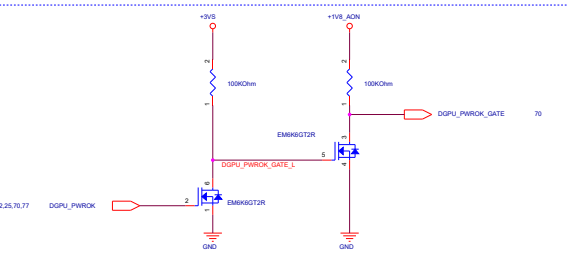
Default: LLL

GPU GPIO INPUT

GPU GPIO INPUT

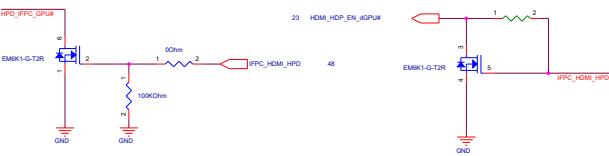


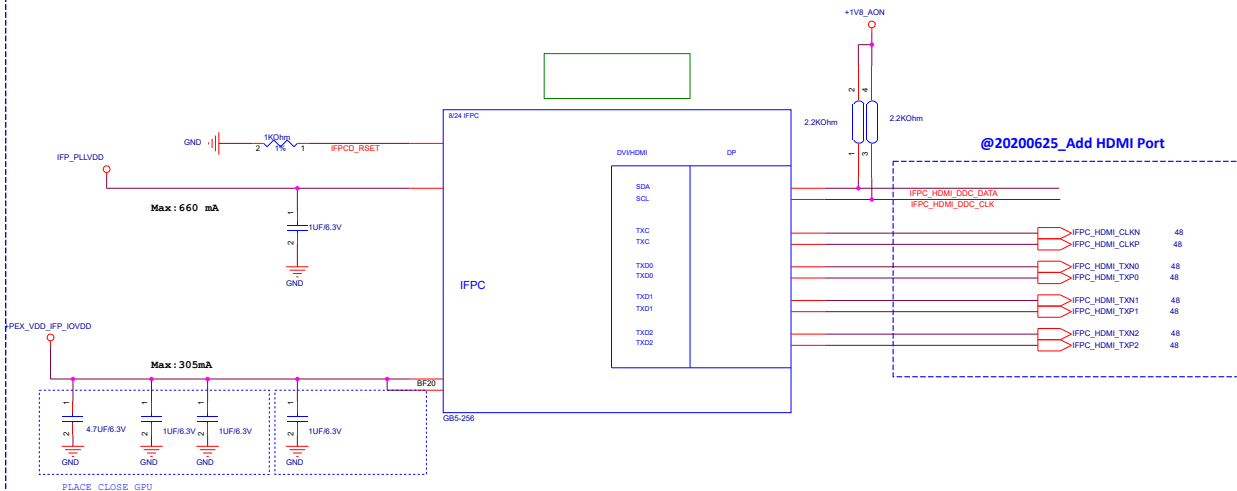
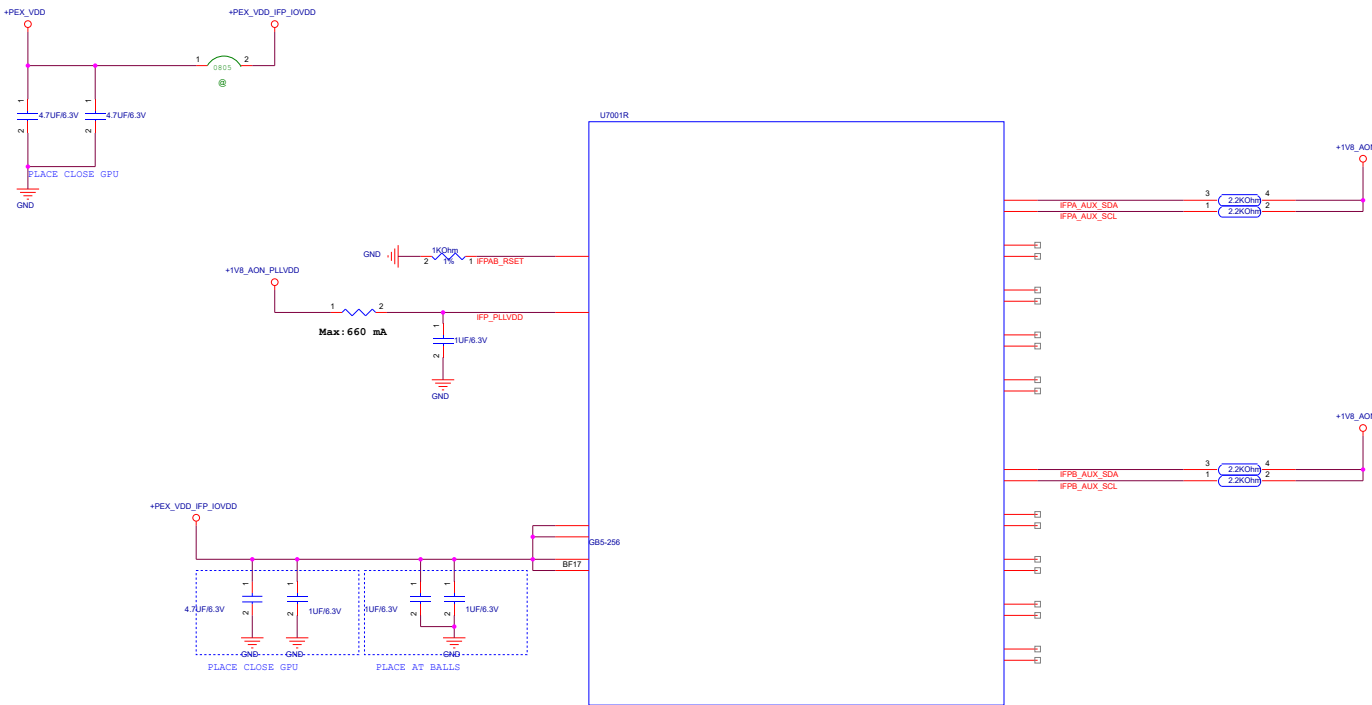
@20200621_follow GPU P0



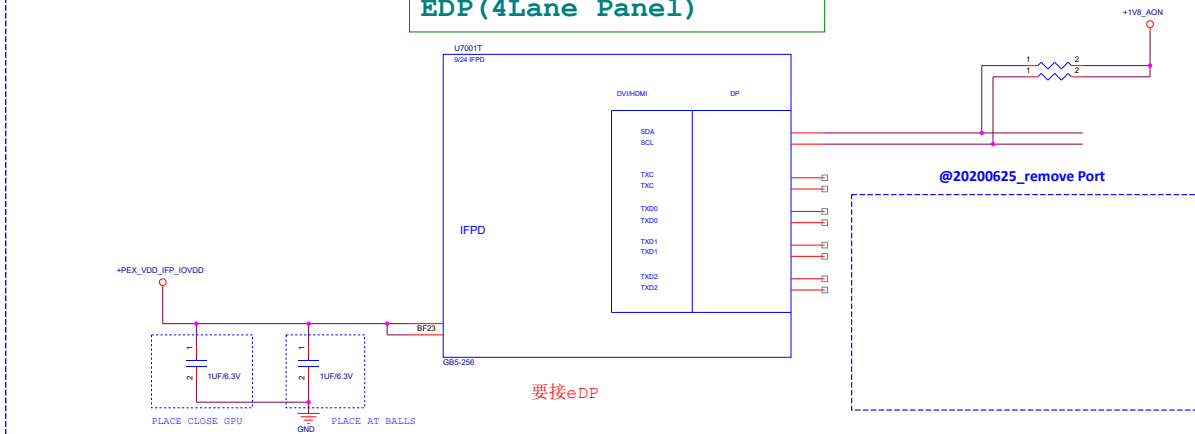
Assumed Configuration Strap:
1. SMI, ALT_ADDR Enable: "1" support G-Link, "0" support G-Link, "1" support G-Link, "0" support G-Link.
2. DEV0_SEL: G-Link Function: "0" normal GPU ID, "1" support G-Link GPU ID.
3. PCE_CFG: PCE Setting: "0" "0" Setting default, "1" "1" Setting default.
4. VGA_DEVICE: Graphics circuit: "0" "0" Setting default, "1" "1" Setting default.

0. SMI, ALT_ADDR Disable
1. DEV0_SEL: G-Link Function
2. PCE_CFG: PCE Setting
3. PCE_CFG: PCE Setting
4. VGA_DEVICE: Graphics circuit

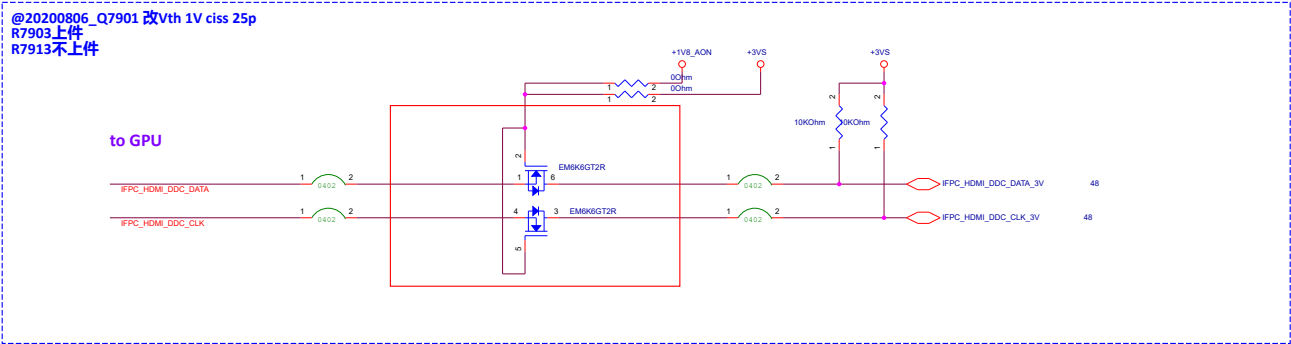
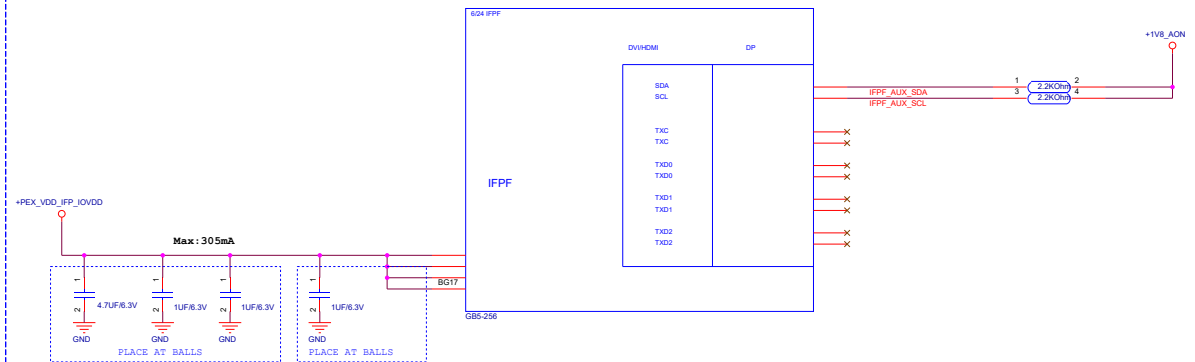




EDP(4Lane Panel)

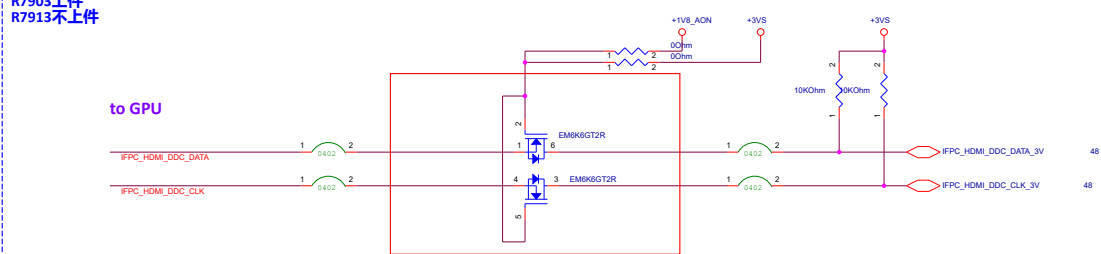


IFPF(not used)

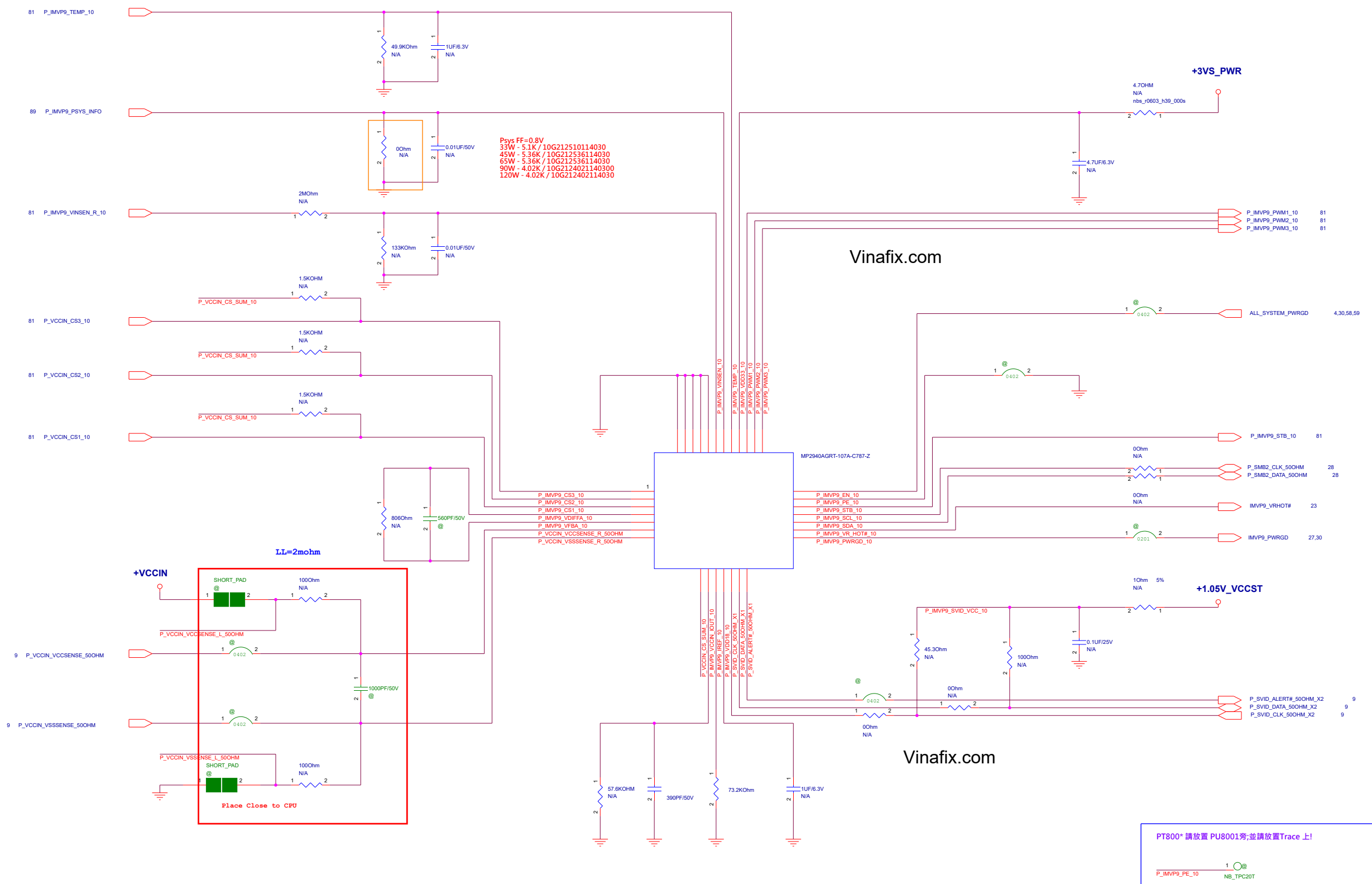


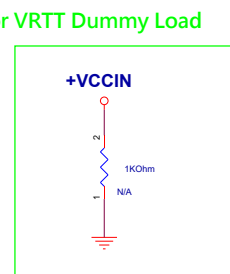
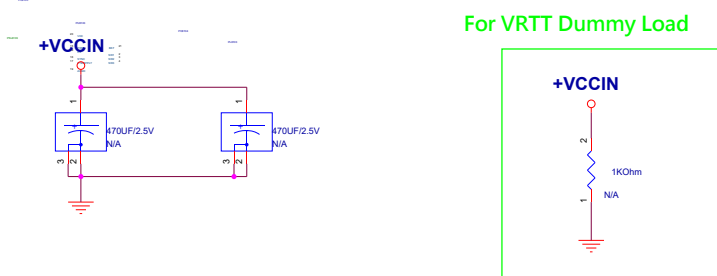
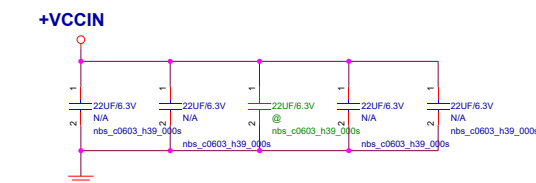
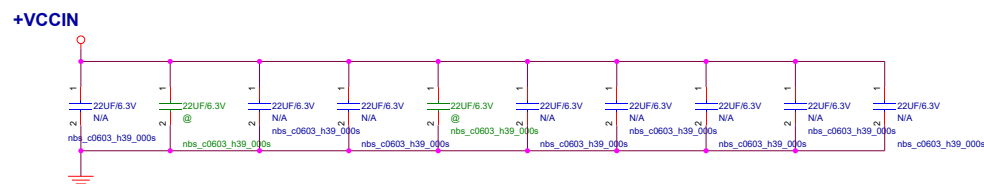
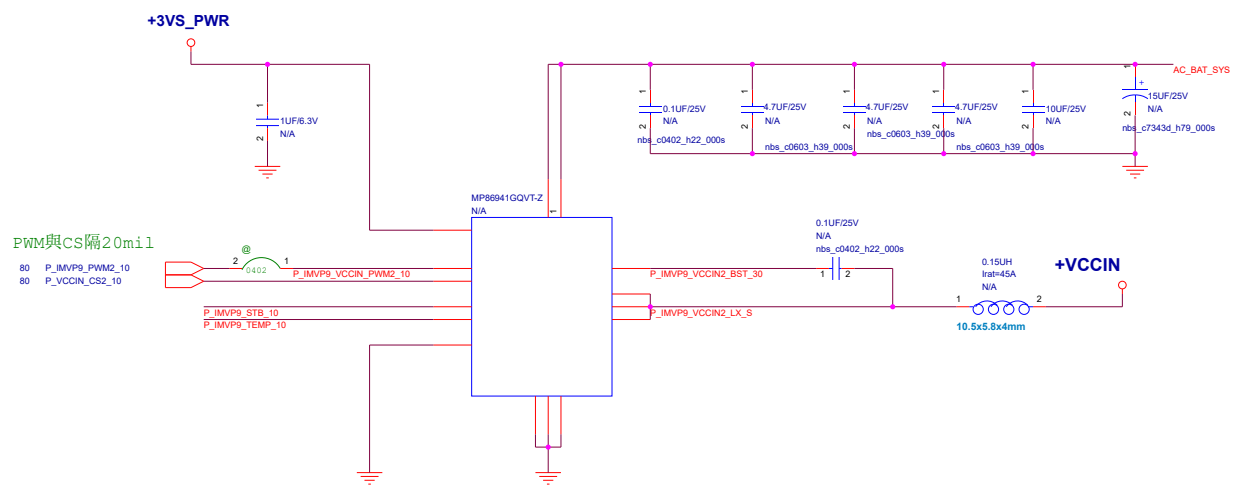
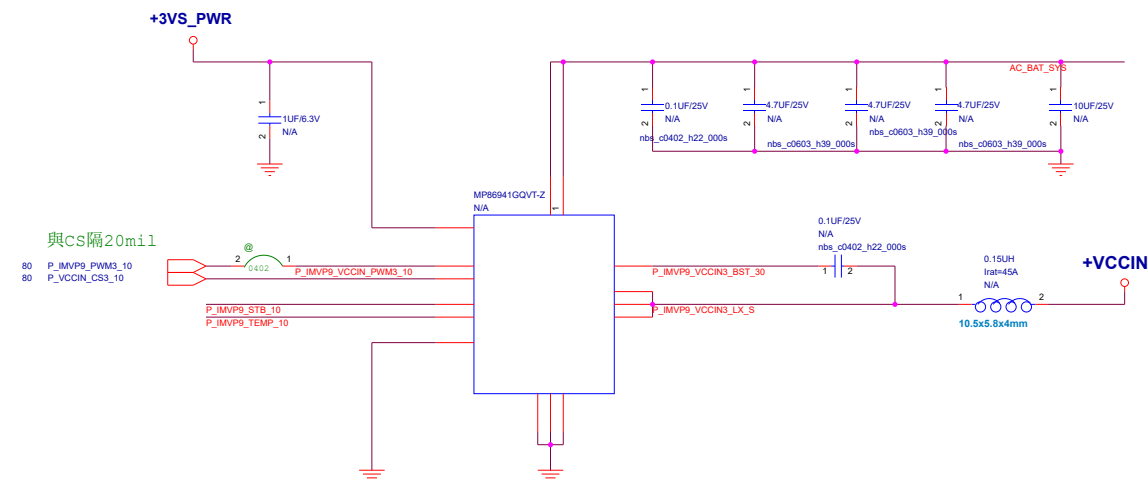
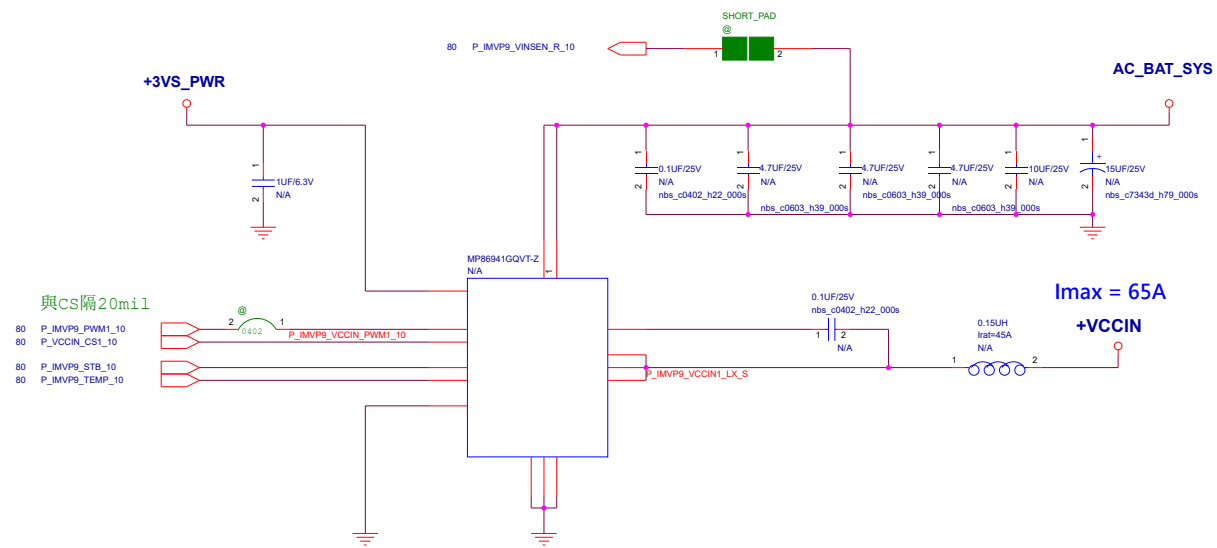
@20200806_Q7901 改Vth 1V ciss 25p
R7903 上件
R7913不上件

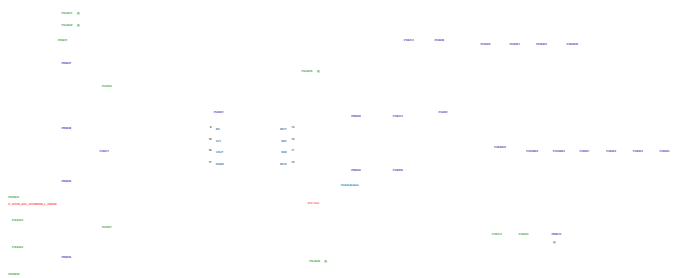
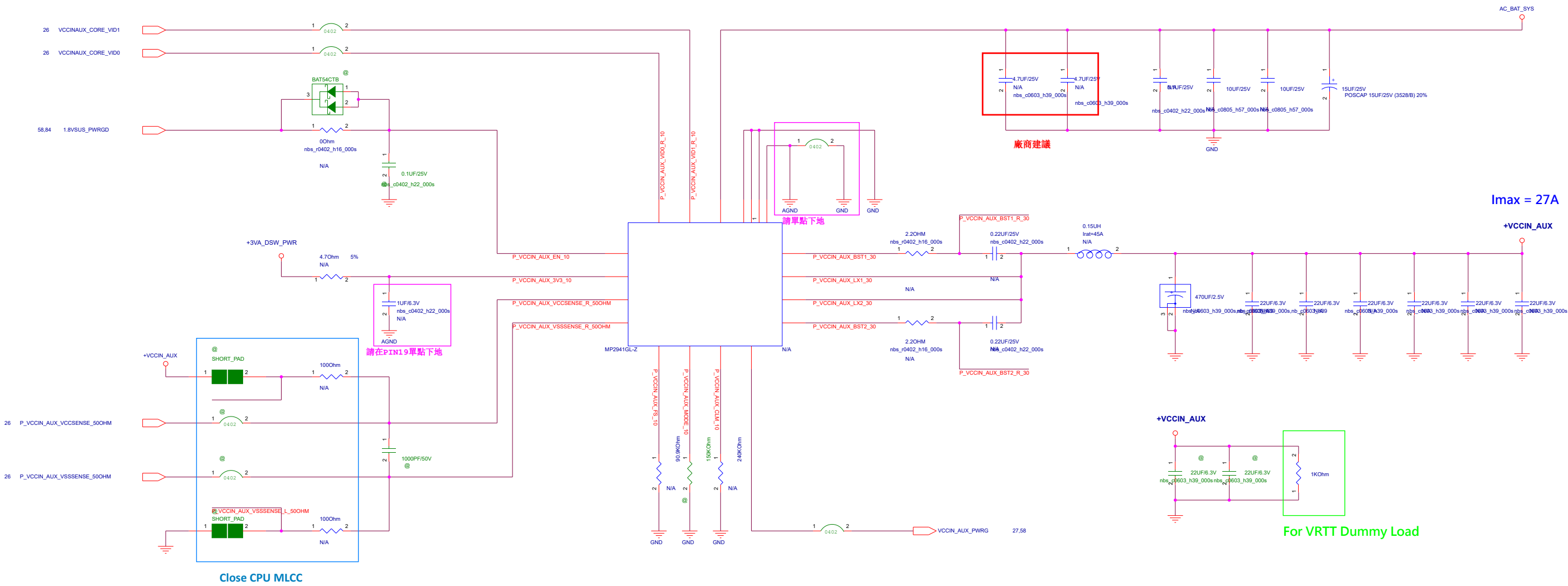
to GPU



TGL IMVP9 (1) Power [For CPU]

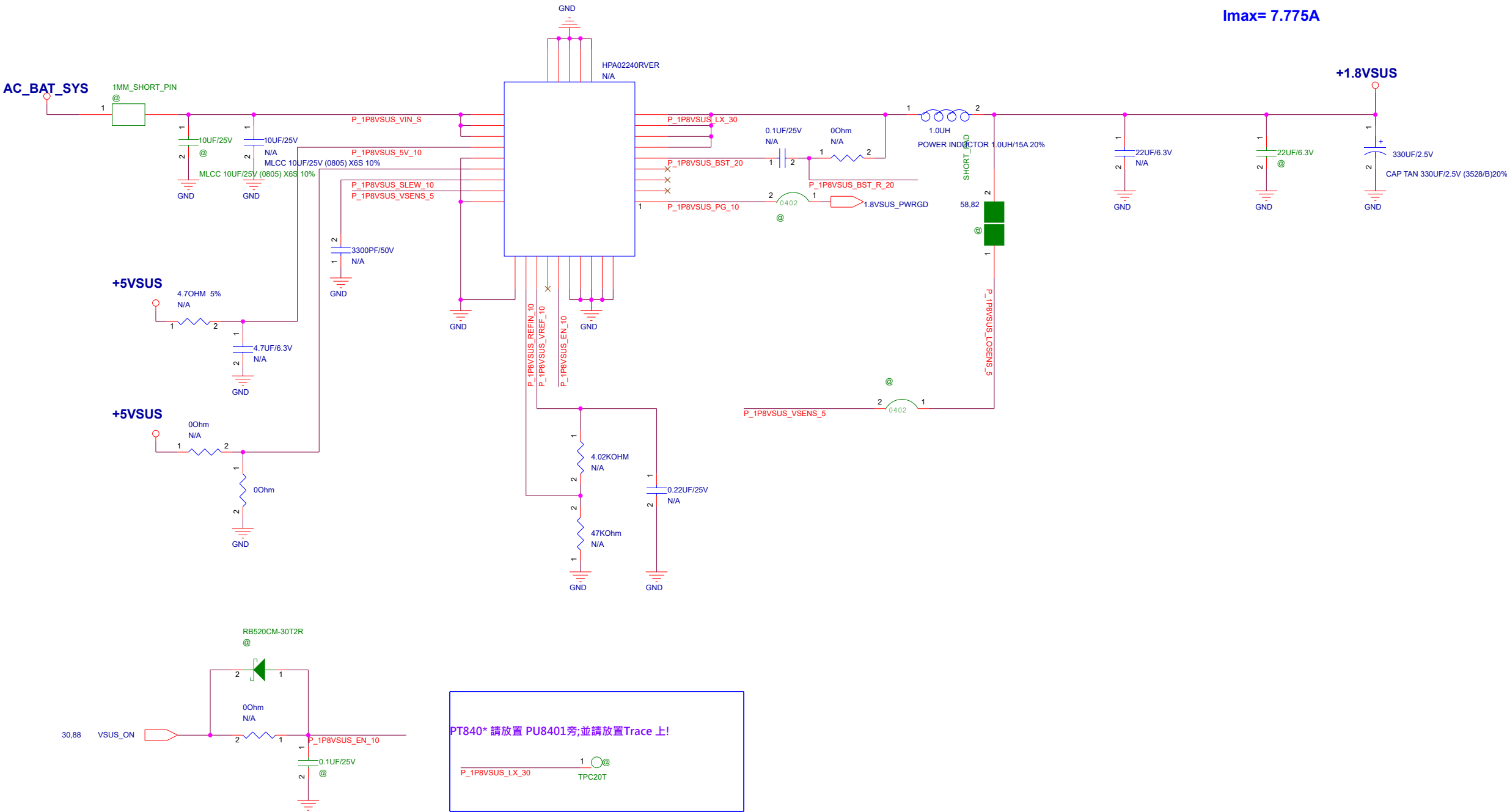


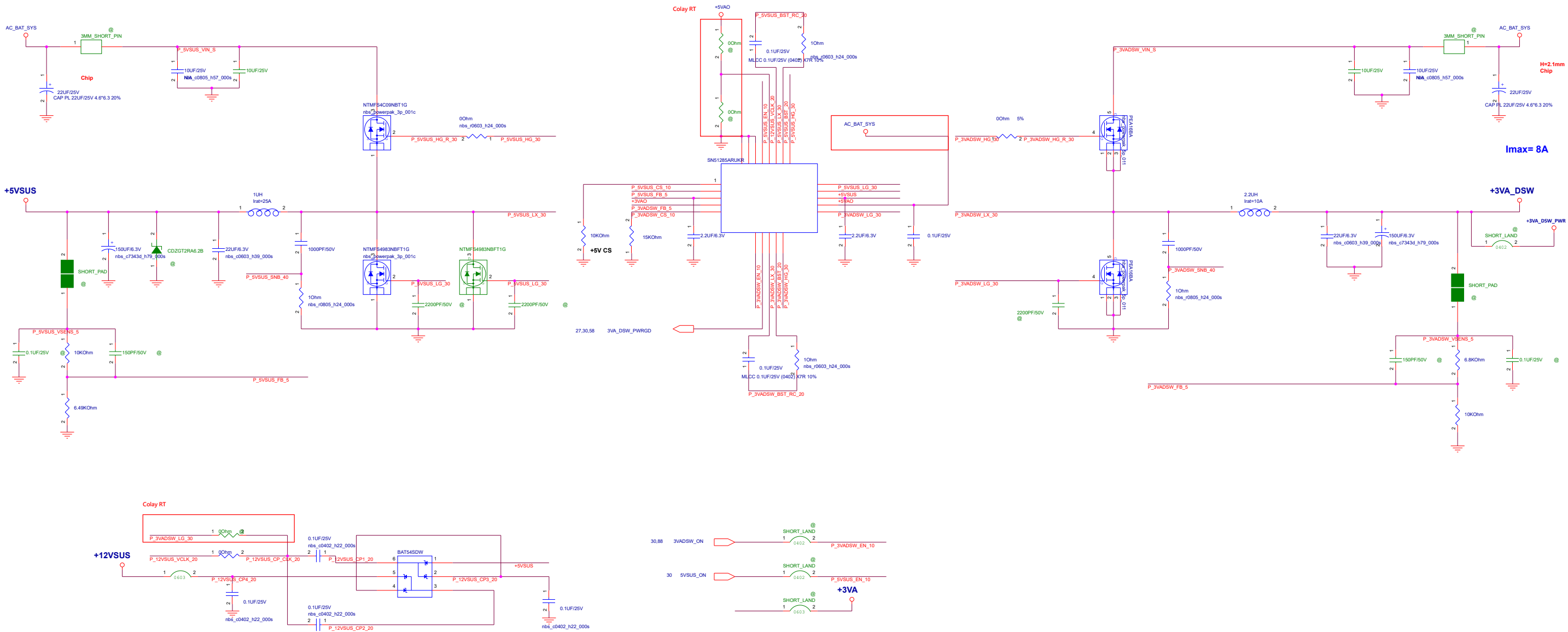




+1.8VSUS [For PCH]

Imax= 7.775A



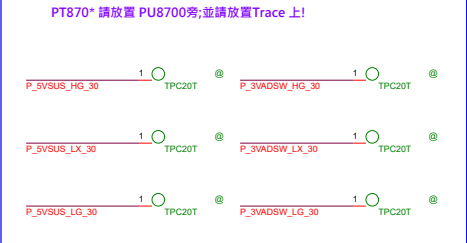


請 check 整份線路 +12VSUS total 並聯對地電阻不得小於10kOhm

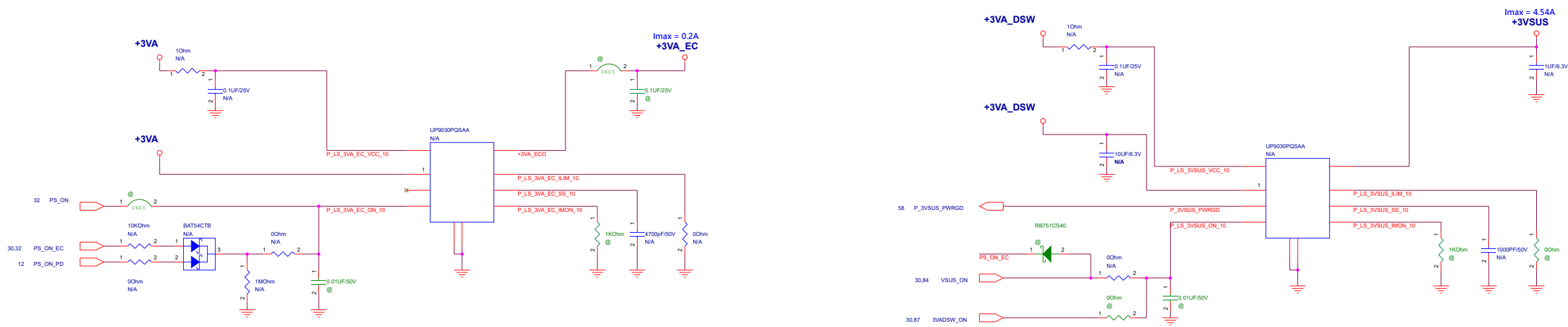


	S0	CS	S3	DS3	S4	S5	S5 with USB Charger+
PS_ON	1	-	1	-	1	-	1
3VADSW_ON	1	-	1	-	1	-	1
3VSUS_ON	1	-	1	-	-	-	1
5VSUS_ON	1	-	1	-	1	-	1
1.35V_ON	1	-	1	-	0	-	0
SUSC_EC#	1	-	1	-	0	-	0
SUSB_EC#	1	-	0	-	0	-	0

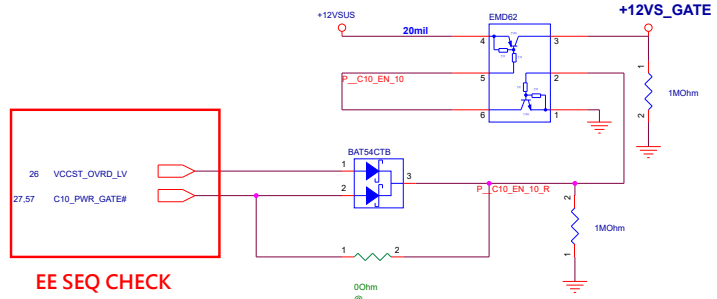
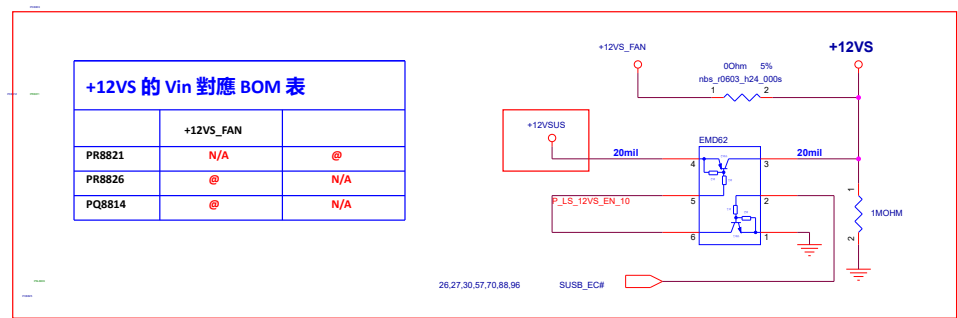
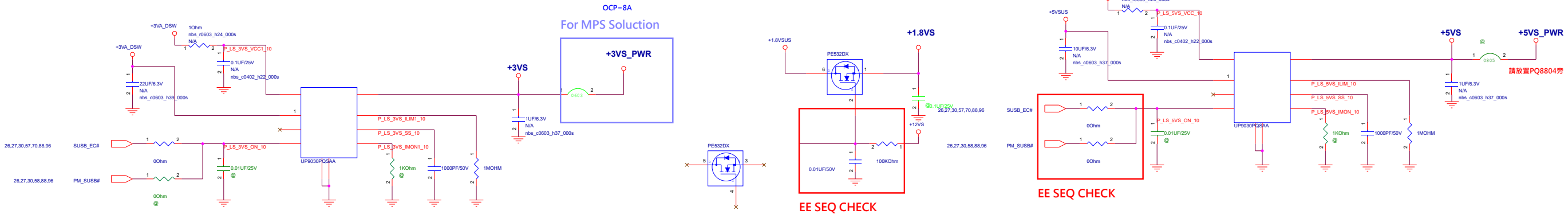
Battery Mode (IMVP6)							
	S0	CS	S3	DS3	S4	S5	S5 with USB Charger+
PS_ON	1	-	-	1	0	0	1
3VADSW_ON	1	-	-	1	0	0	0
3VSUS_ON	1	-	-	0	0	0	0
5VSUS_ON	1	-	-	1	0	0	1
1.35V_ON	1	-	-	1	0	0	0
SUSC_EC#	1	-	-	0	0	0	0
SUSB_EC#	1	-	-	0	0	0	0

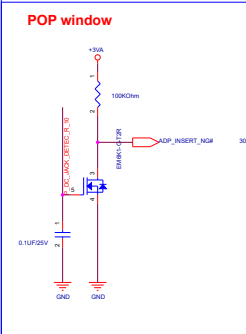
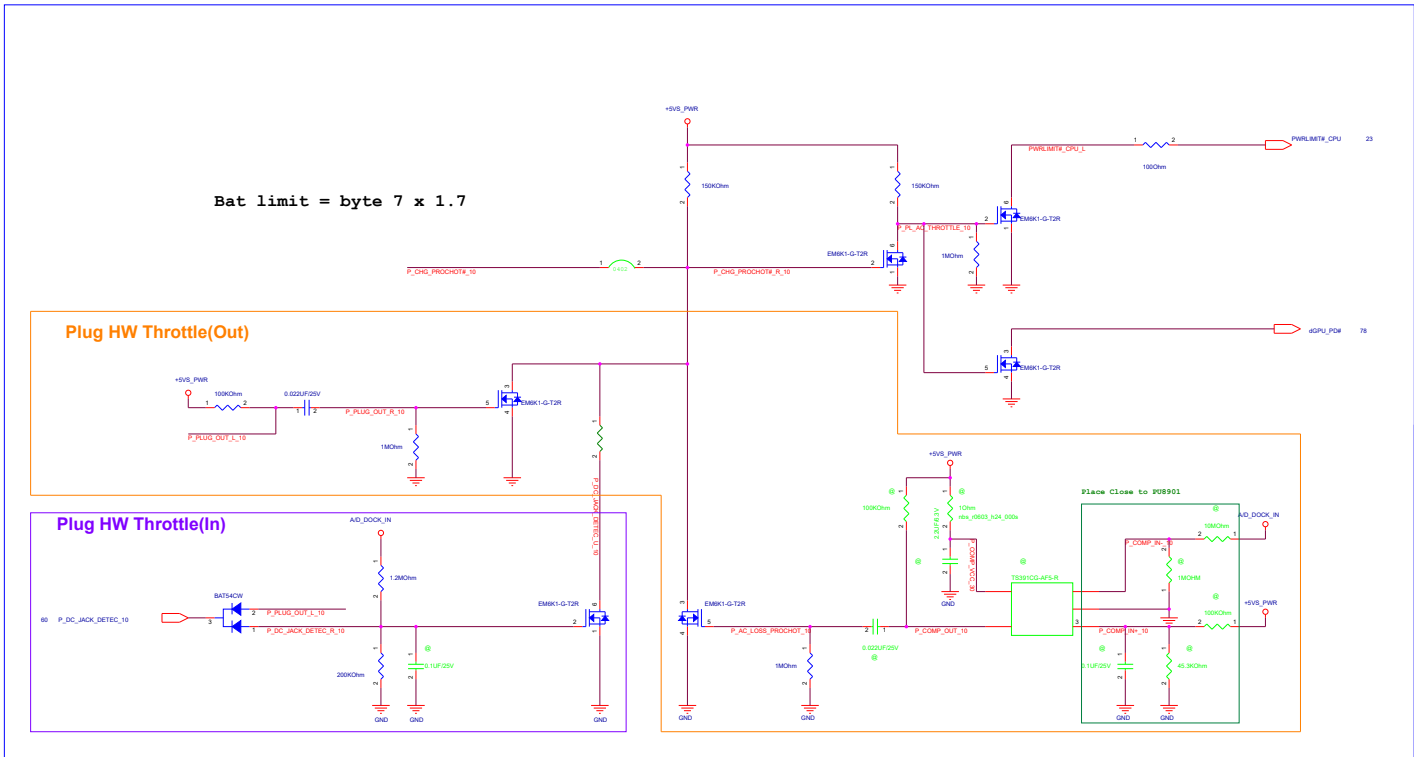
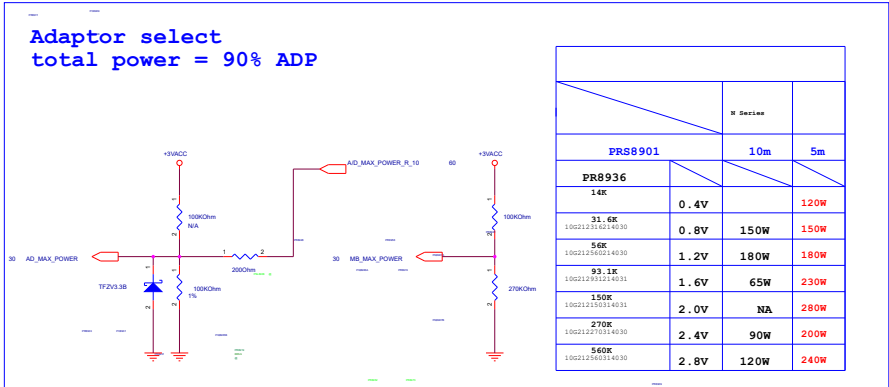
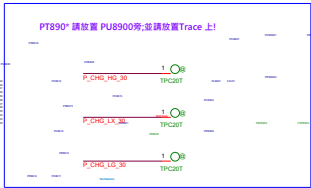
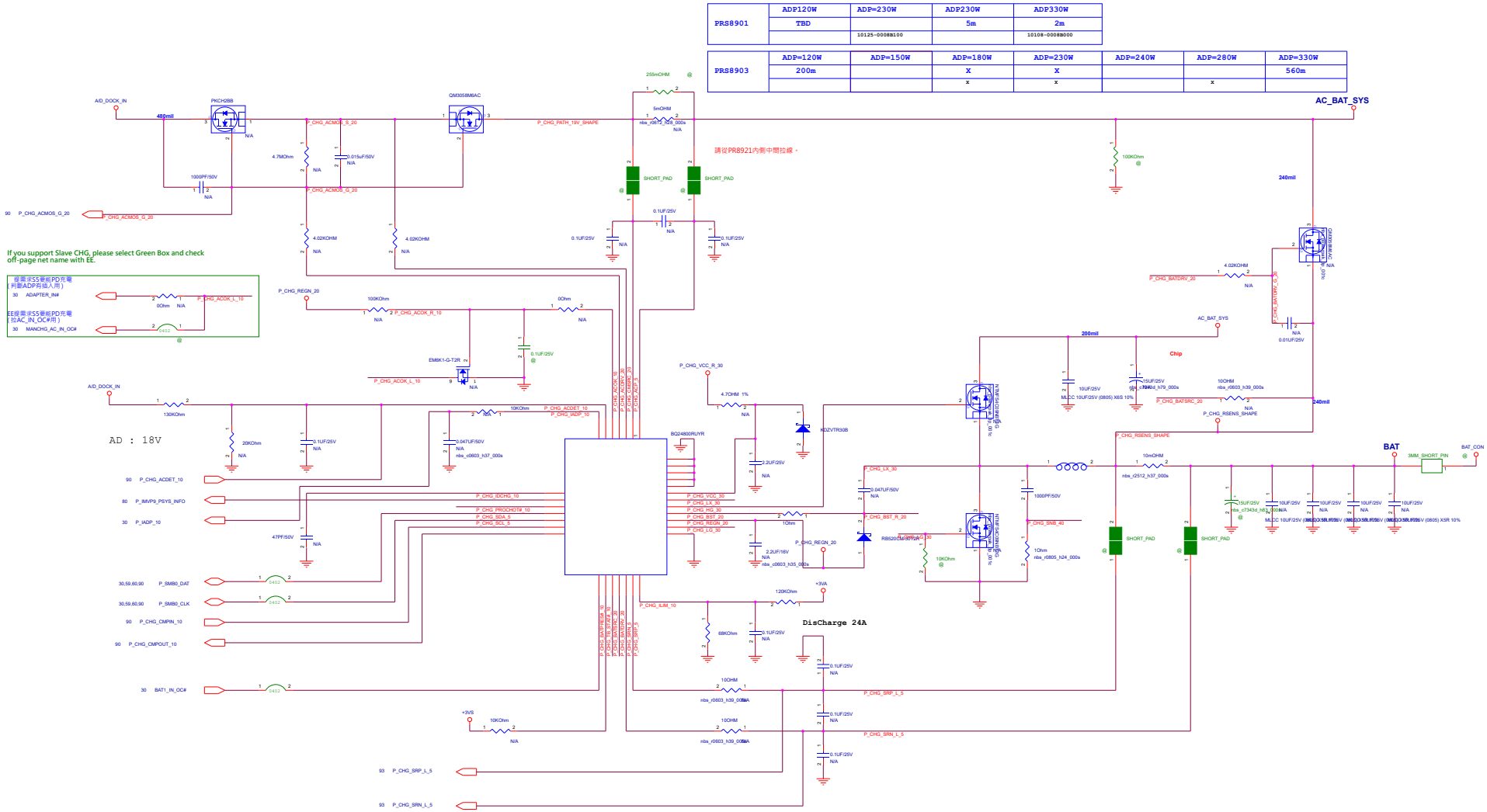


Load Switch



uP9030 ILIM/LPM Setting 對應表		
	LPM (C10)	
GND	Off	3A
1M to GND	Off	5A
Float/VDD	On	8A

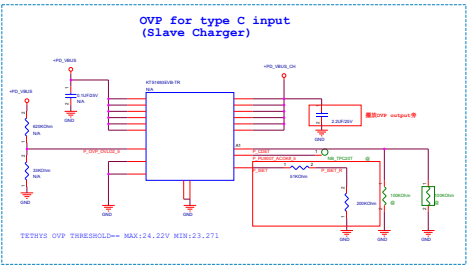
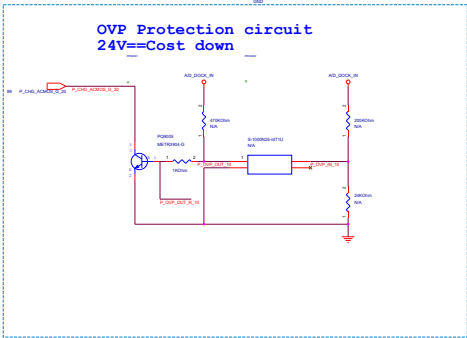
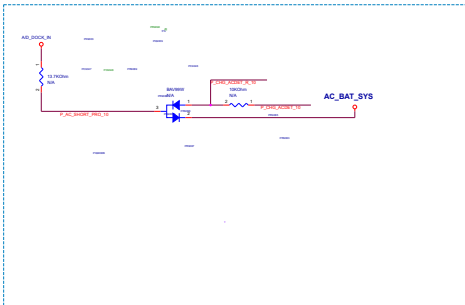
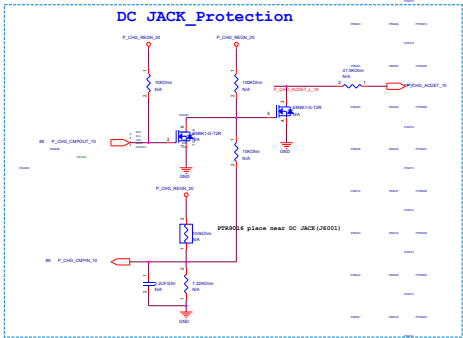
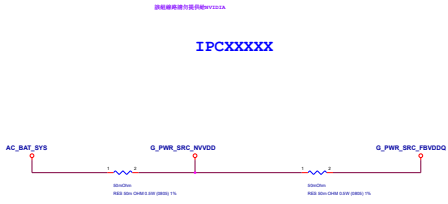
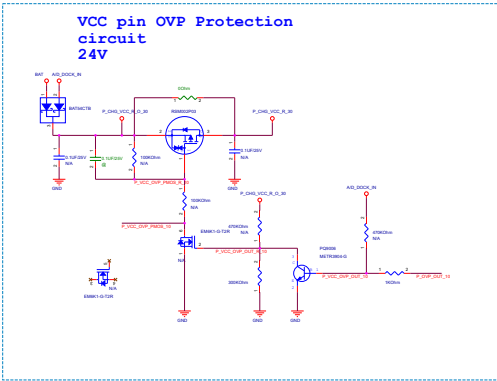
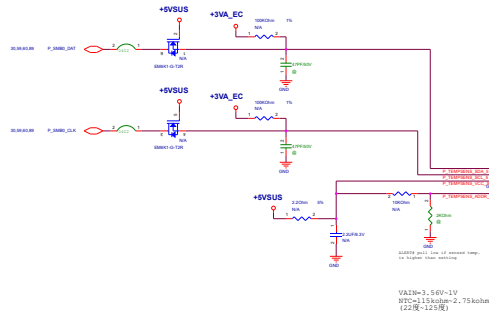


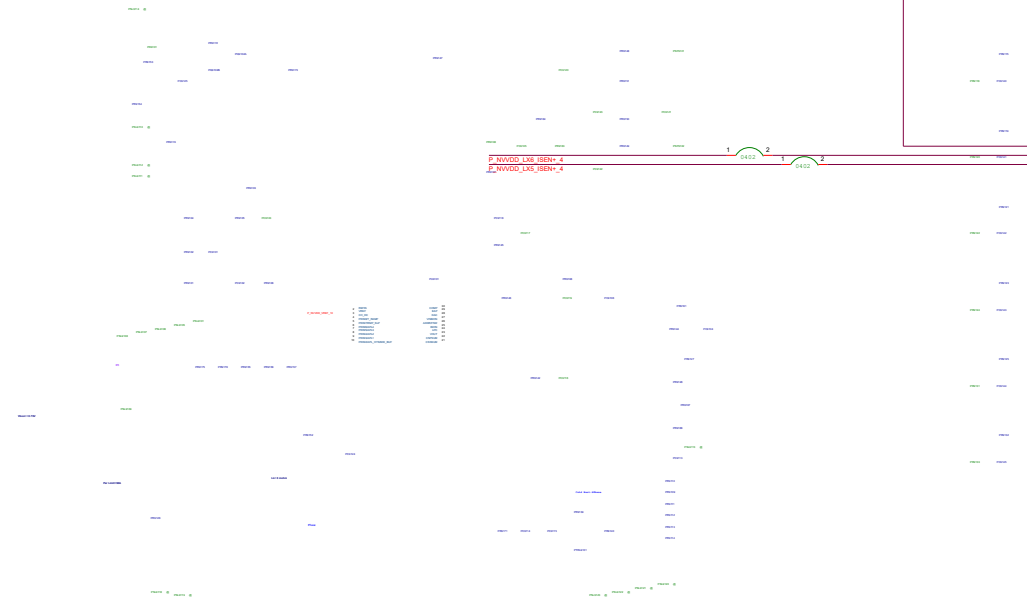


P90_PROTECTION

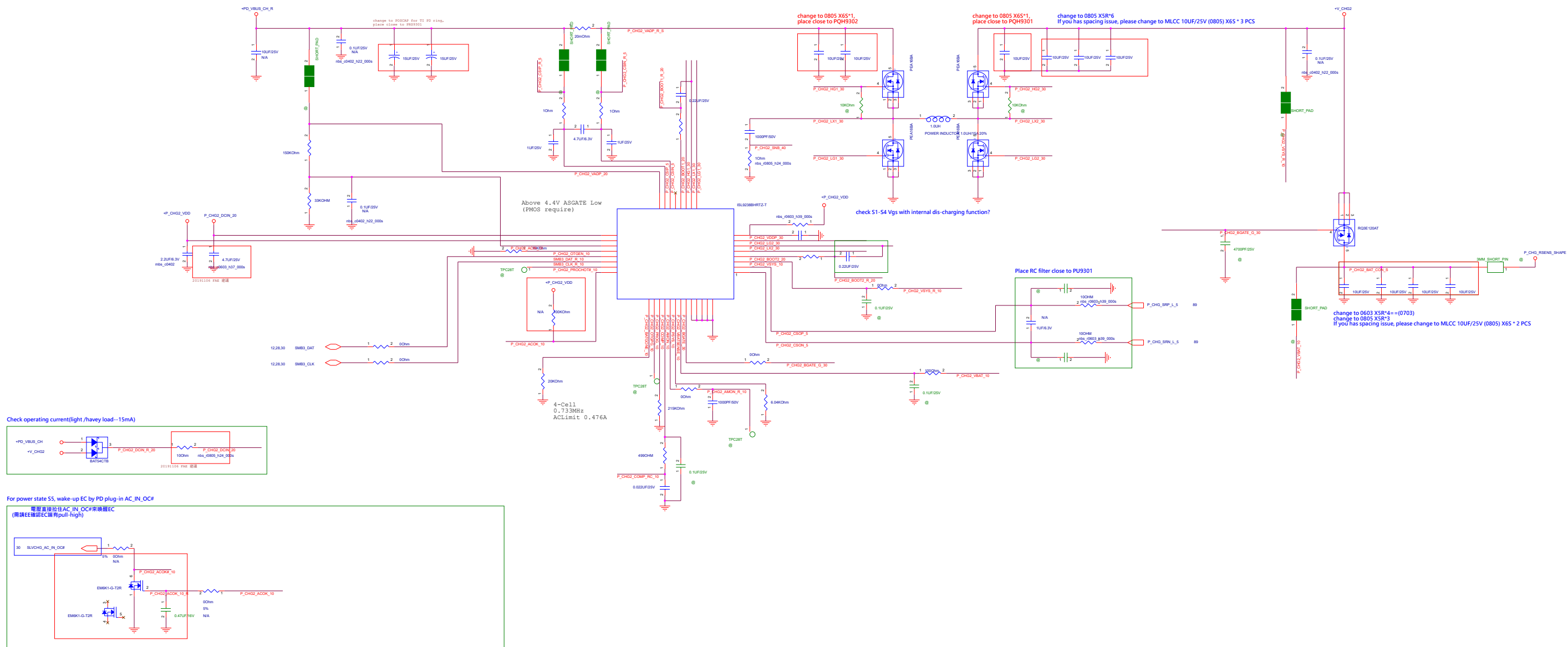
Address Selection Table											
0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011
0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011

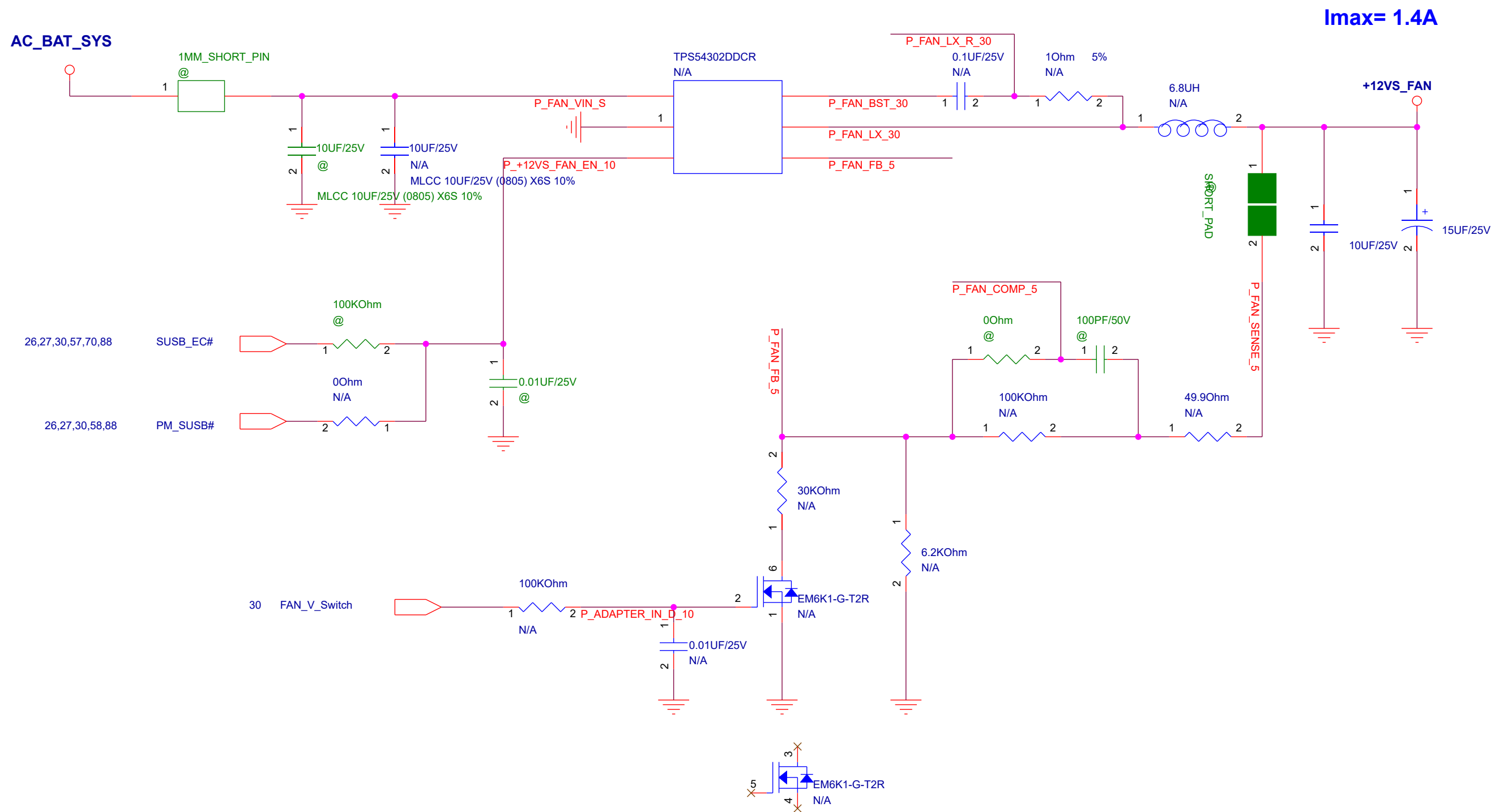
Register Address			
0000	0001	0010	0011
0100	0101	0110	0111
1000	1001	1010	1011



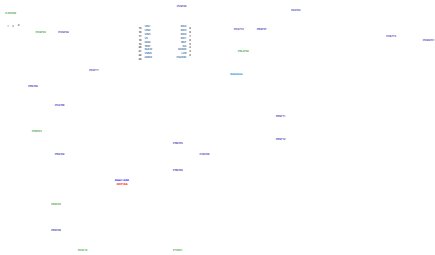
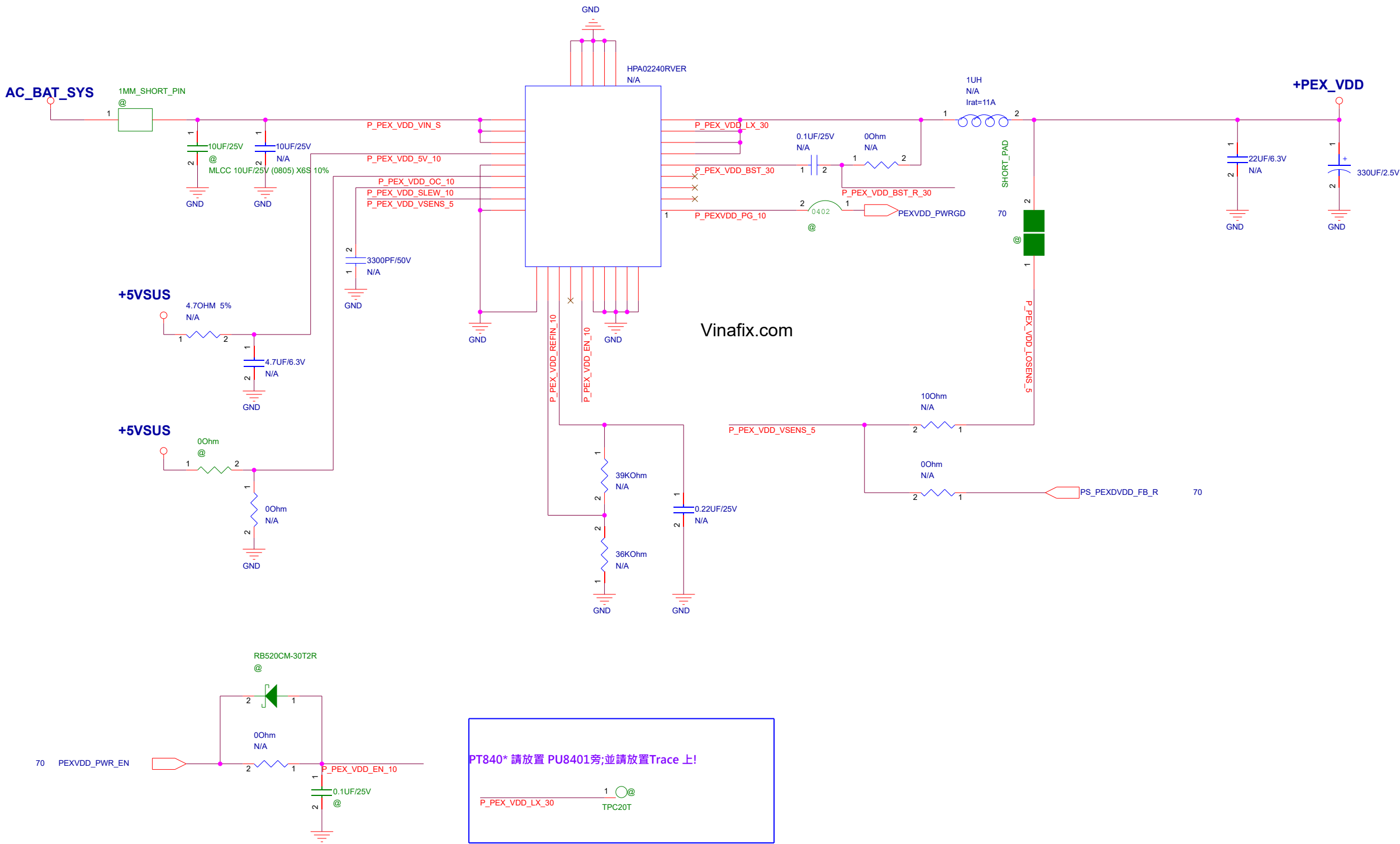
[illegible]

Charger ISL9238 (NVDC)

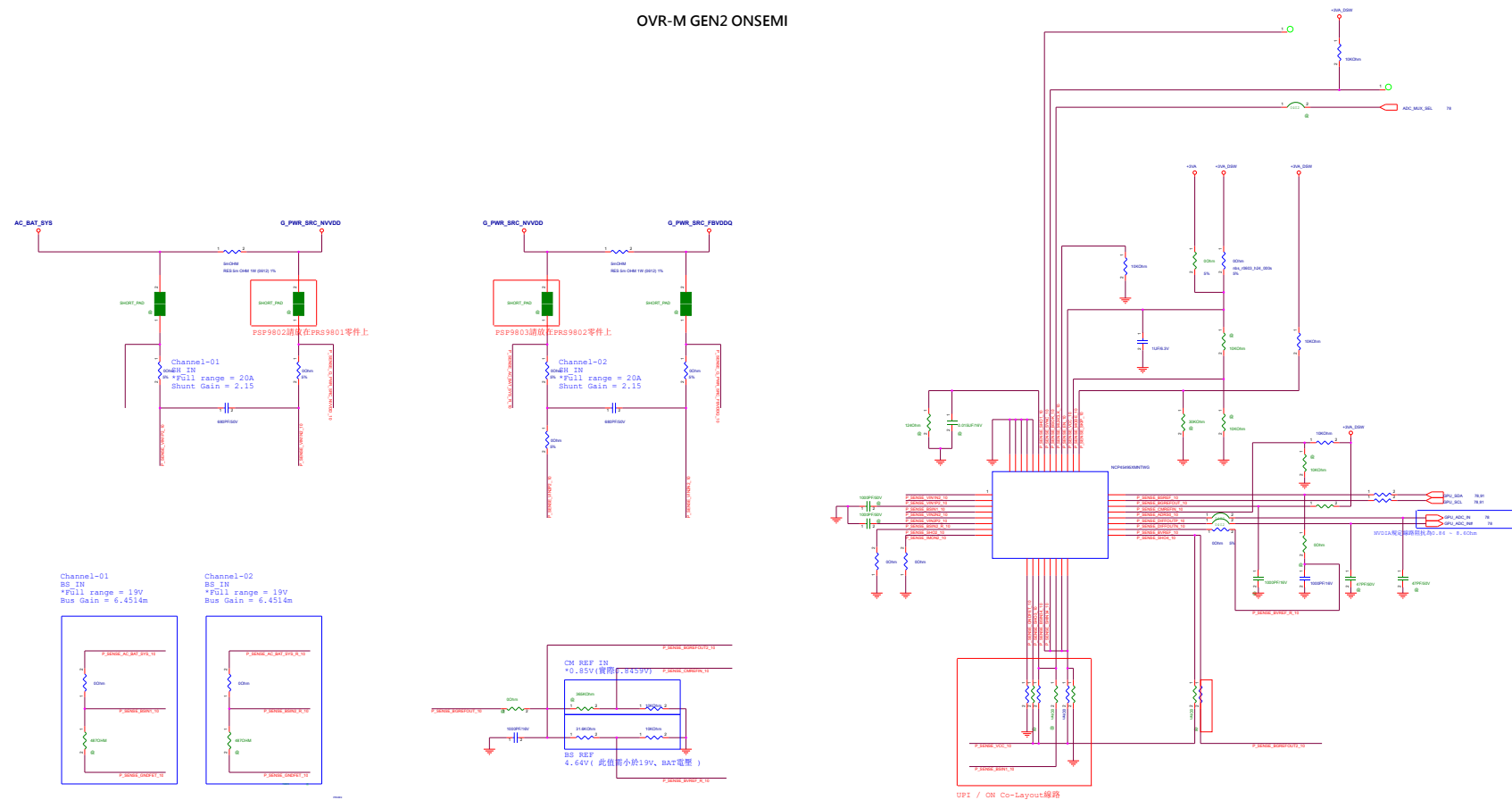




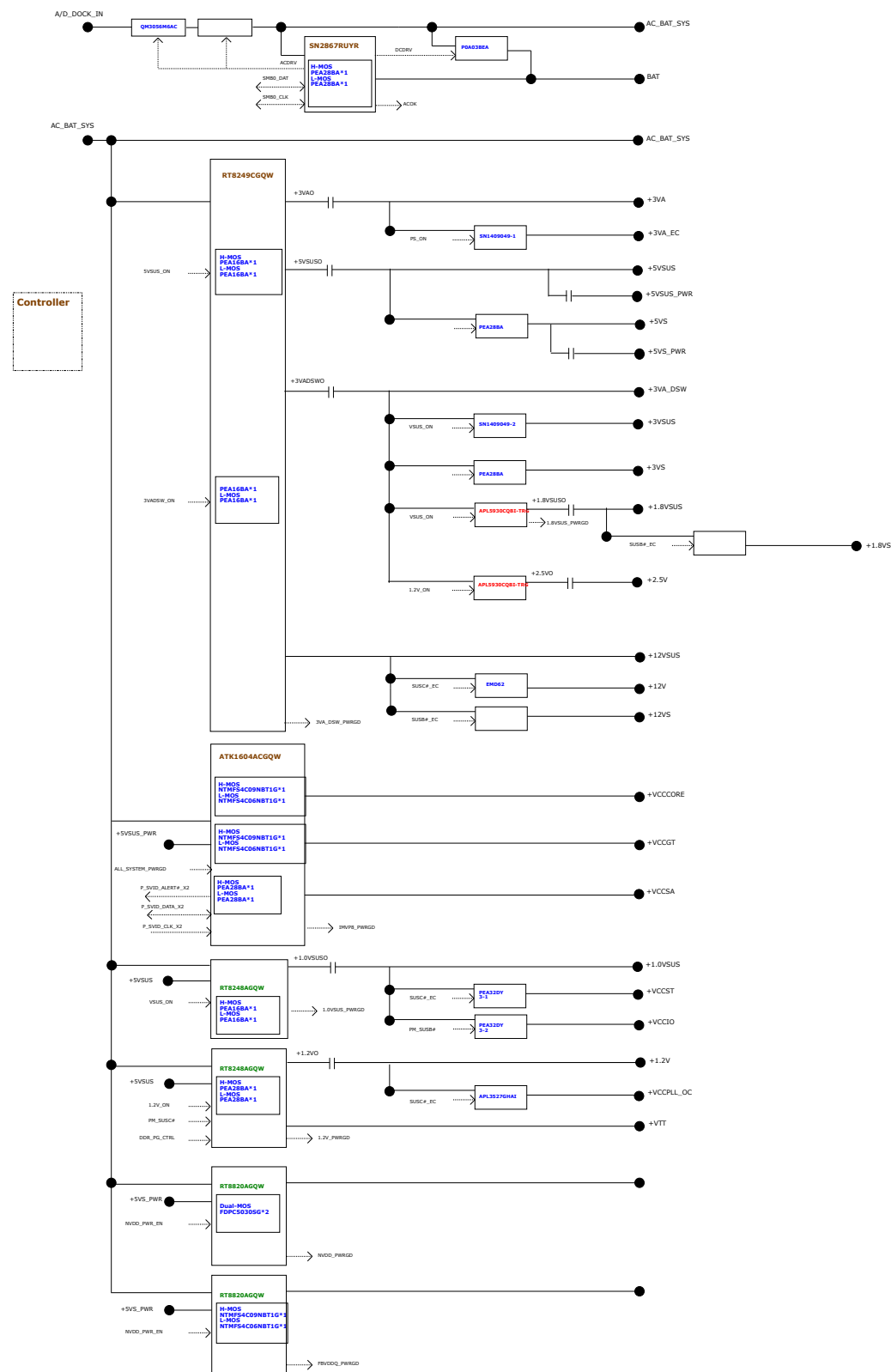
PEX_VDD [For GPU]



OVR-M GEN2 ONSEMI



	PR9801	PR9805	PR9807	PR9803	PR9804	PR9805	PR9814	PR9855	PR9822
GN20	06129-00220000 06129-00101010	0 Ohm 10G212000004030	0 Ohm 10G212000004030	0 110G32115314321	0 110G32115314321	0 0.0150P/16V 110G32115311360	0 Ohm 10G212000004030 3570hm 10G212357014010	0 Ohm 10G212000004030	0 Ohm 10G212000004030 49.90hm 10G212498914010
	PC9810	PR9860	PR9809	PR9810	PR9834				
GN20	0 1000PF/16V 11G232110211030	0 Ohm 10G212000004030	0 360R0hm 10G212364004010	10R0hm 10G21100214010 680R0hm 10G212680314010	31.6R0hm 10G212316214010 324R0hm 10G212324314010	10G212000004030 10G212000004030	10G212000004030 0 0.0150P/16V 110G32115311360	4870hm 10G212487014010	4870hm 10G212487014010
GN20		10G212000004030		10G212100214010	10G212000004030	10G212000004030		10G212000004030	
N18P-G1	4870hm 10G212487014010	0 10G212000004030	0hm 10G212000004030	0 10G212100014010	1000hm 10G212100014010	49.90hm 10G212498914010	3570hm 10G212357014010		10G212000004030



AC-IN Mode

Power-On Sequence
Timing Diagram Rev.0.1

please refer to #543016 chapter 43

+3VA_EC
EC_RST#

+3VADSW/+5VSUS

6 PM_SLP_SUS#

7 VSUS_ON

8 PM_RSMRST#

11

12

13 PWR_SW#

14 PM_PWRBTN#

15 PM_SUSC#

16 PM_SUSB#

PM_SLP_A#

(EC to power)

+1.2V/+5V/+12V

(EC to power)

SUSB_EC#

19

21 VCCST_PWRGD

ALL_SYSTEM_PWRGD

PM_PWROK_PCH

24 VCCIN_EN

+VCCIN

26

27

BUF_PLT_RST#

t200b

t202

t_plt01

(falling edge)

T=50ms

t204

tCPU07

t_plt03

t_plt05=120ms

Vinafix.com

AC-IN Mode

Power On Sequence Diagram Rev.2.0

